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*H01L 29/66* (2006.01)  
*H01L 29/778* (2006.01)  
*H01L 29/78* (2006.01)  
*B82Y 10/00* (2011.01)
- (52) **U.S. Cl.**  
 CPC .. *H01L 29/66431* (2013.01); *H01L 29/66545*  
 (2013.01); *H01L 29/66795* (2013.01); *H01L*  
*29/66977* (2013.01); *H01L 29/778* (2013.01);  
*H01L 29/7855* (2013.01); *B82Y 10/00*  
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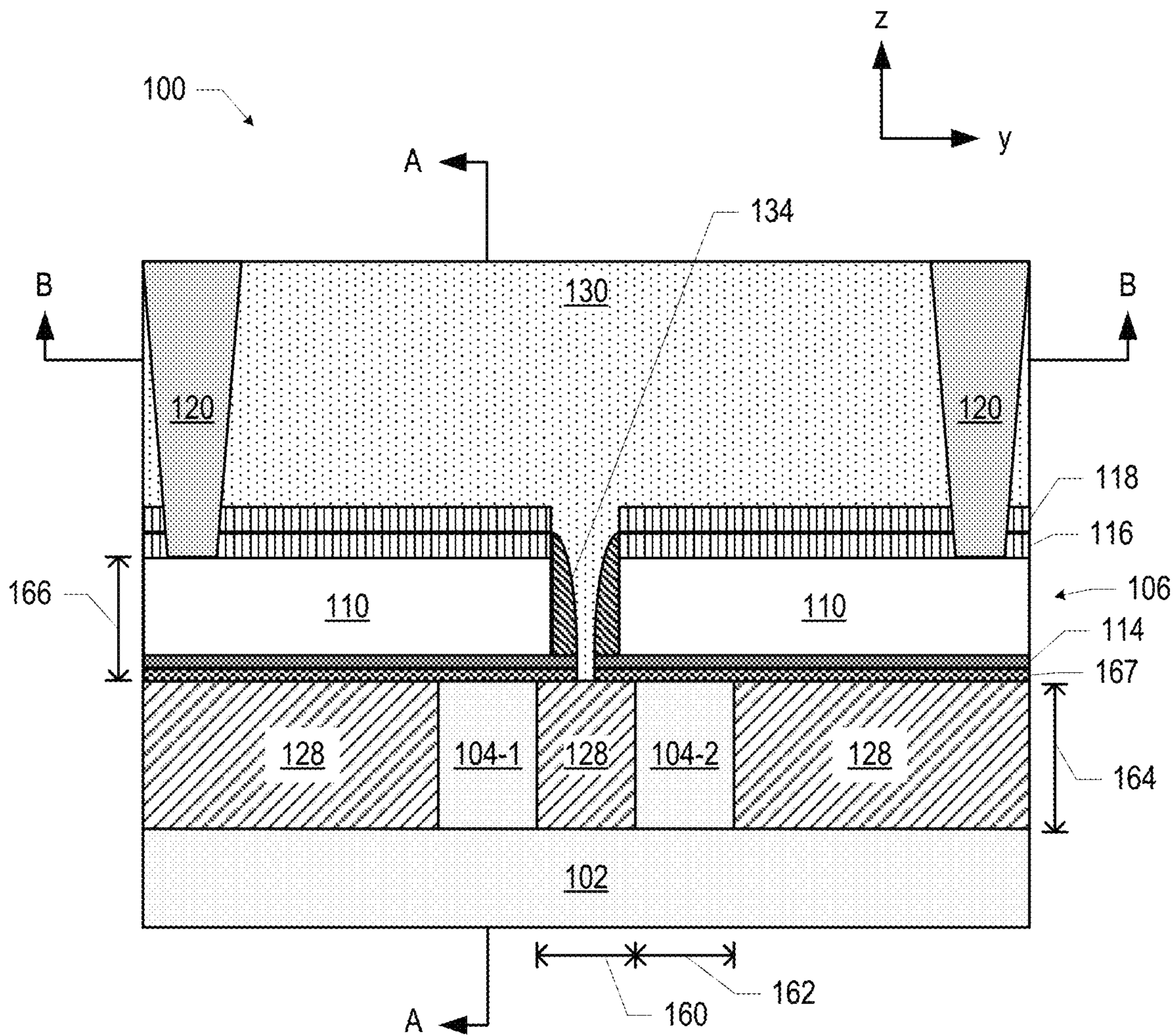


FIG. 1

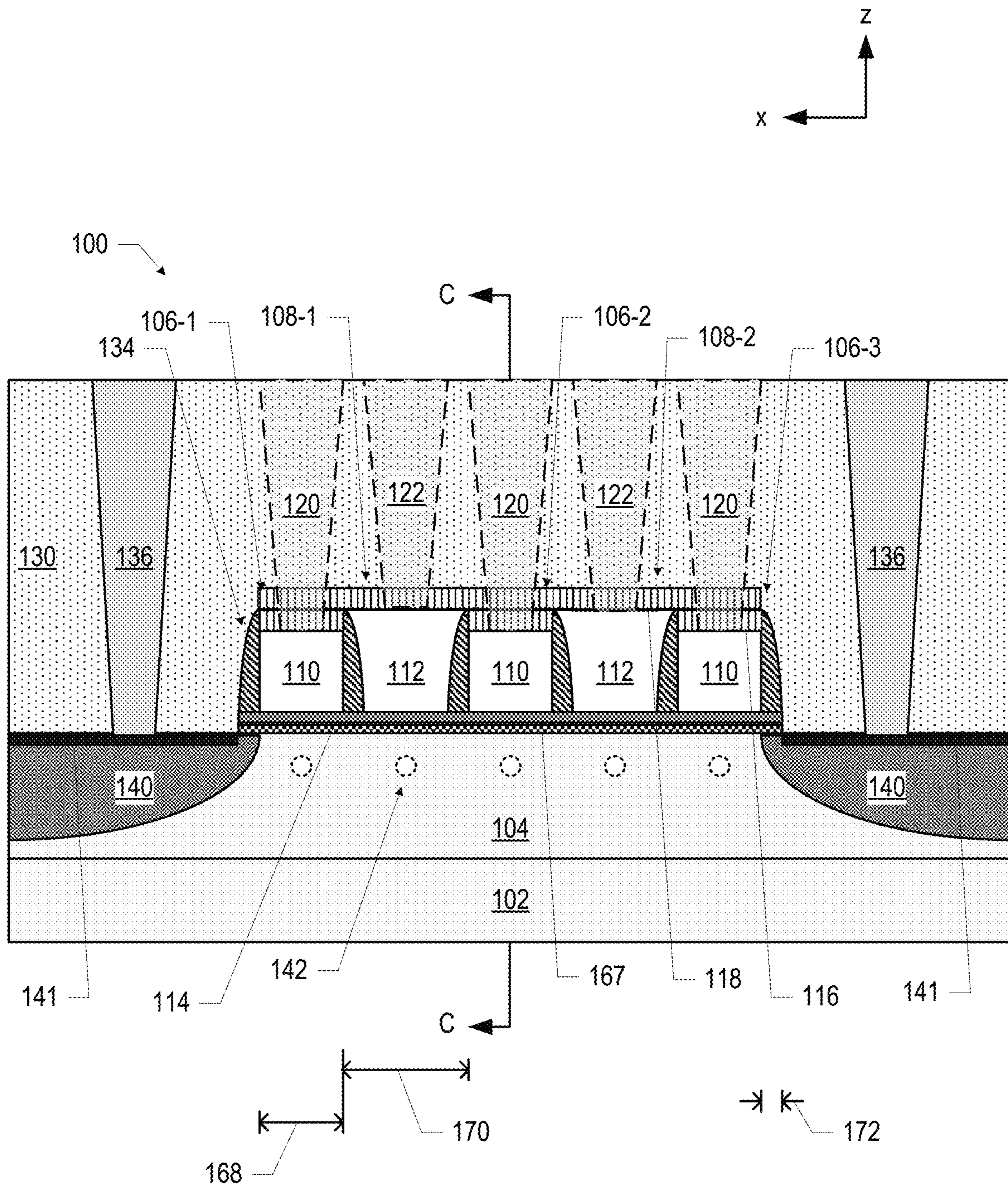


FIG. 2



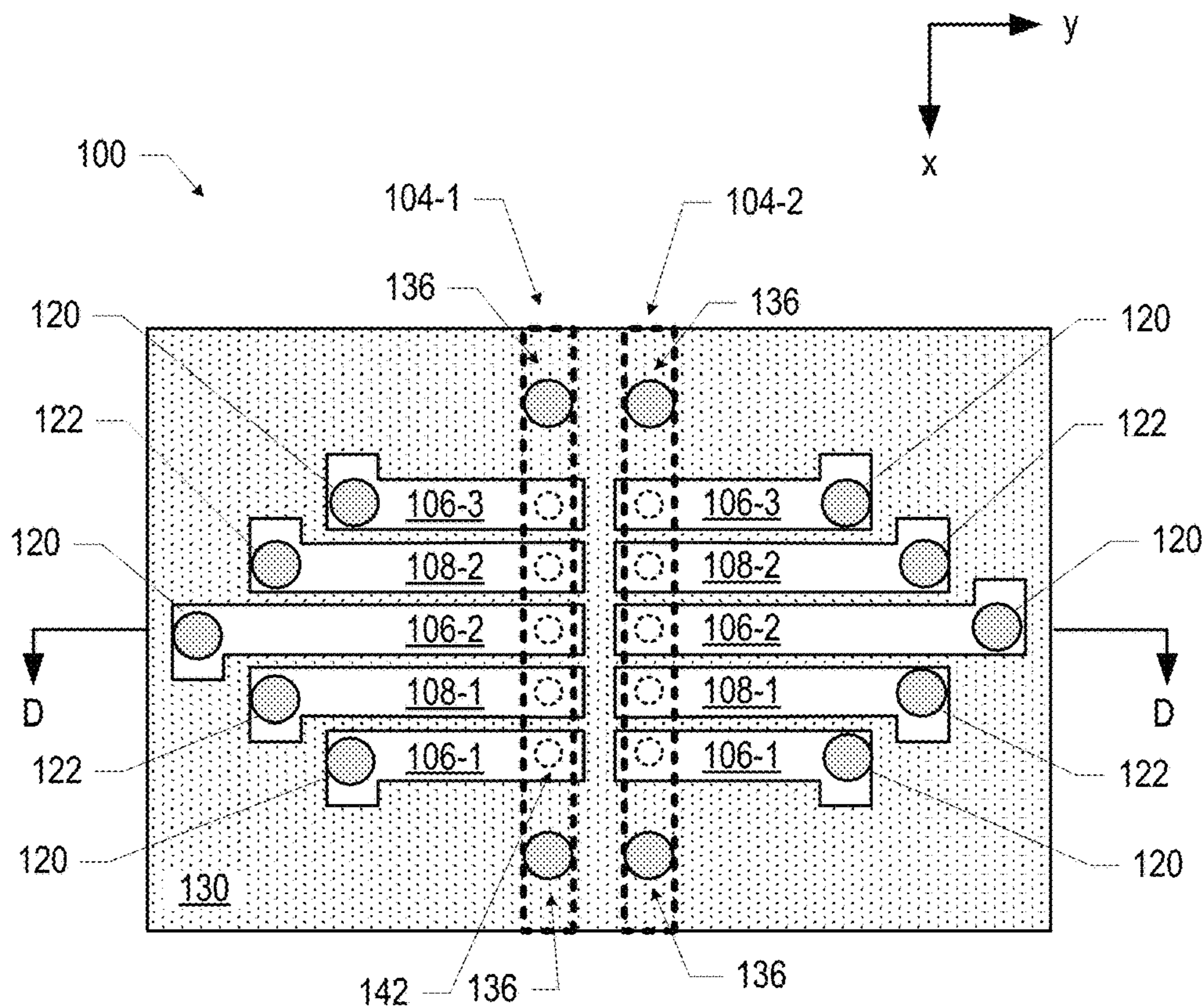


FIG. 3

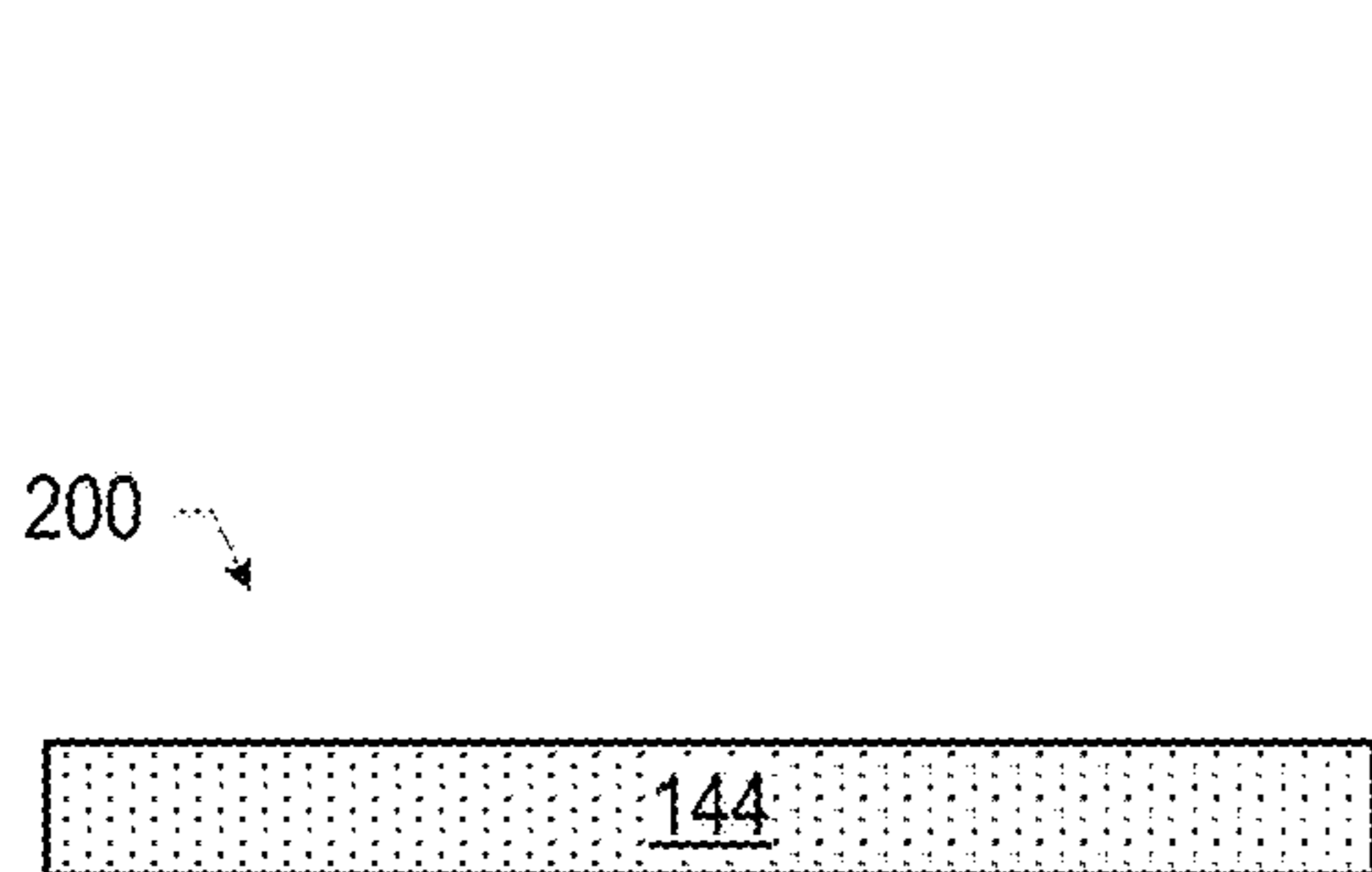


FIG. 4

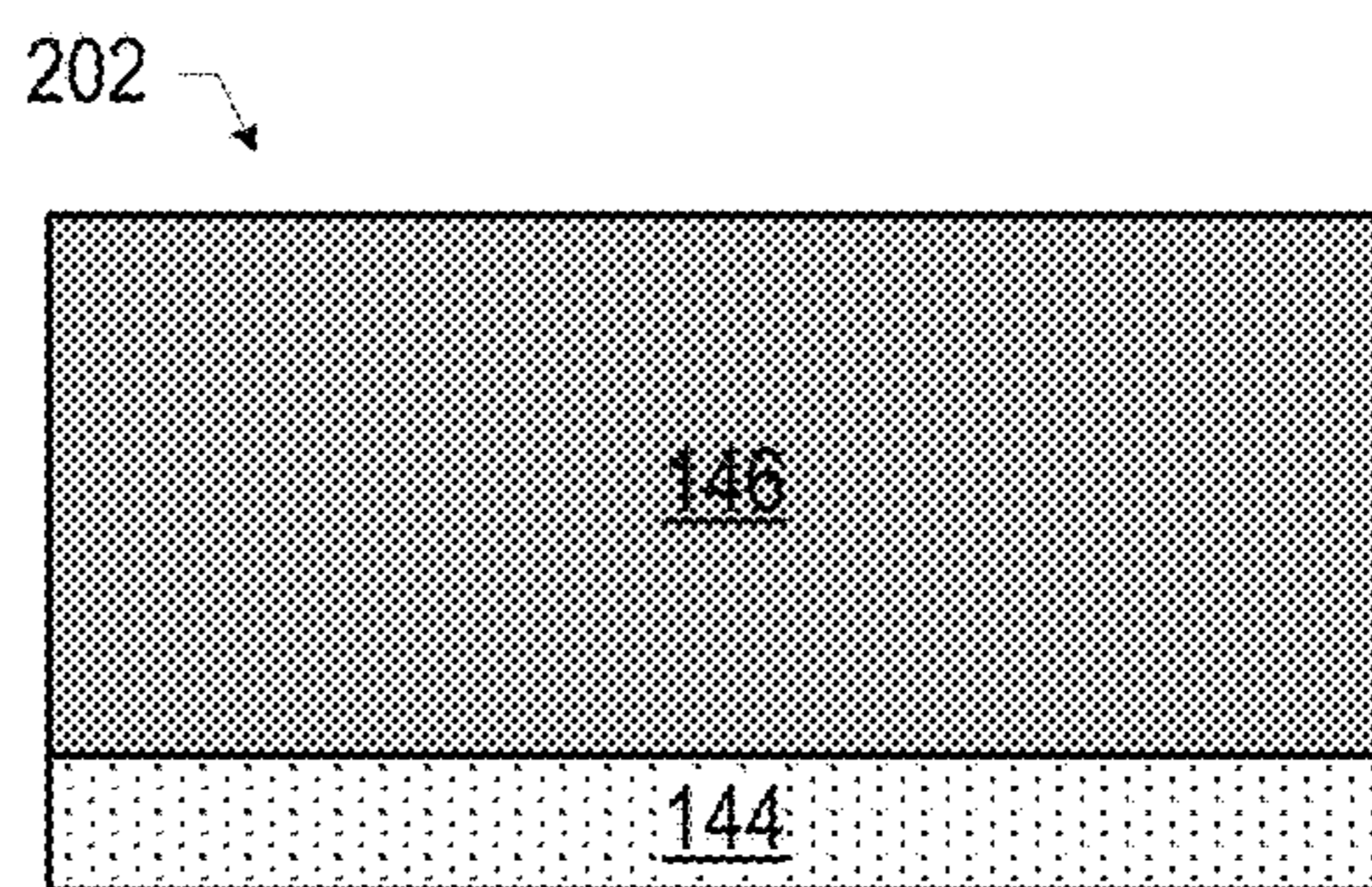


FIG. 5

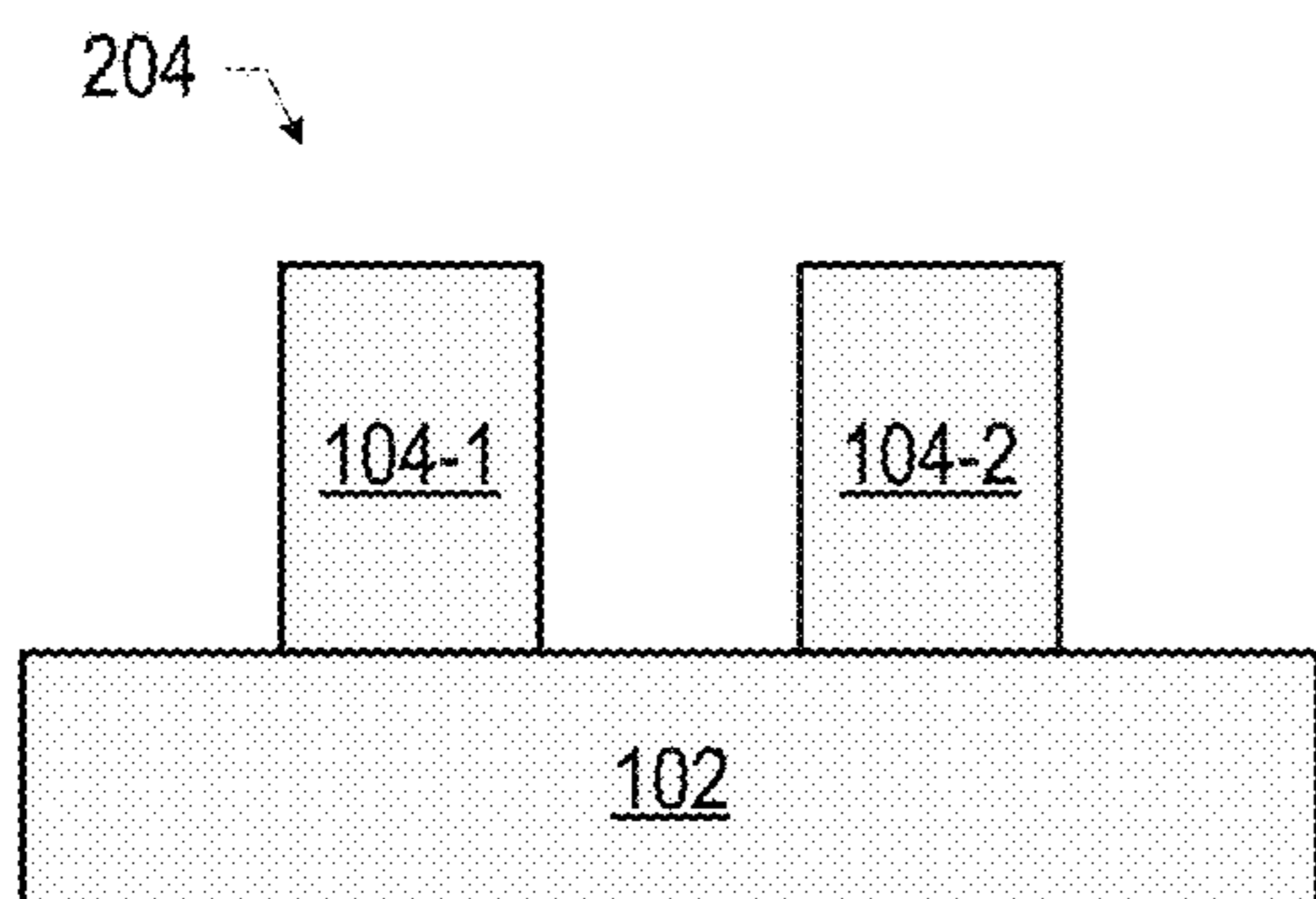


FIG. 6

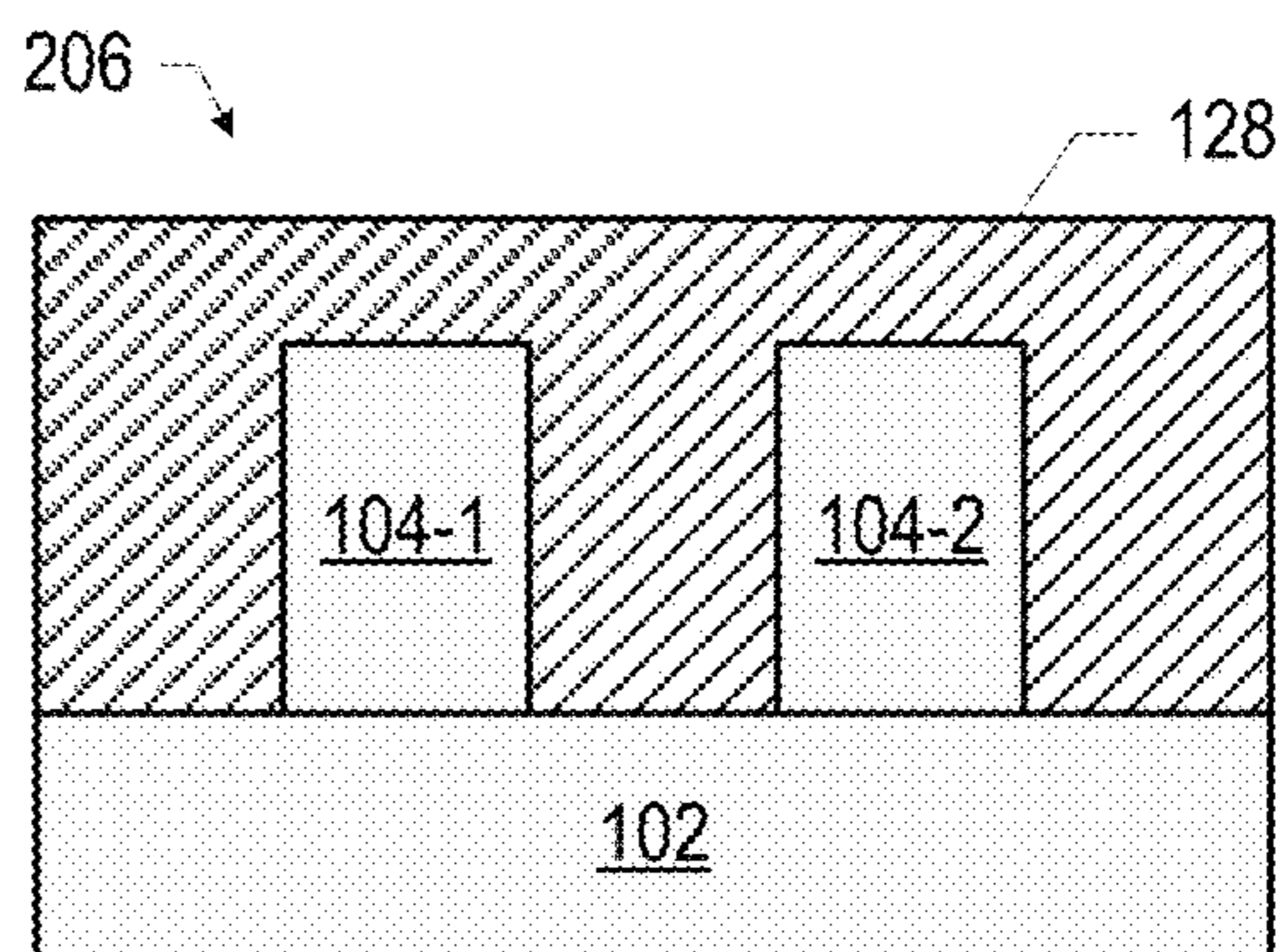


FIG. 7

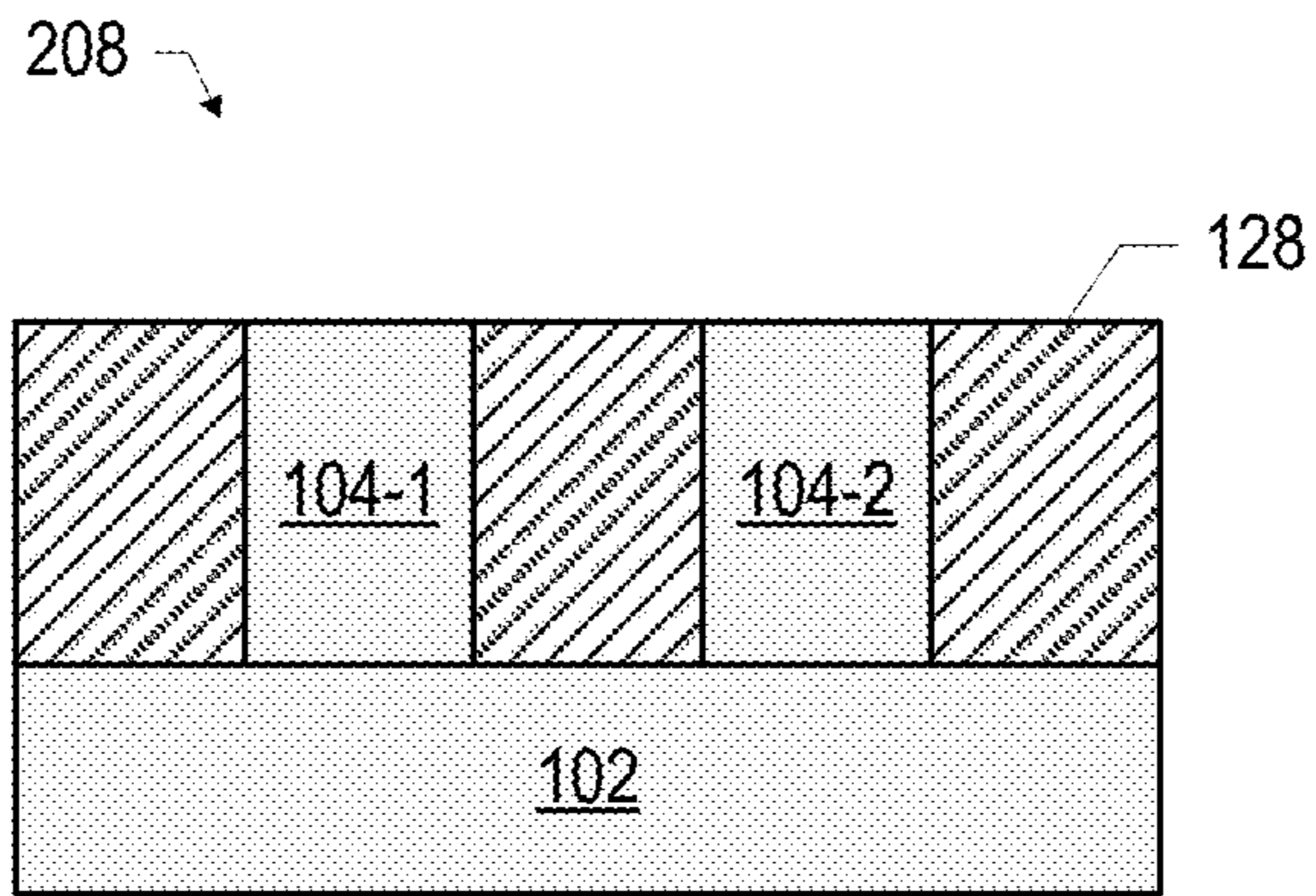


FIG. 8

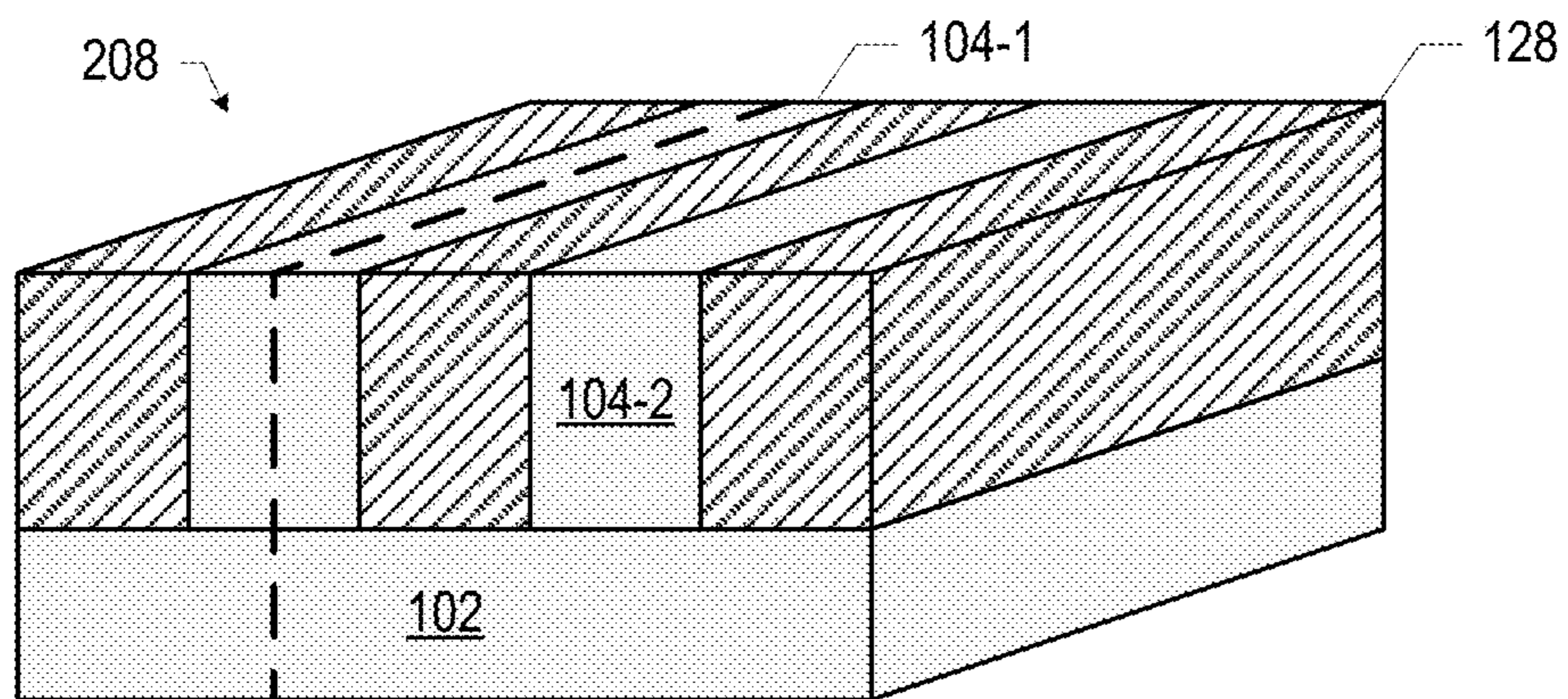


FIG. 9

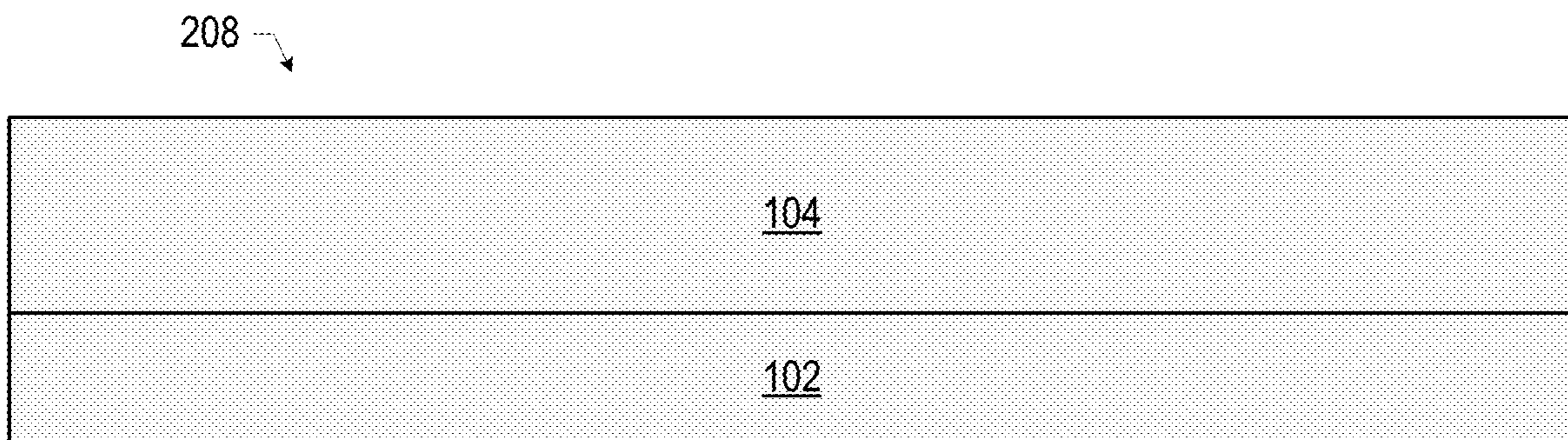


FIG. 10



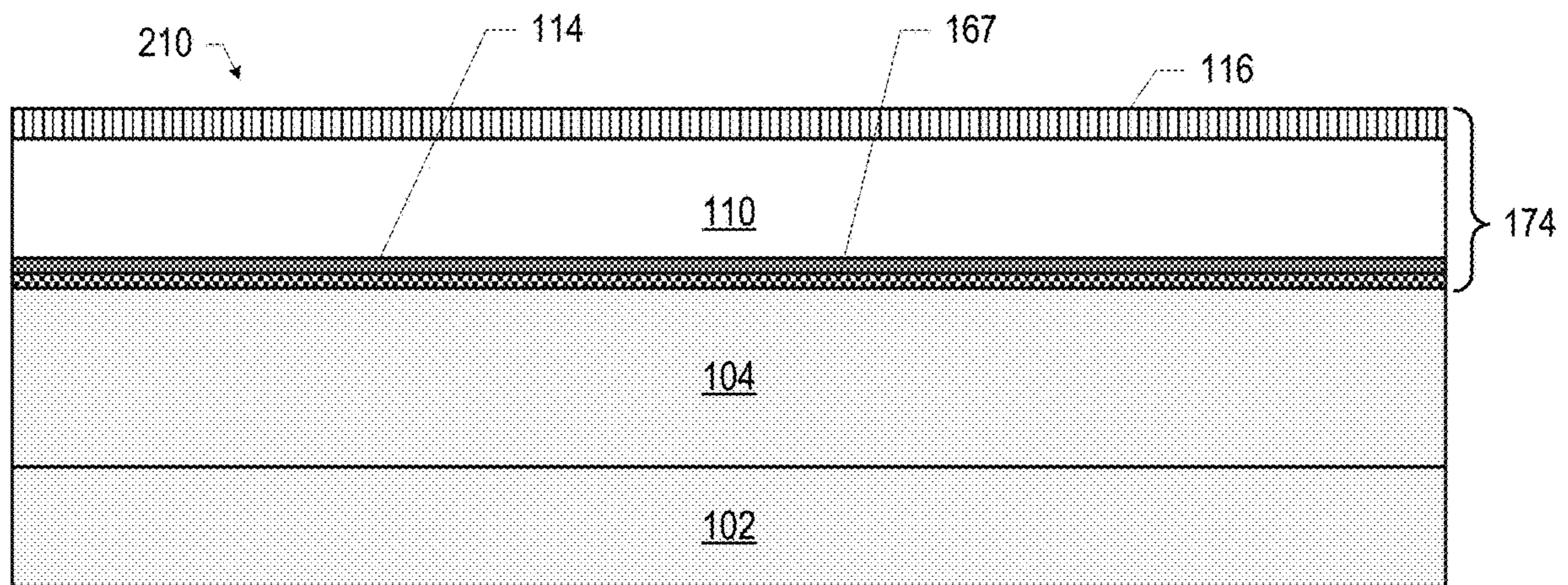


FIG. 11

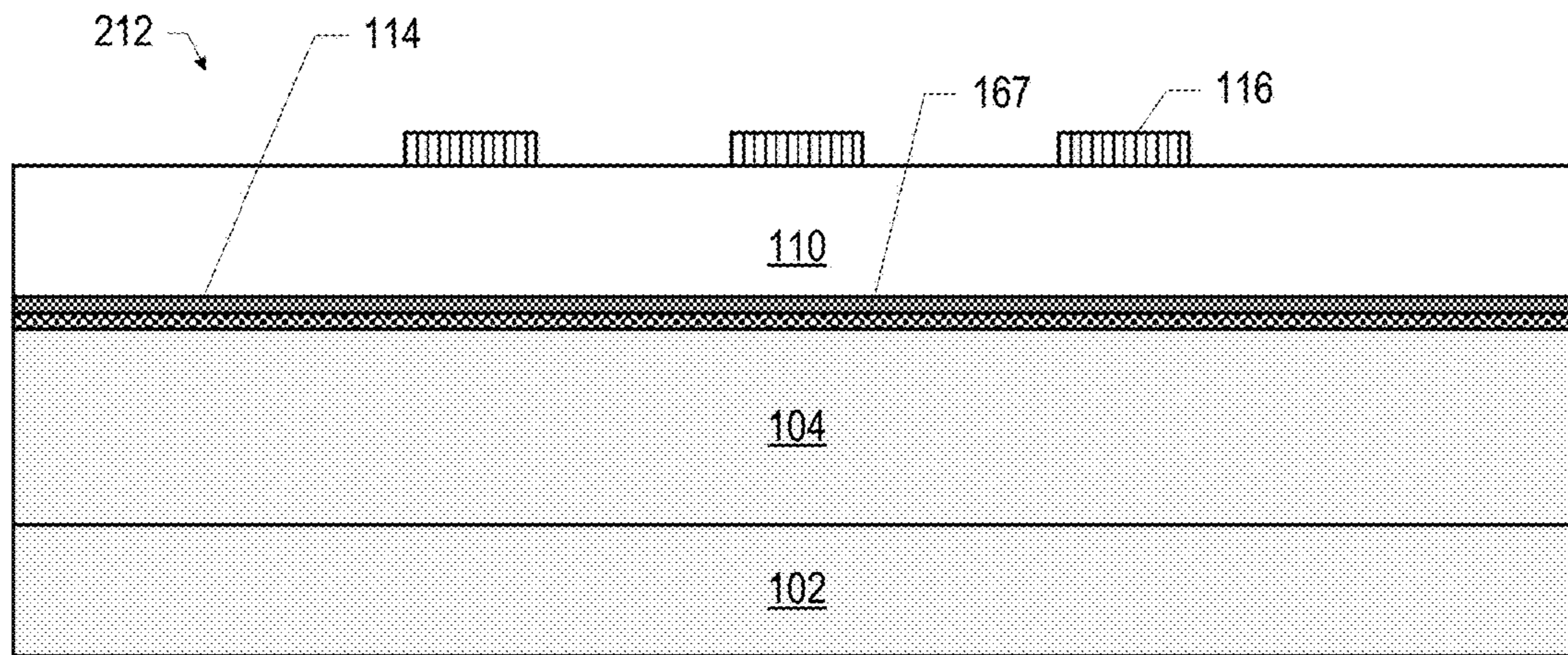


FIG. 12

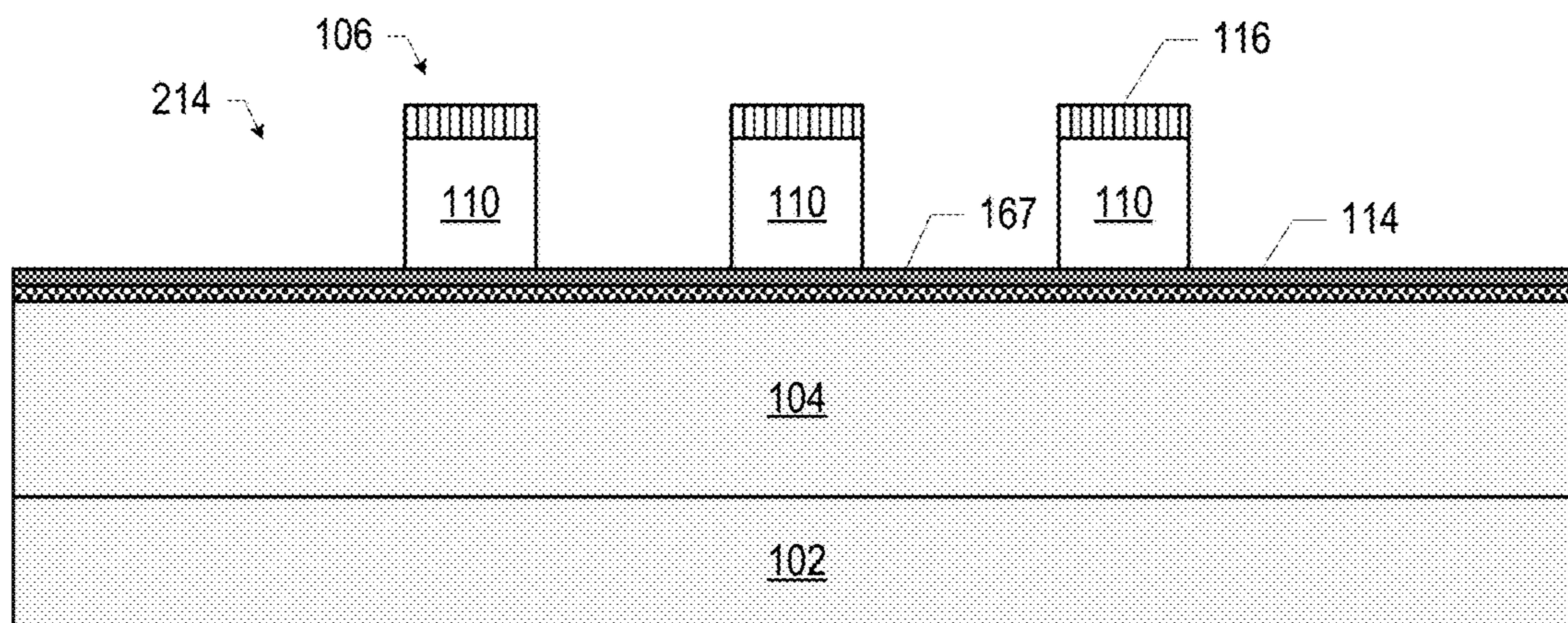


FIG. 13



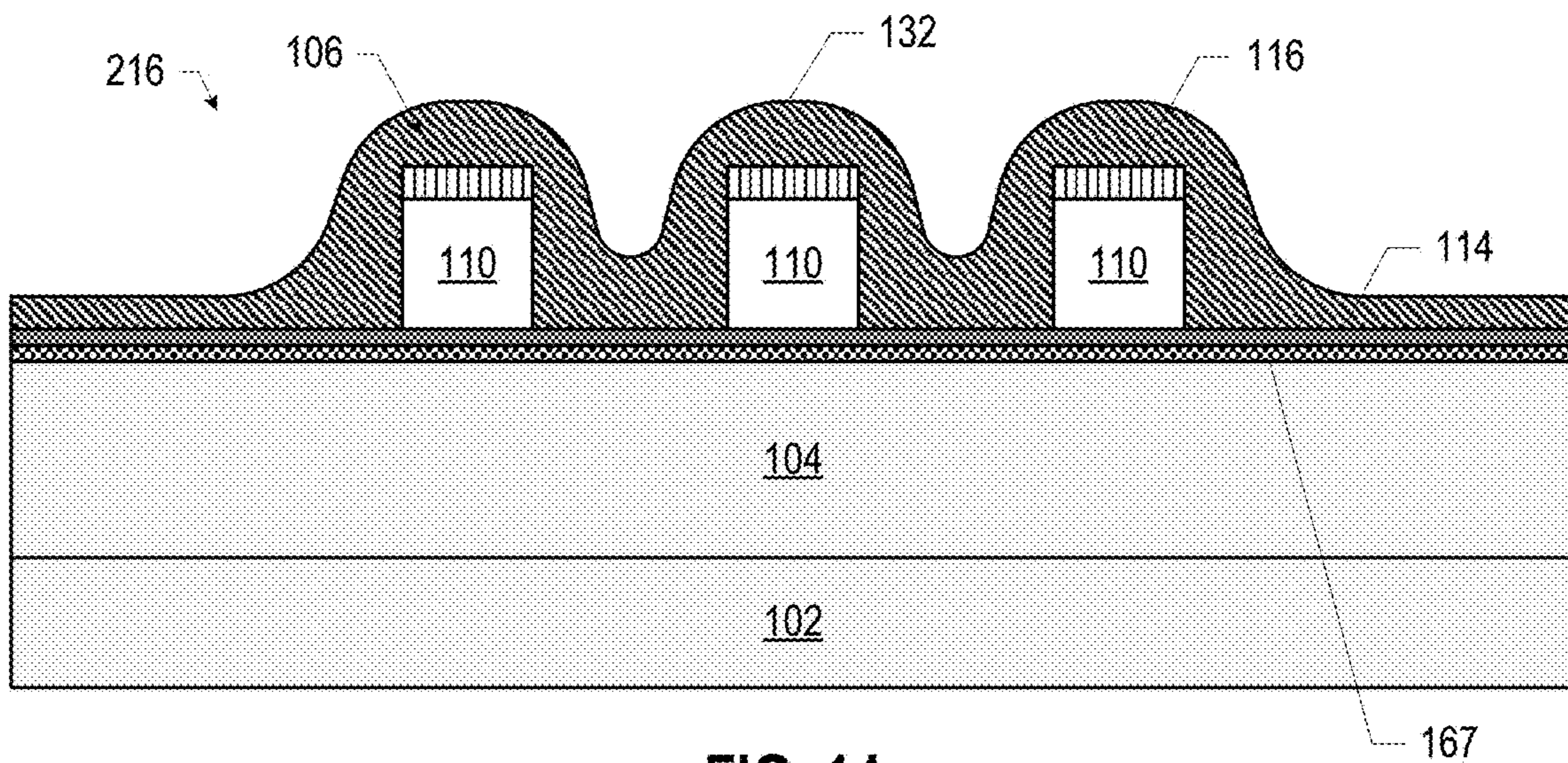


FIG. 14

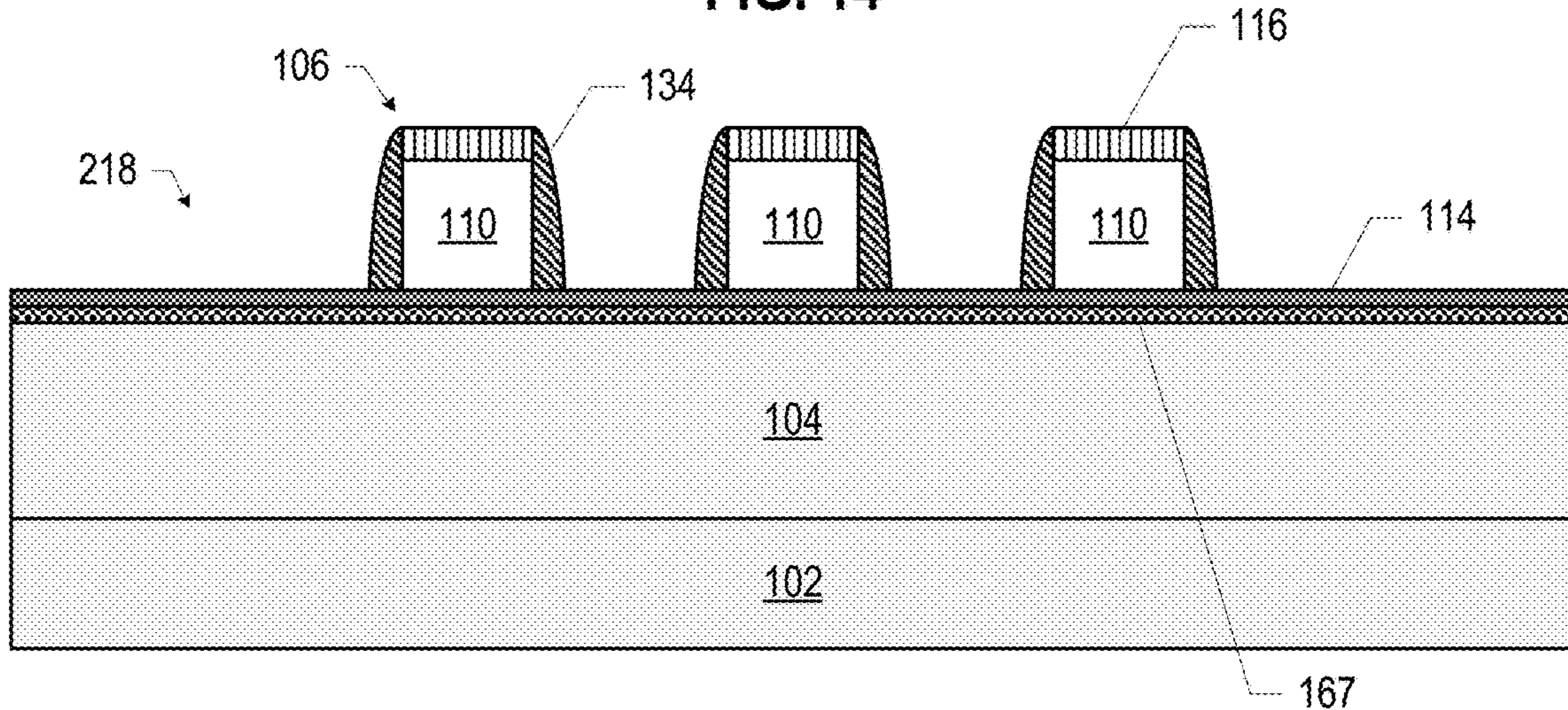


FIG. 15

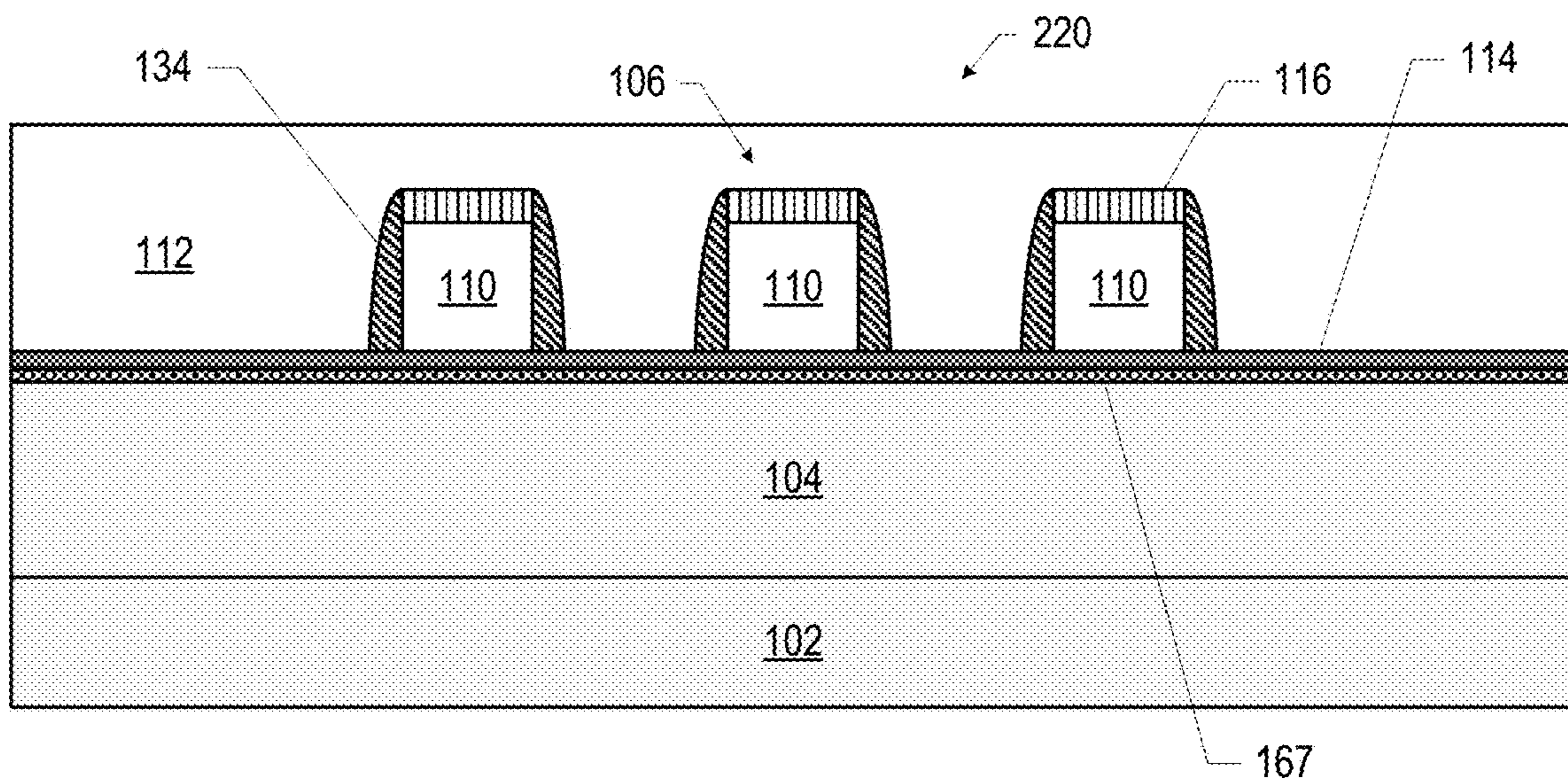


FIG. 16



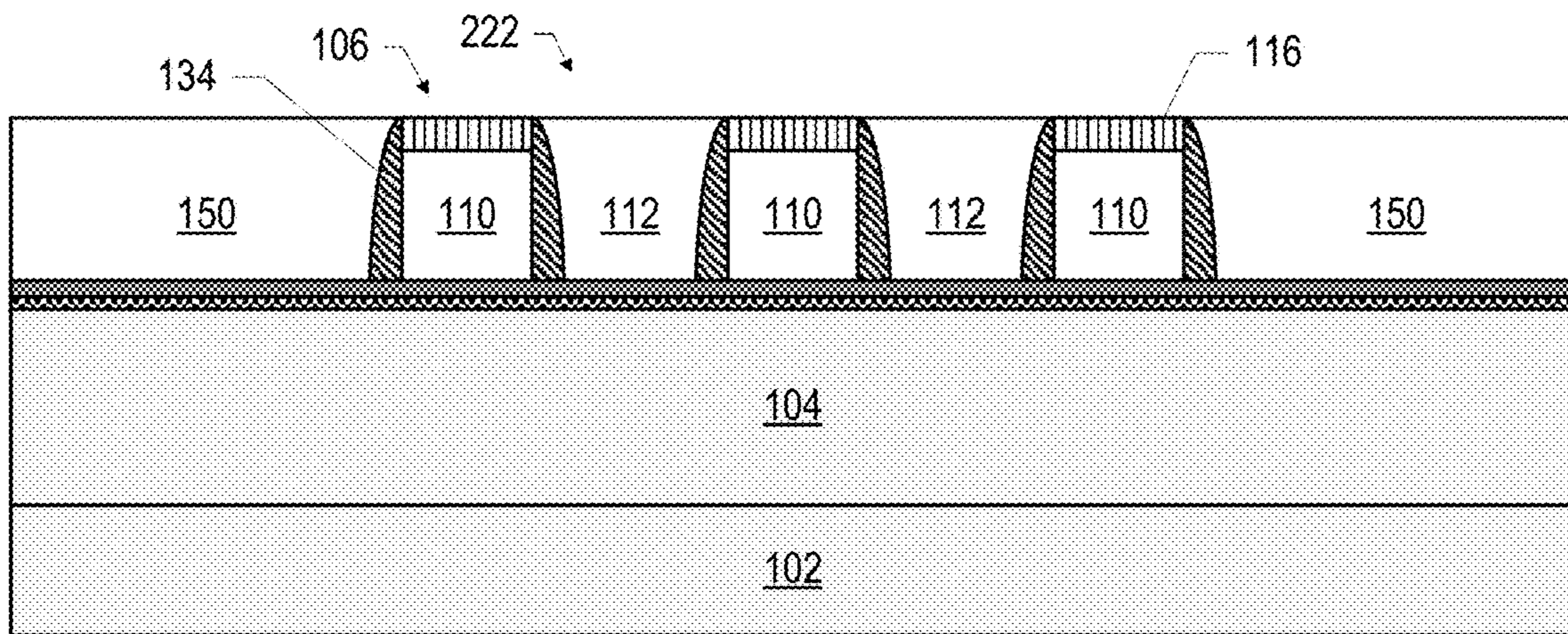


FIG. 17

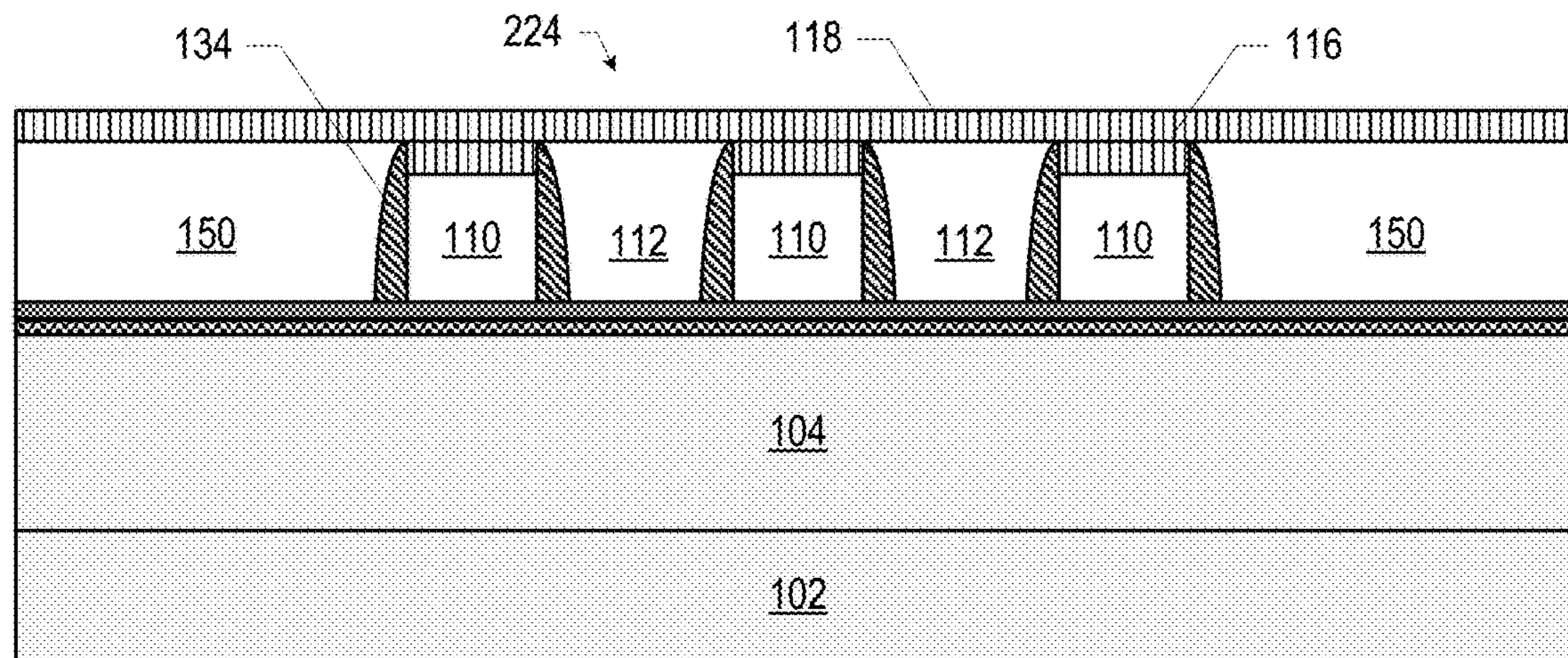


FIG. 18

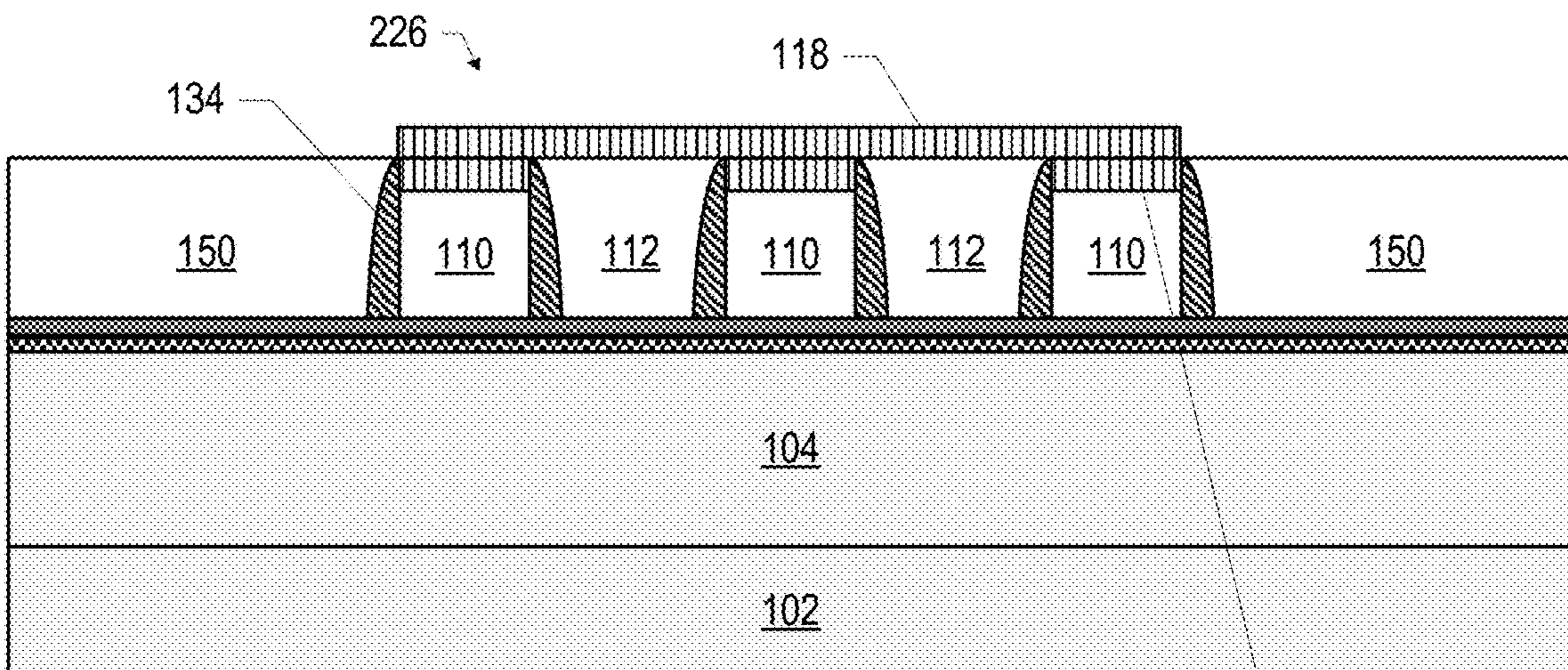


FIG. 19



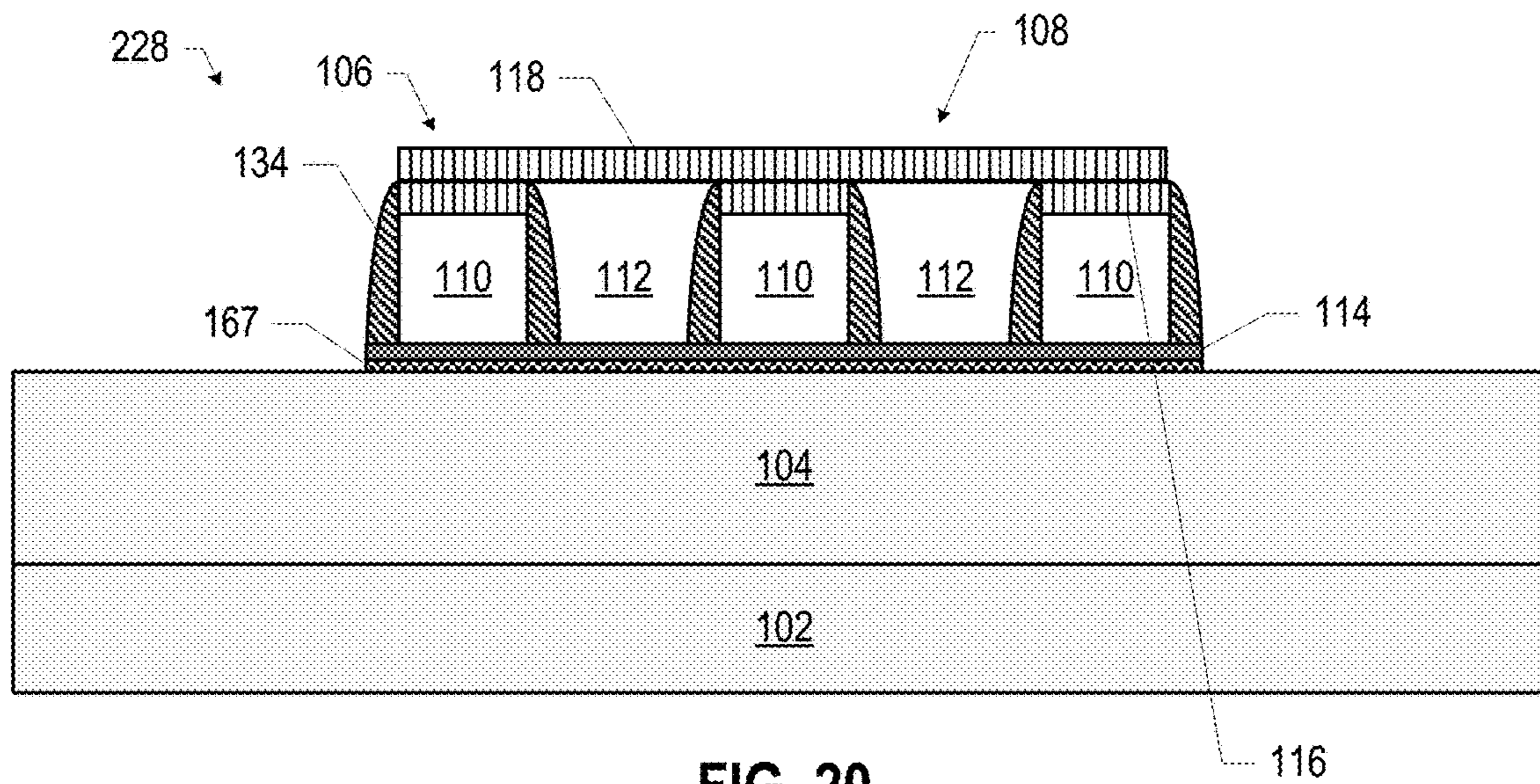


FIG. 20

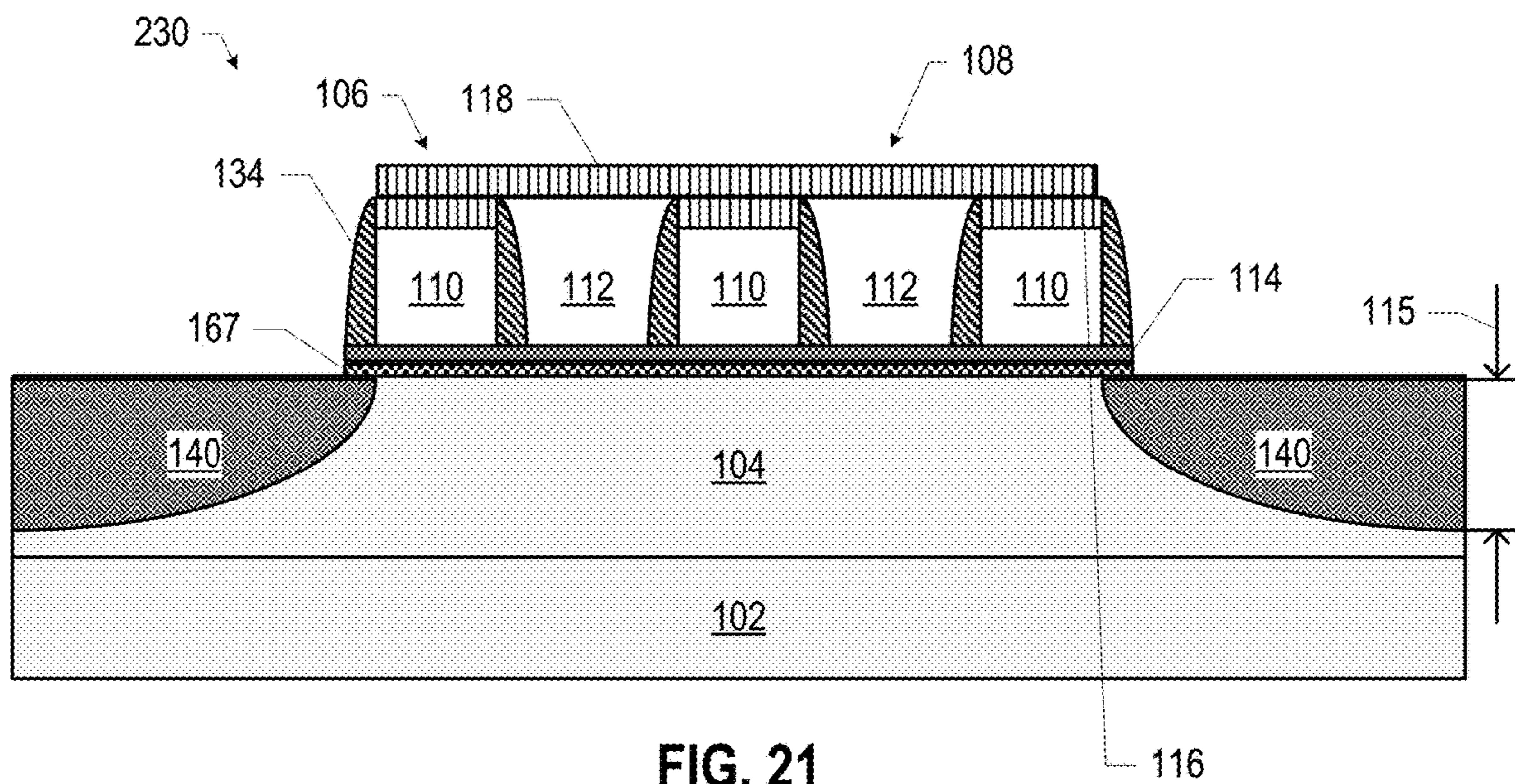


FIG. 21

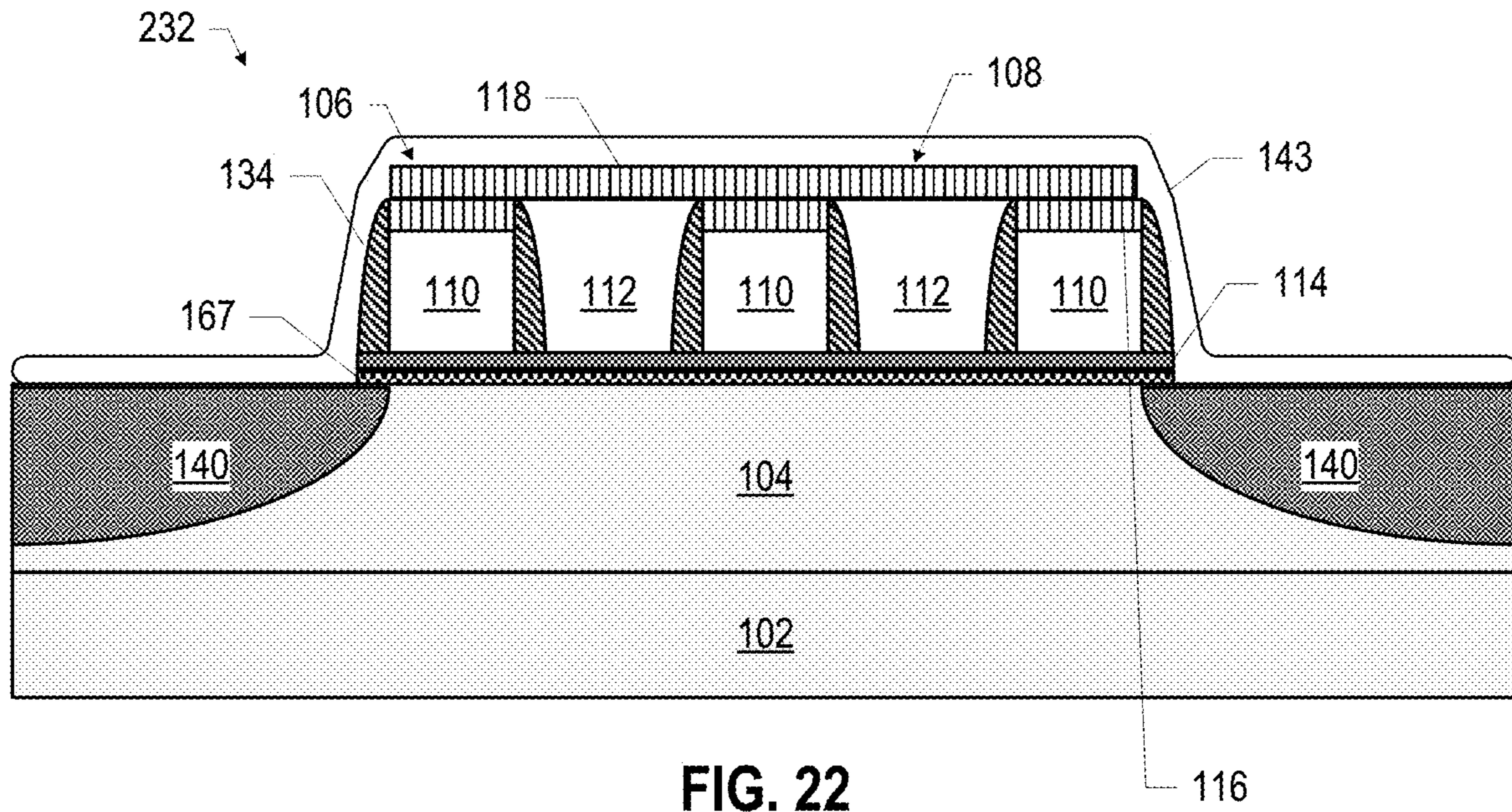


FIG. 22

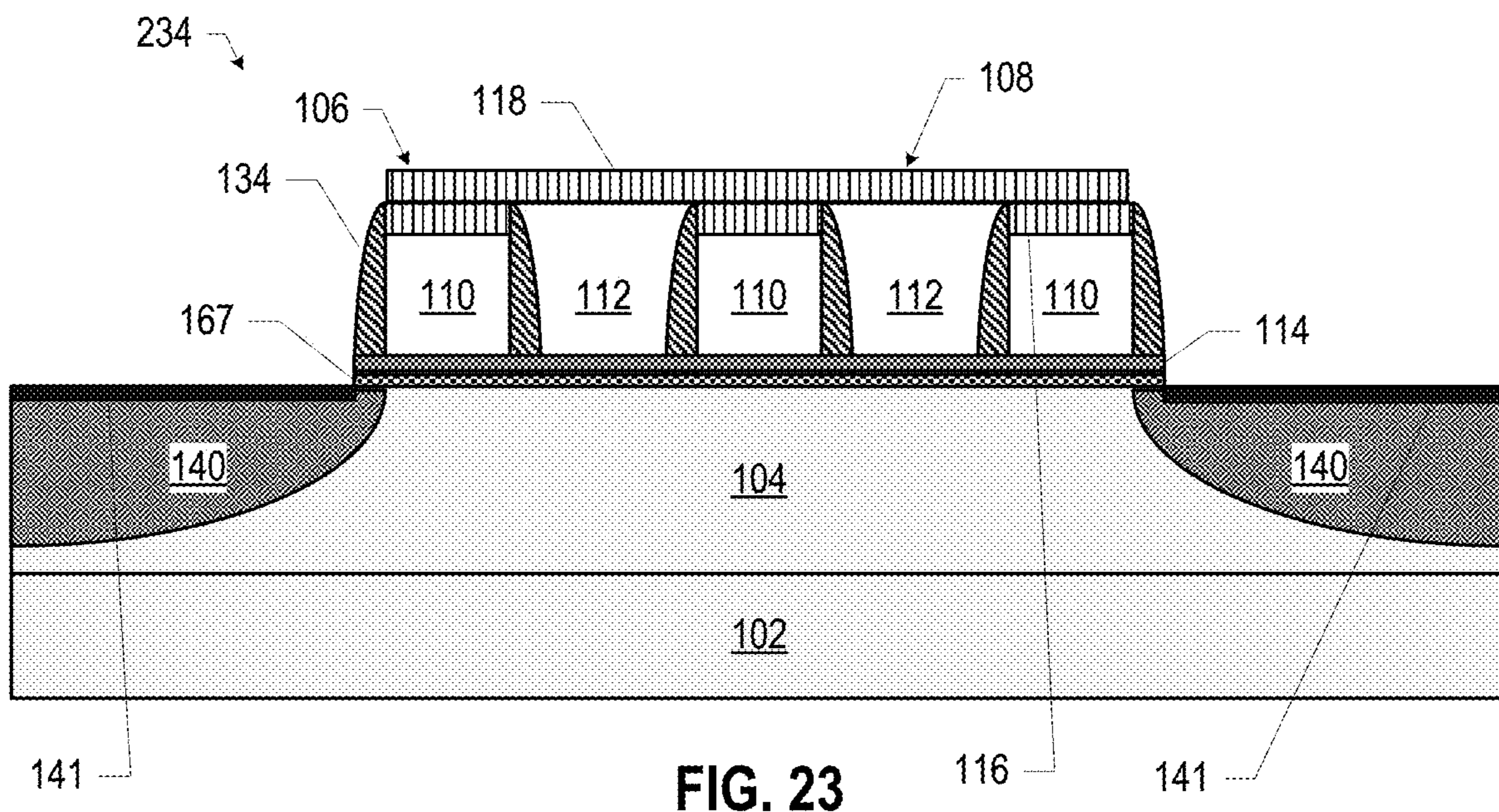


FIG. 23



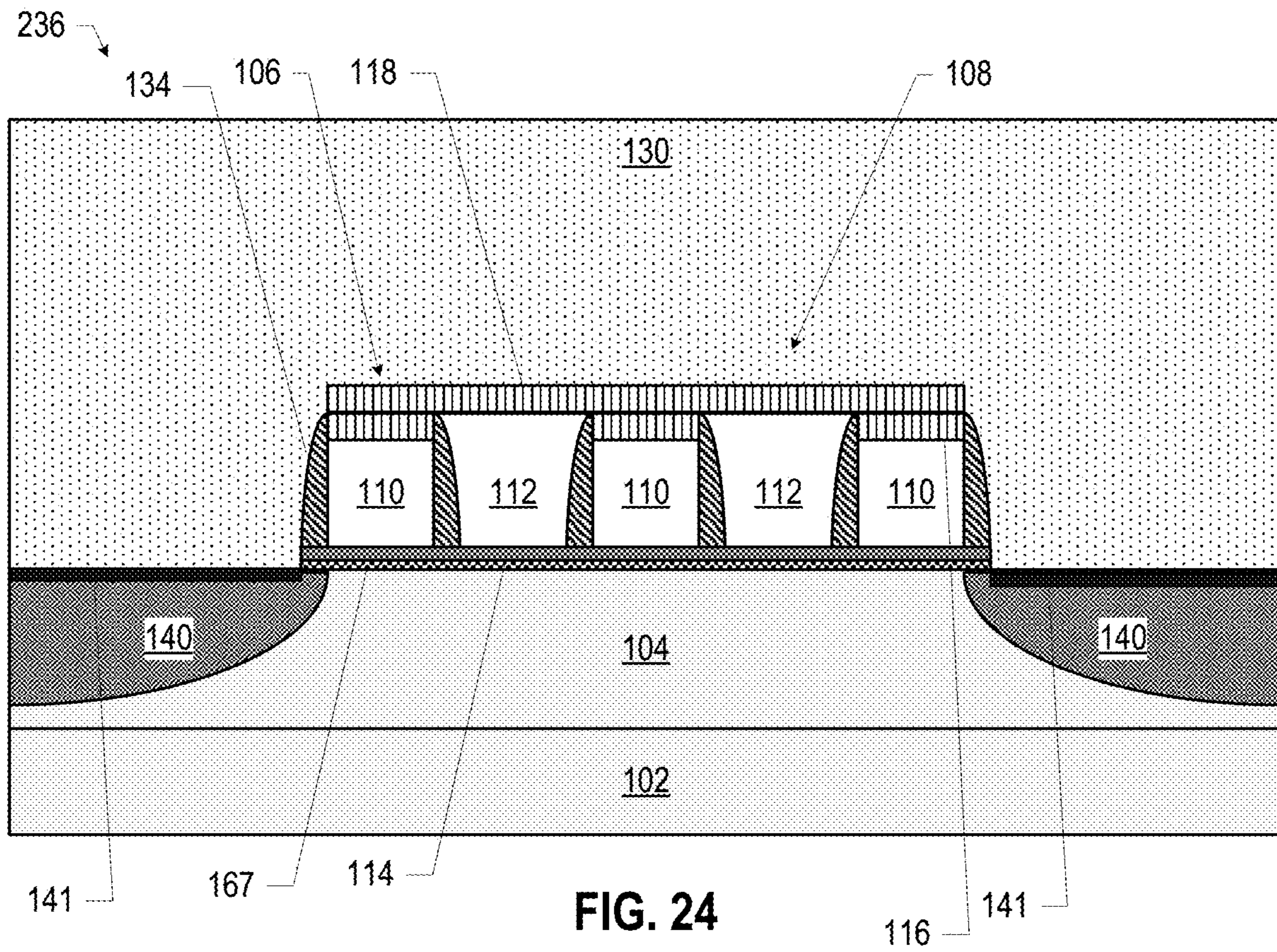


FIG. 24

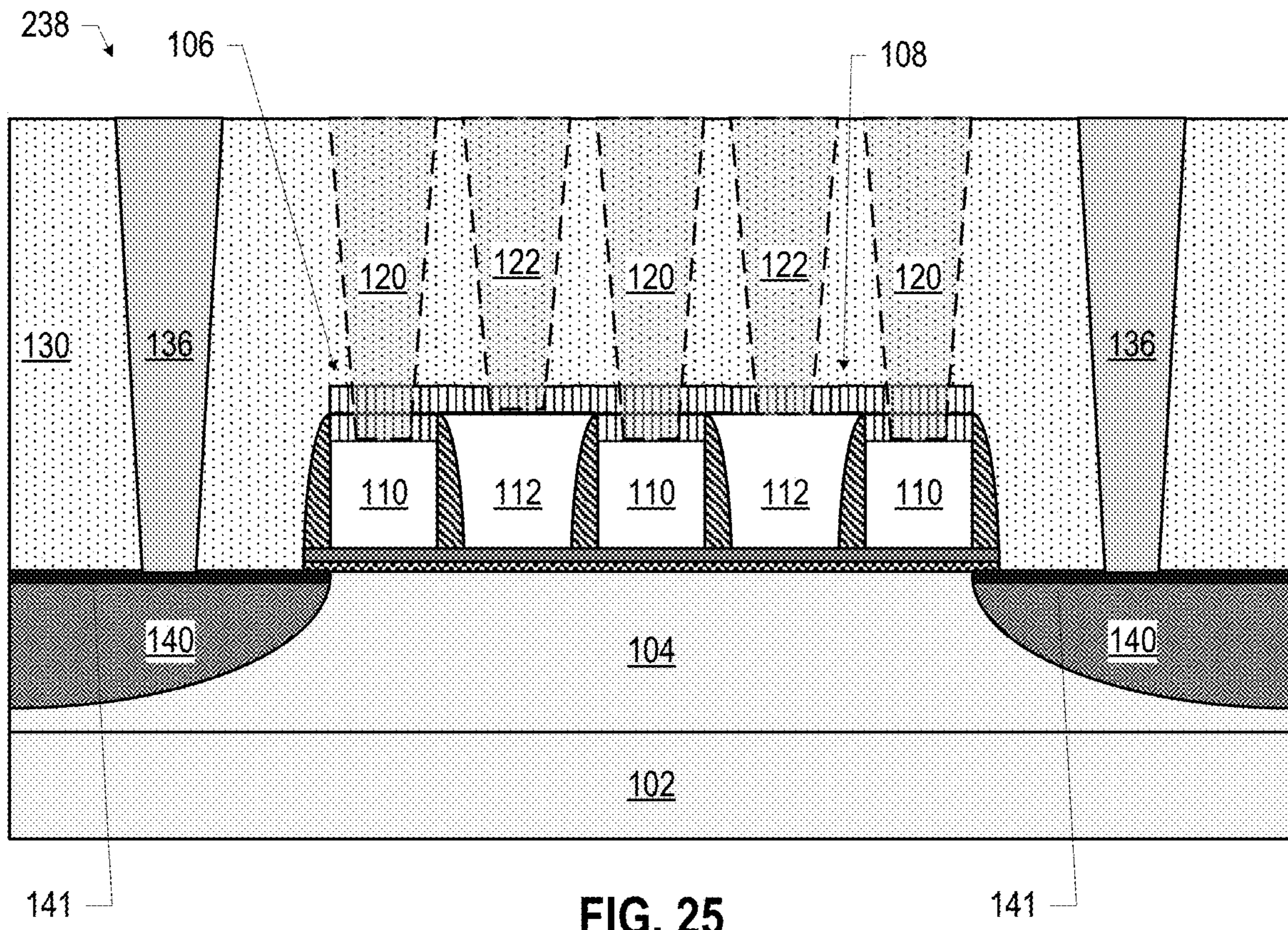


FIG. 25



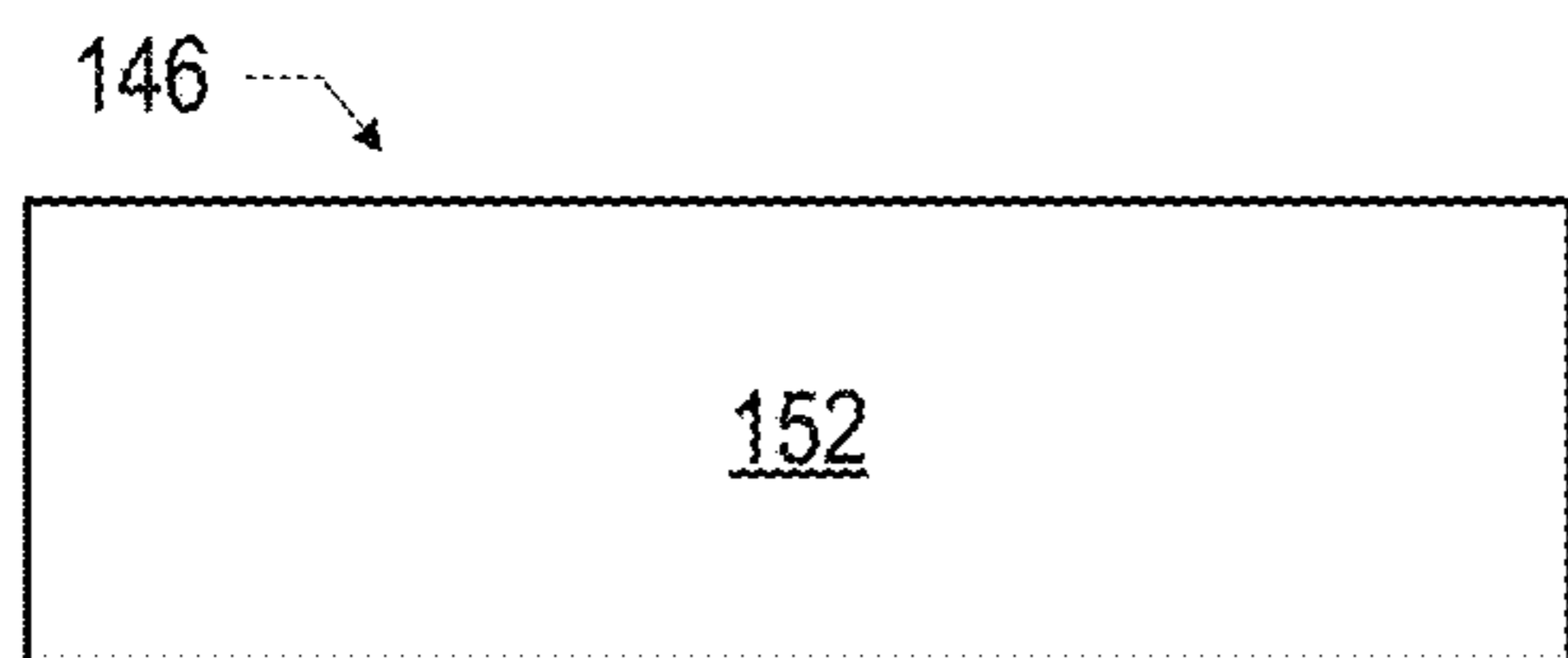


FIG. 26

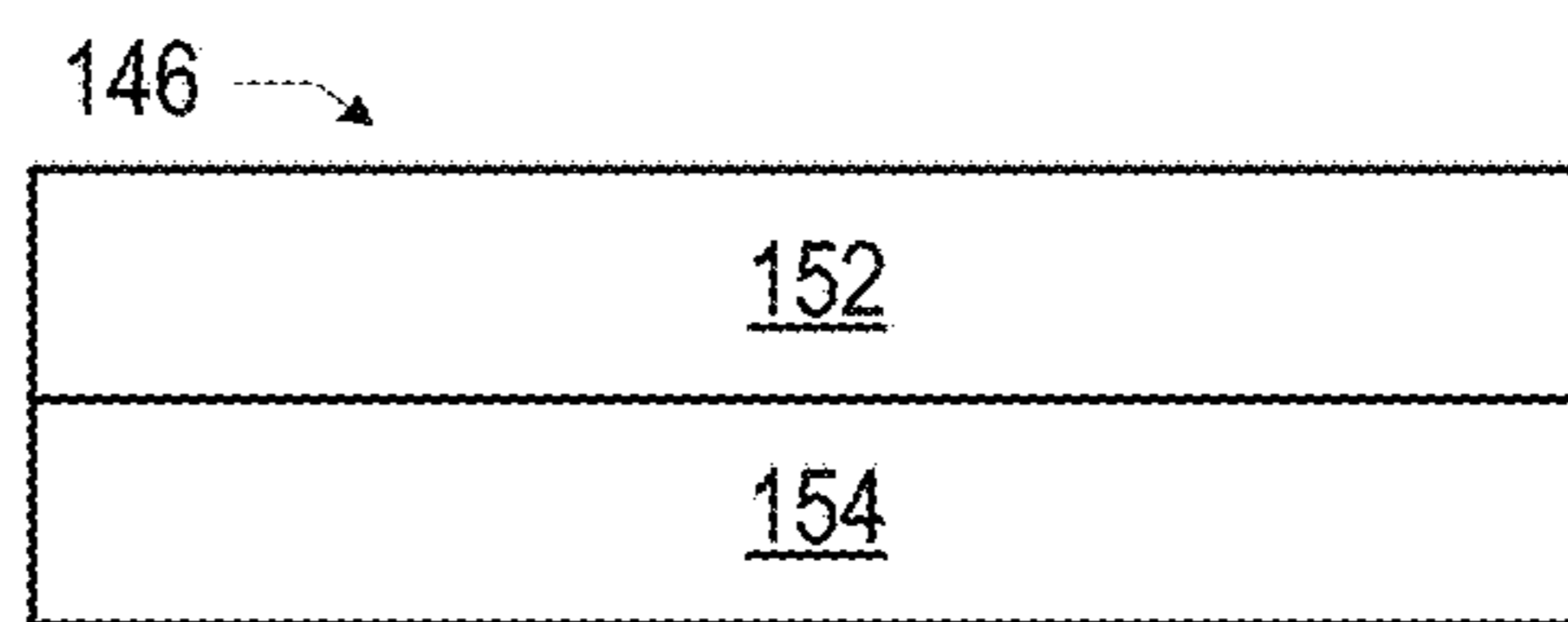


FIG. 27

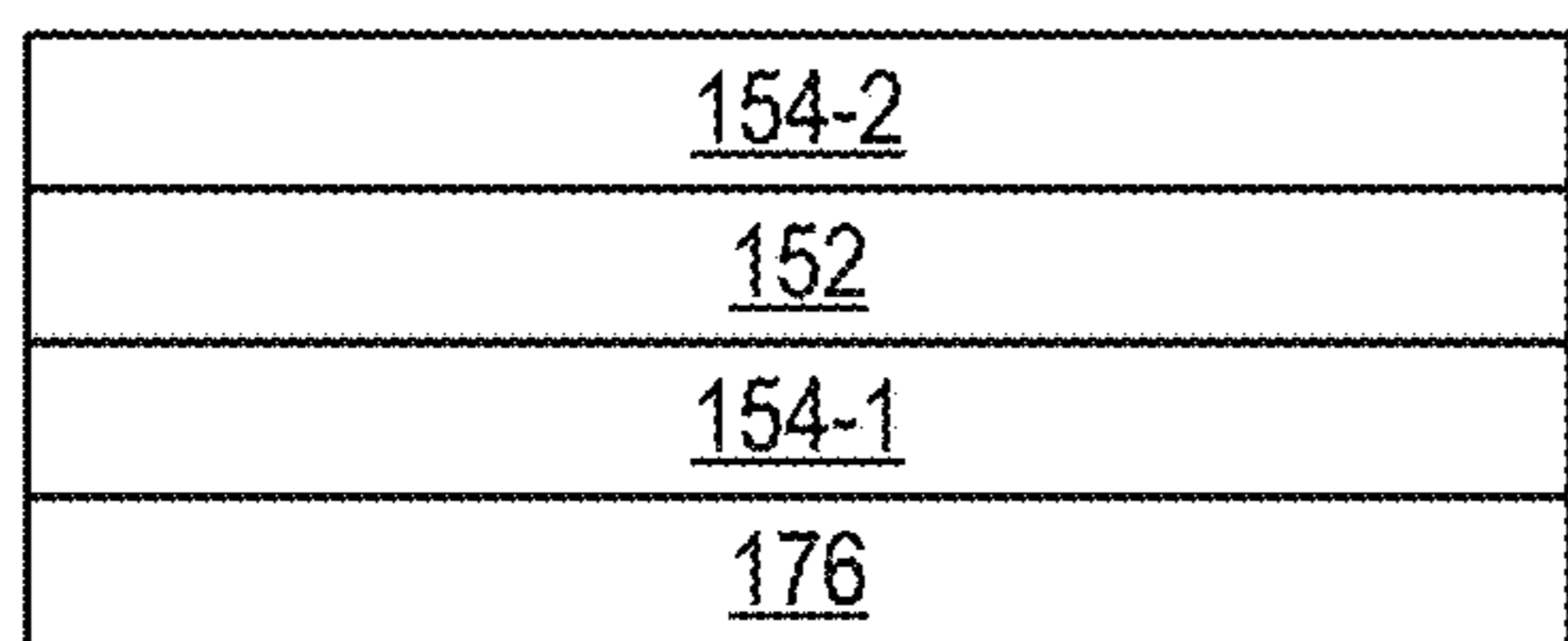


FIG. 28

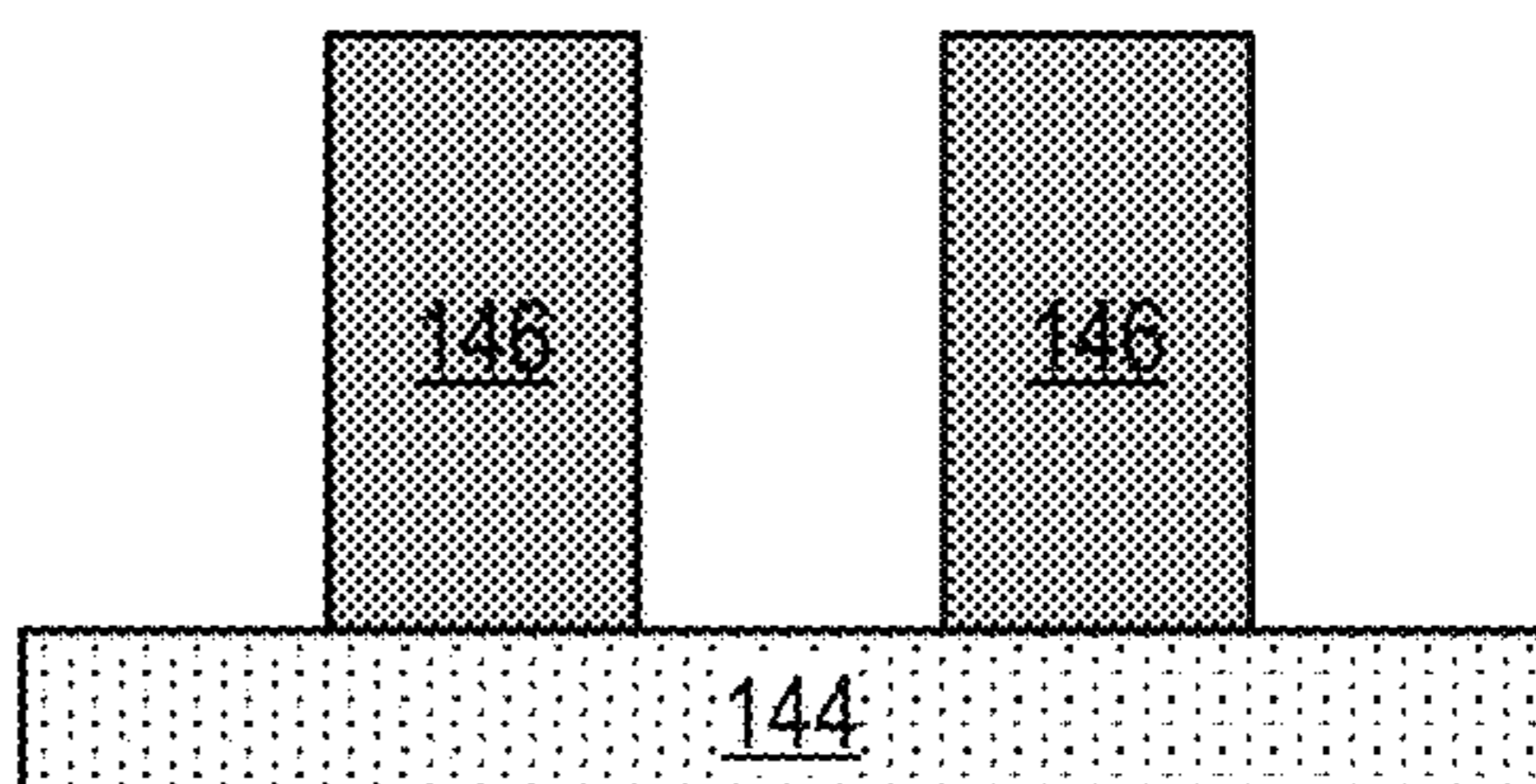


FIG. 29

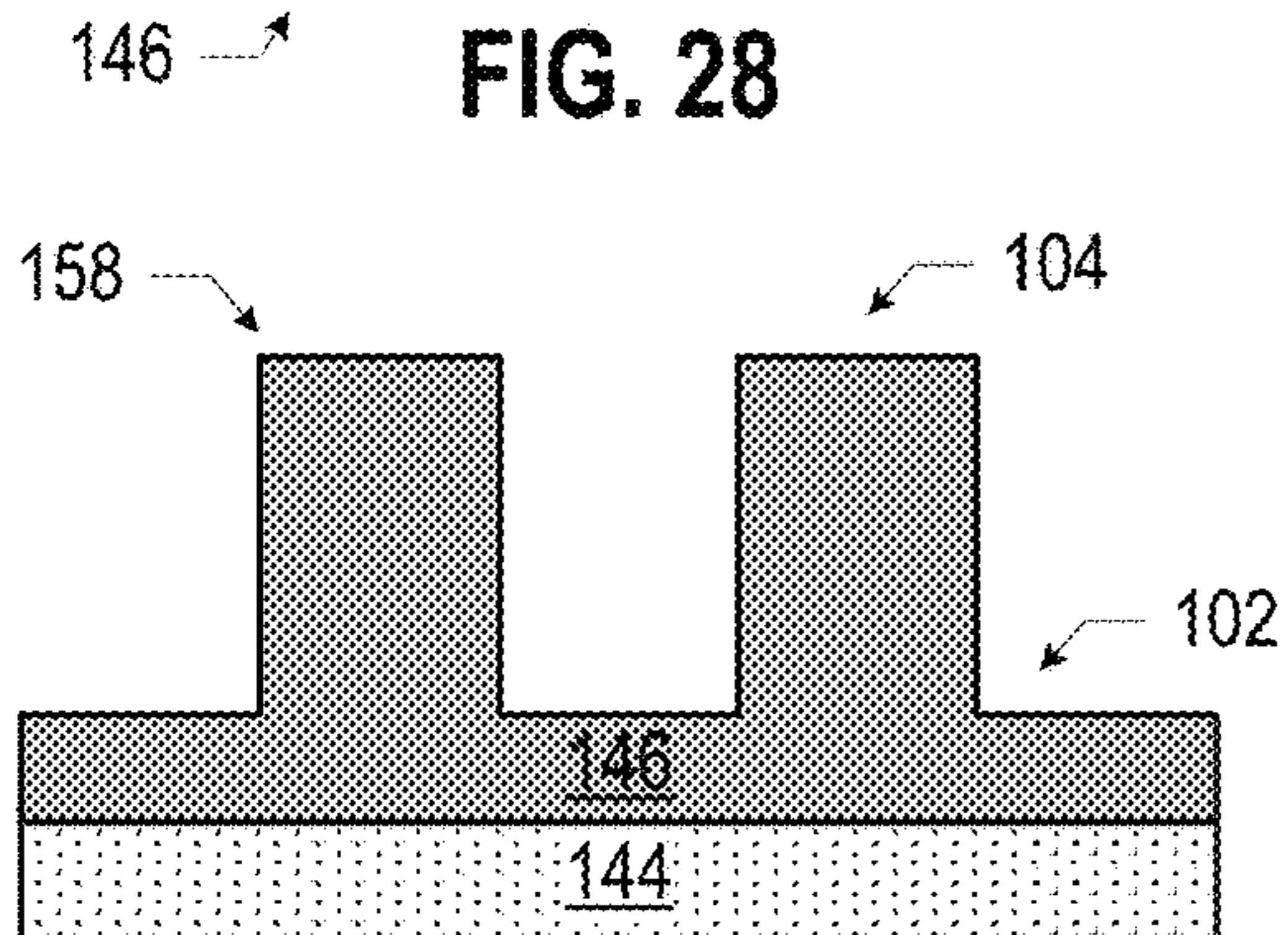


FIG. 30

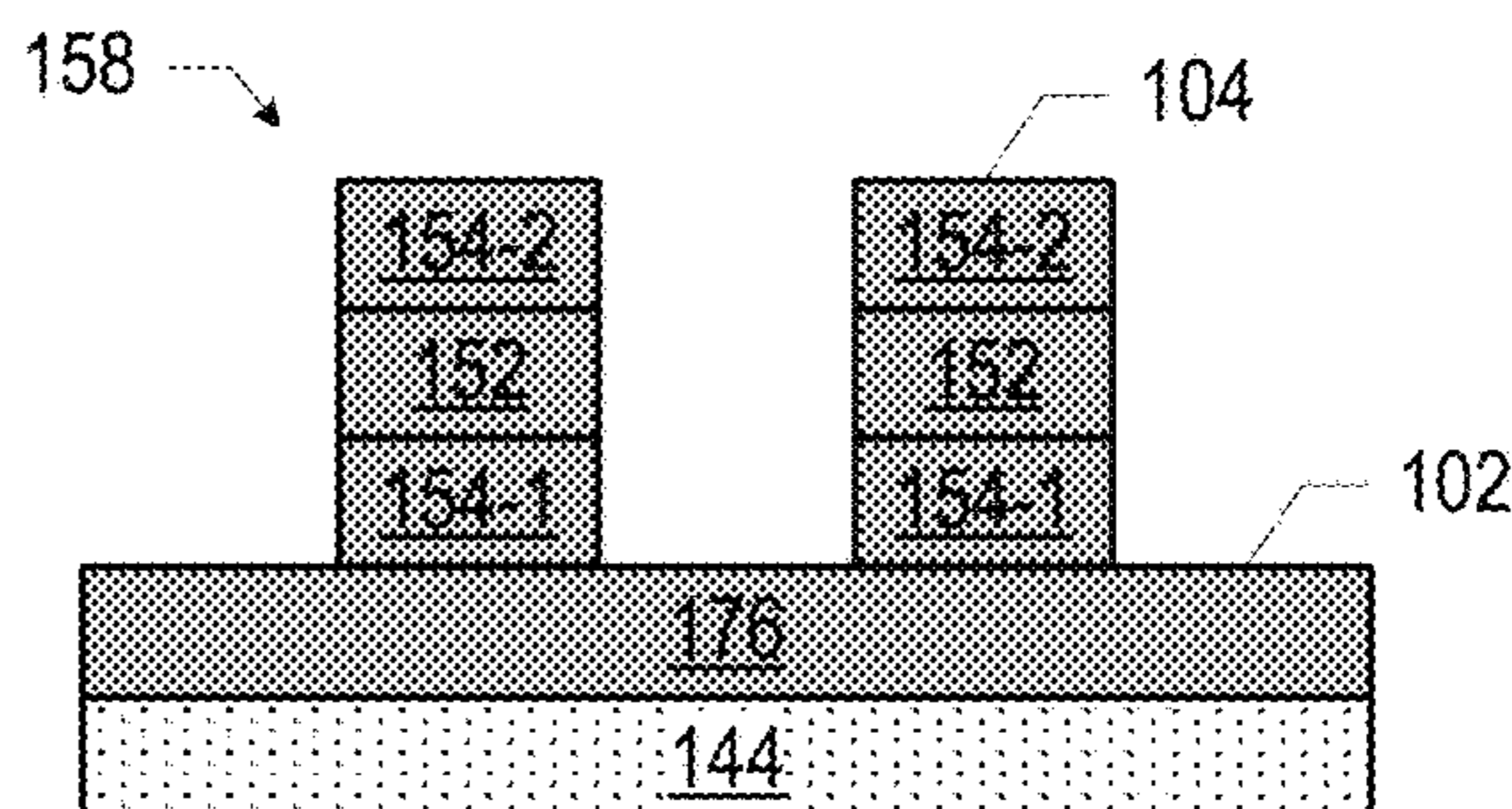


FIG. 31

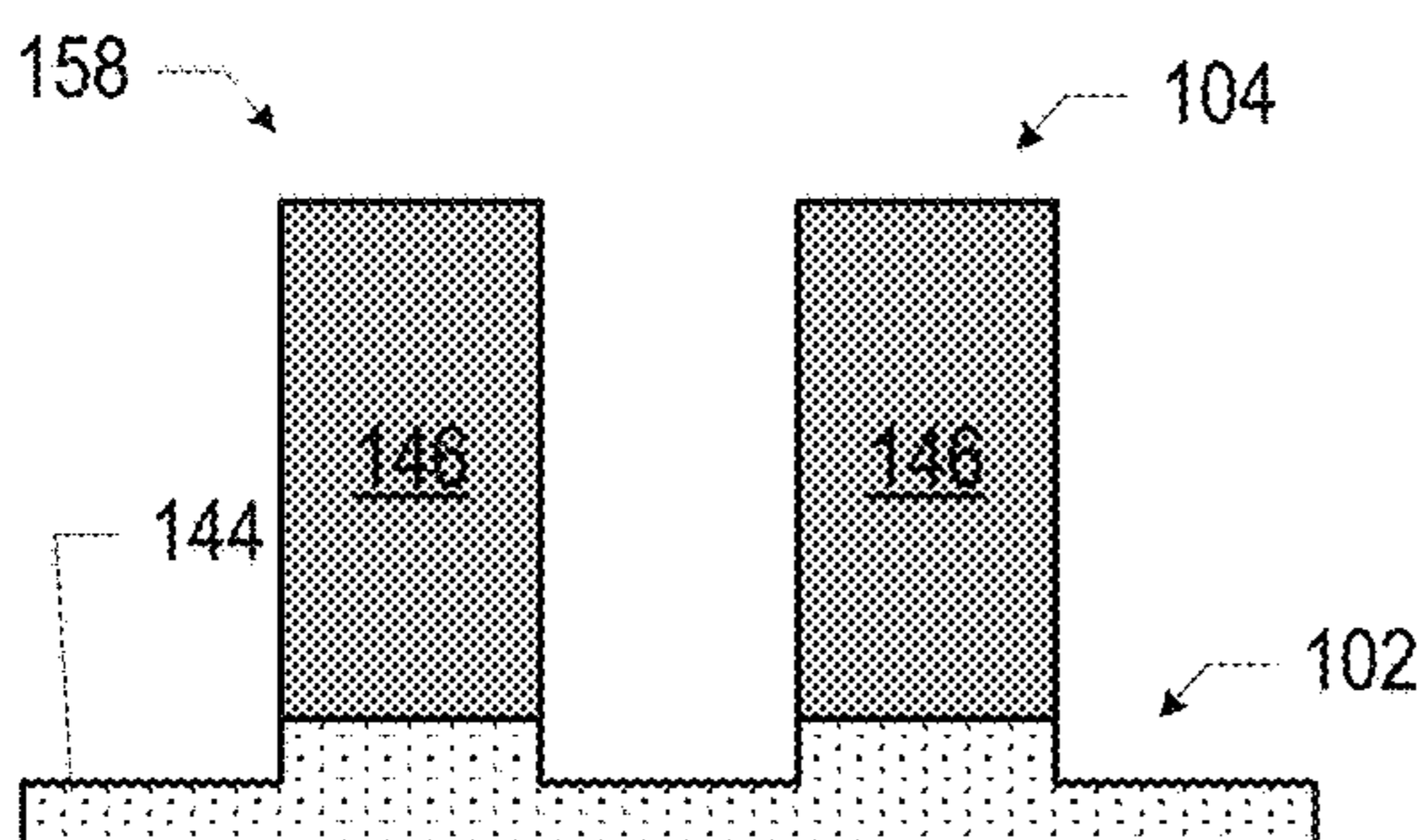


FIG. 32

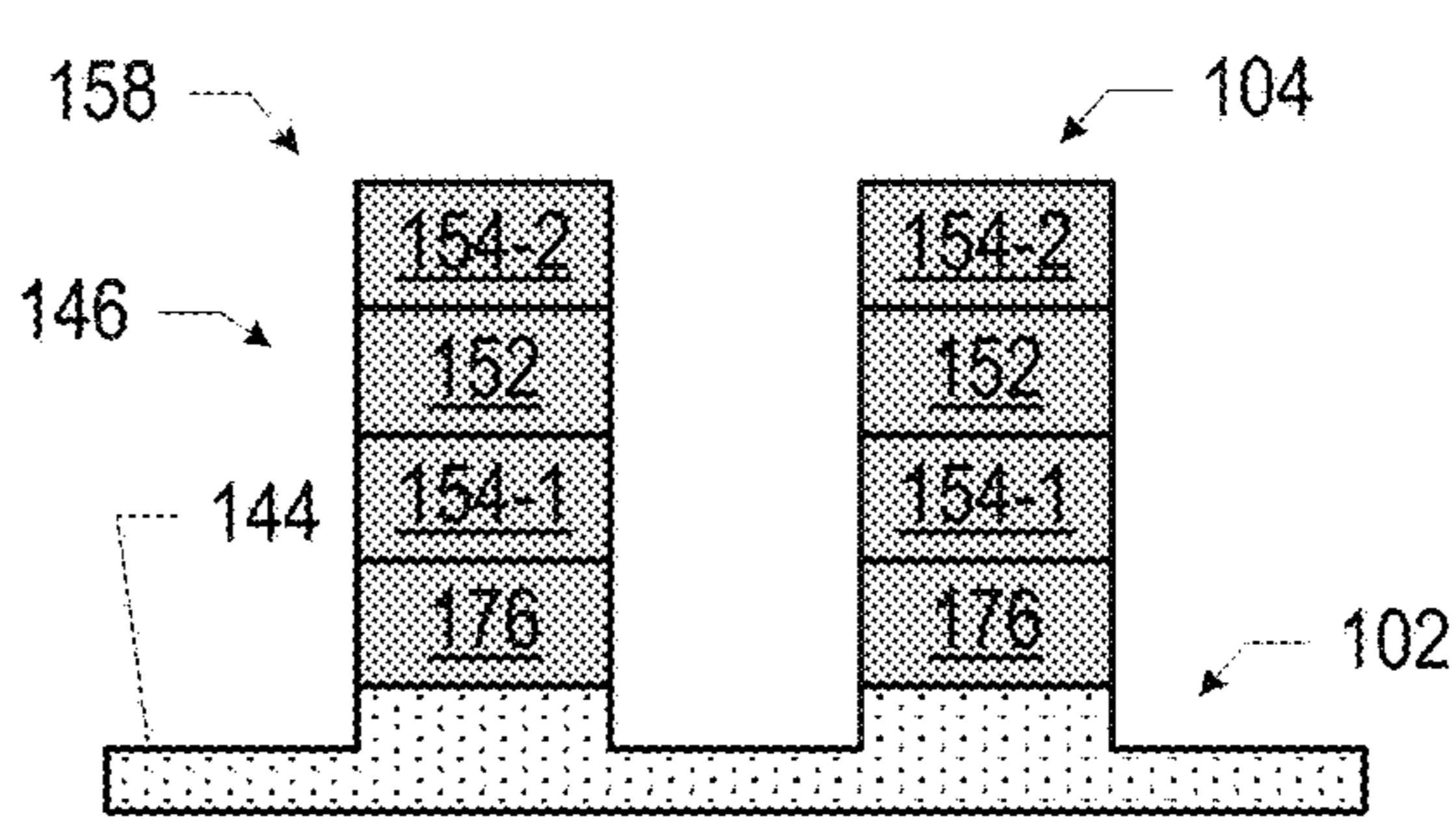


FIG. 33

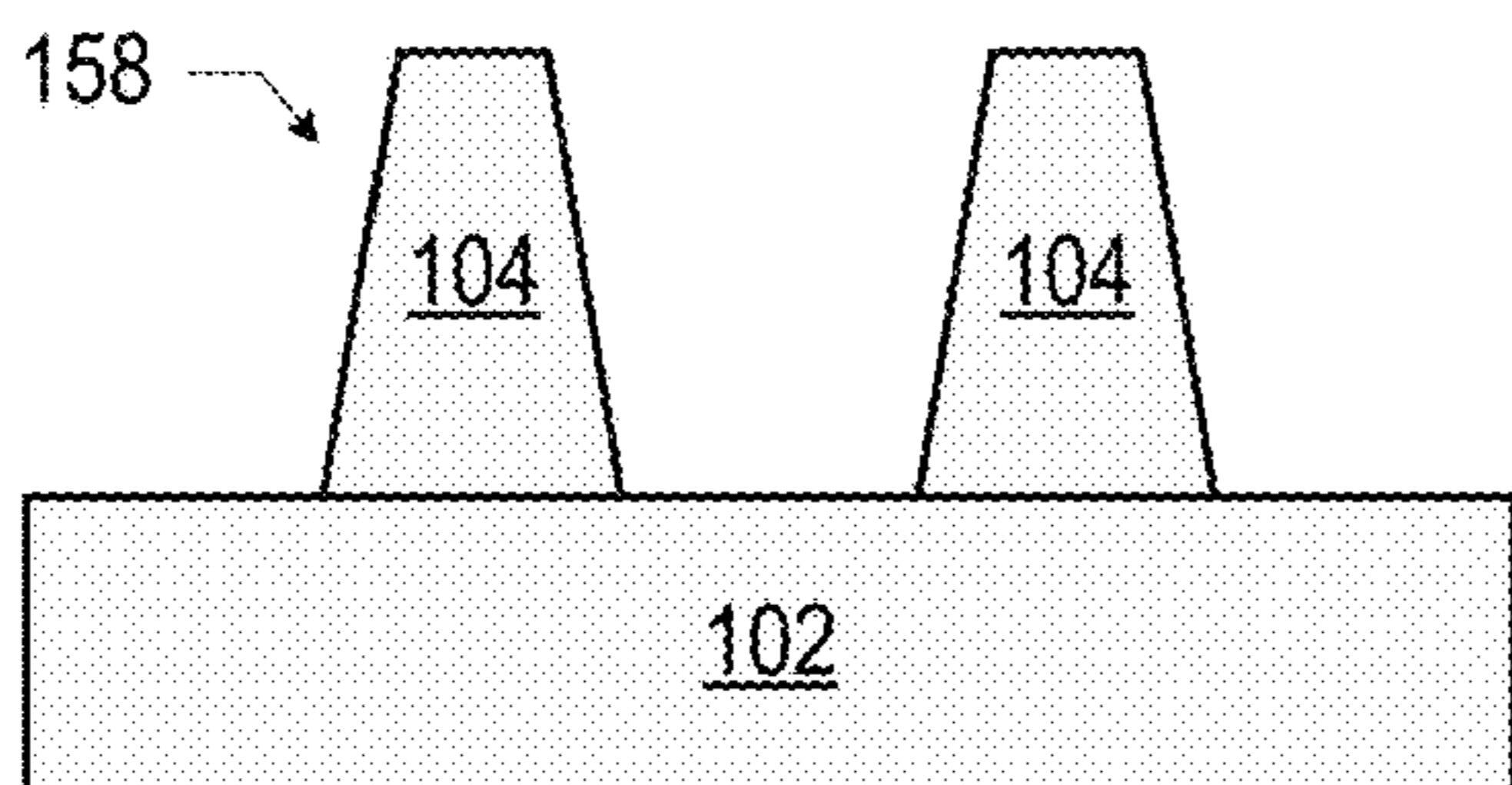


FIG. 34

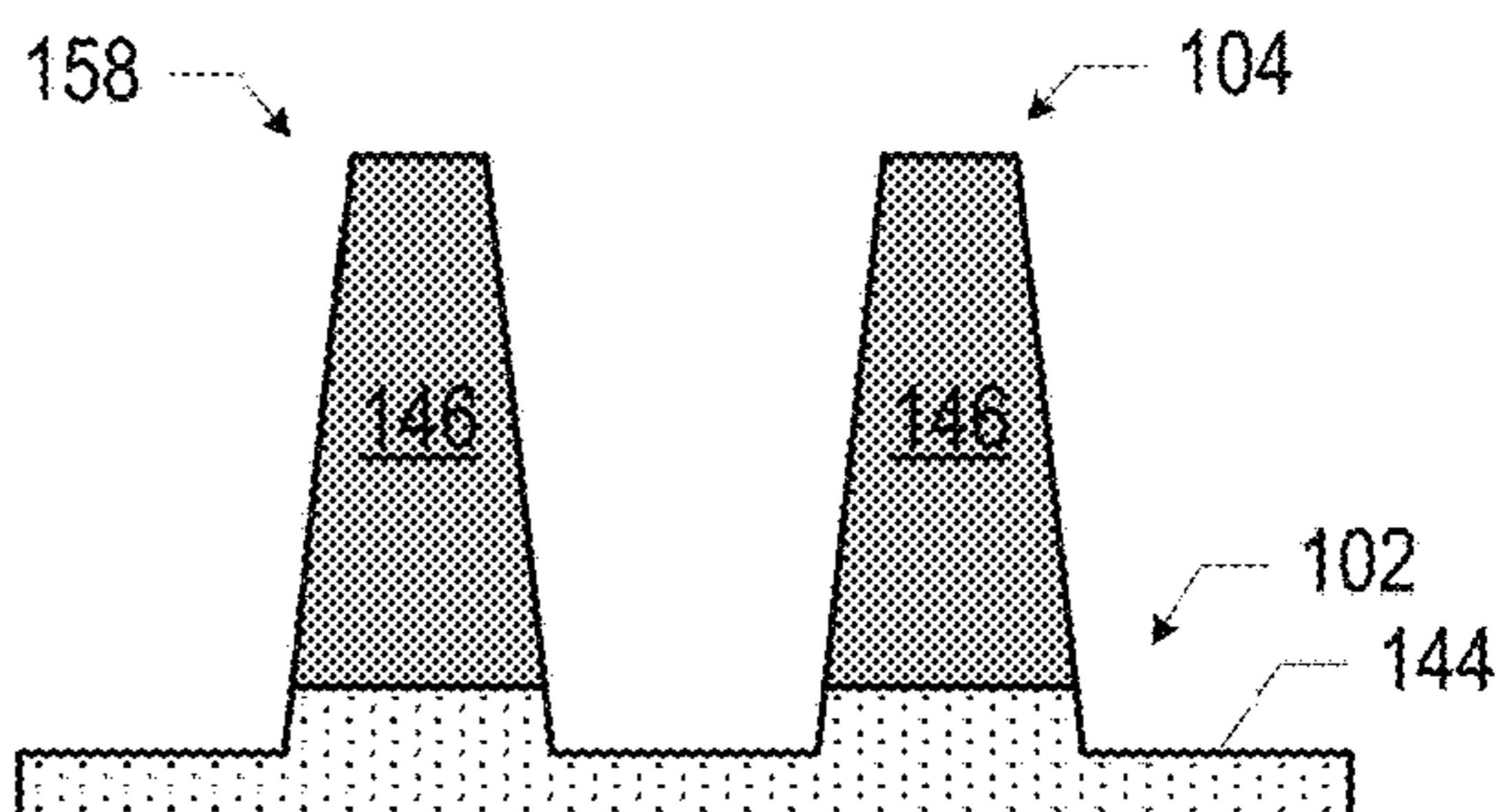
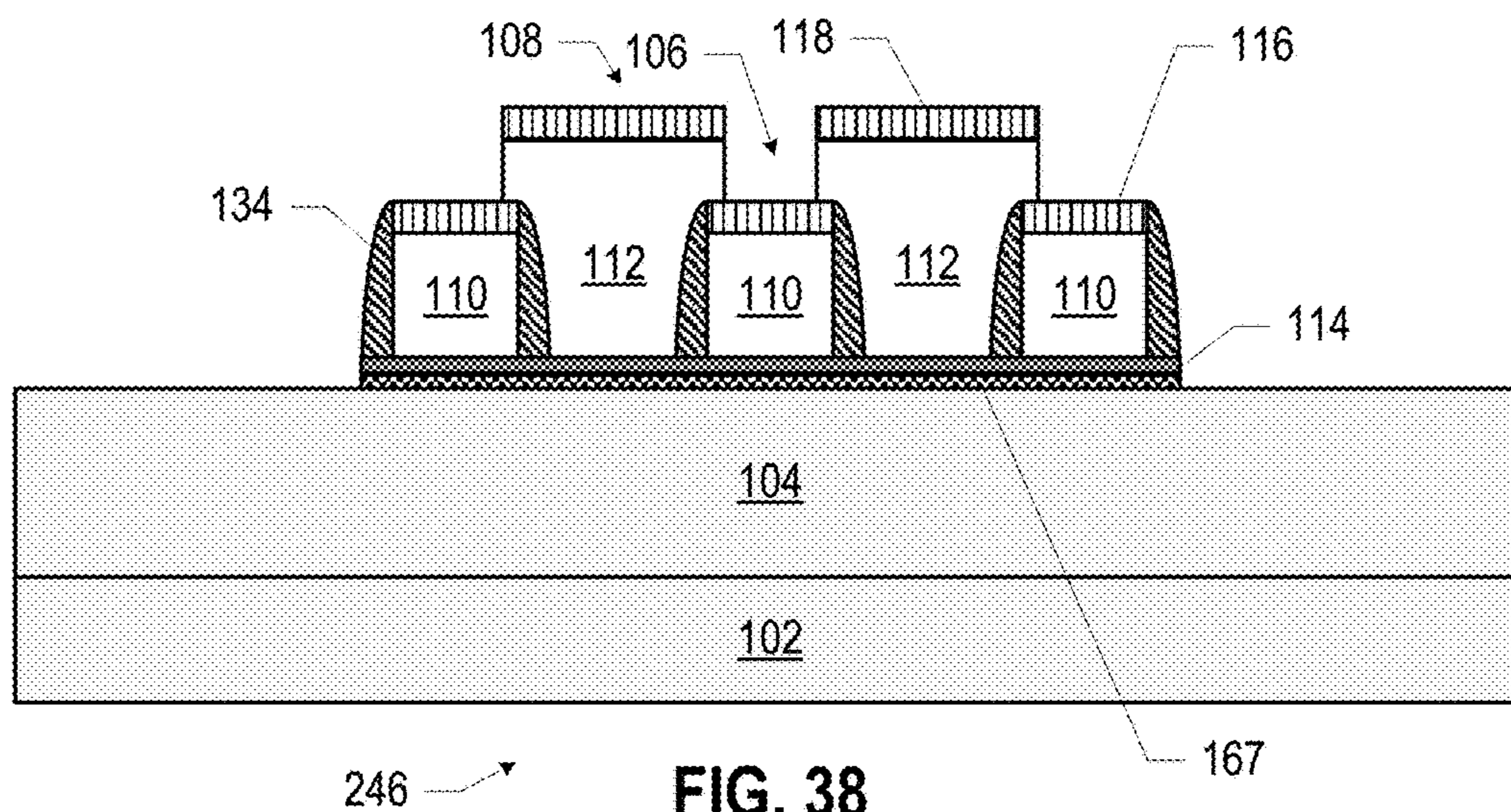
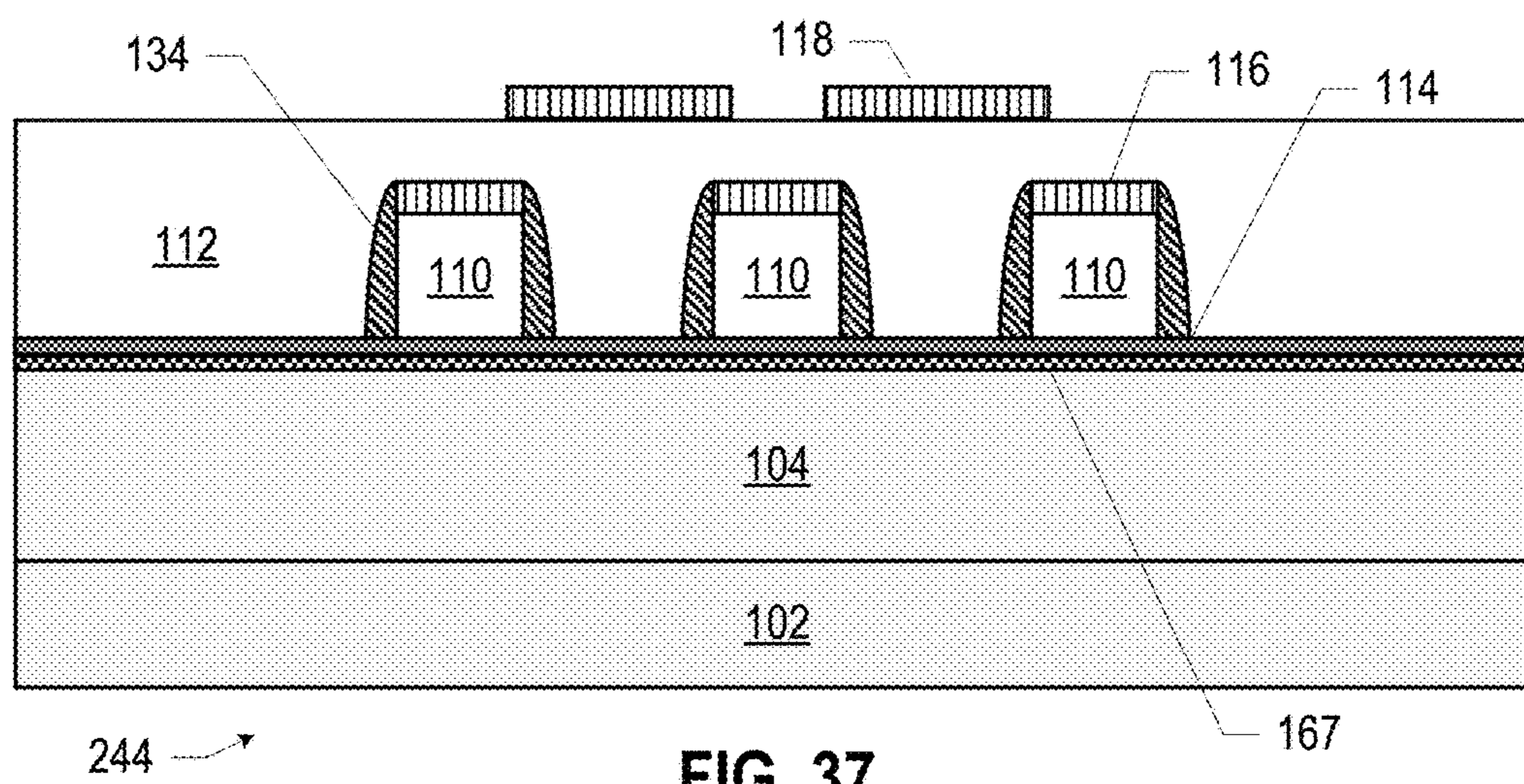
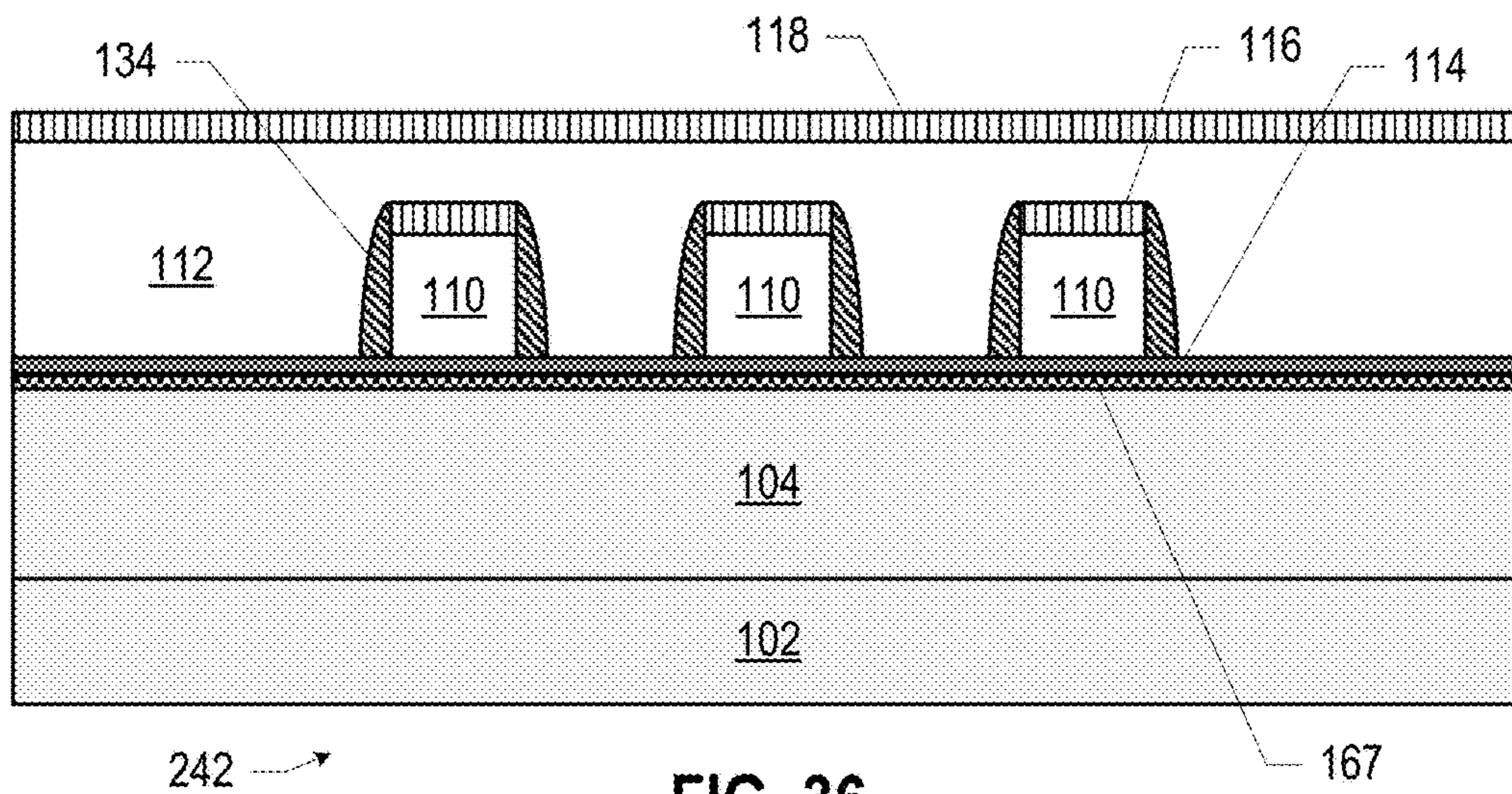


FIG. 35







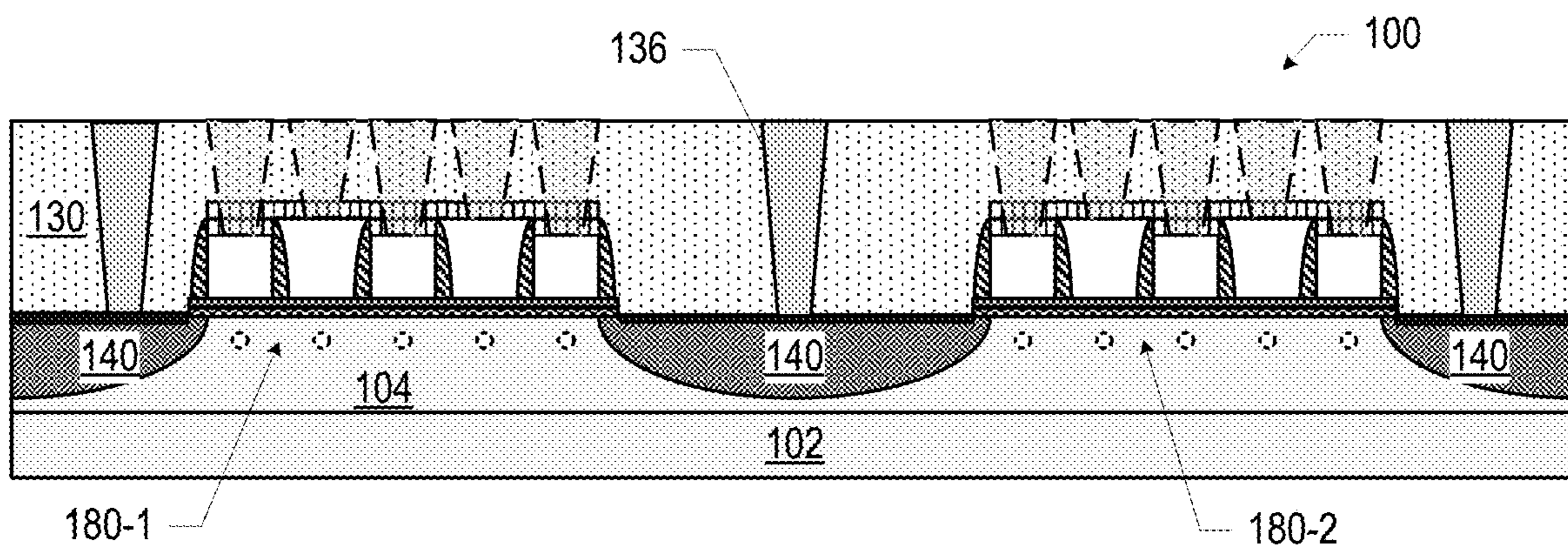


FIG. 39

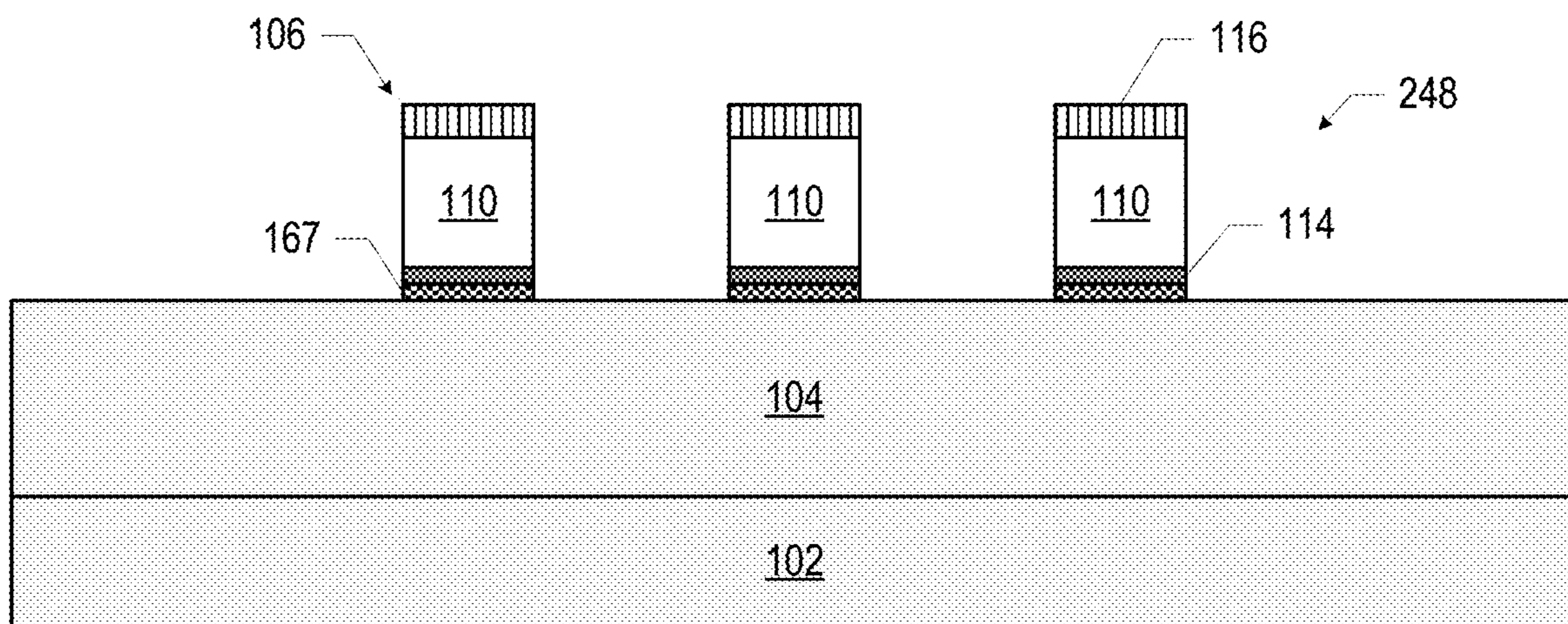


FIG. 40

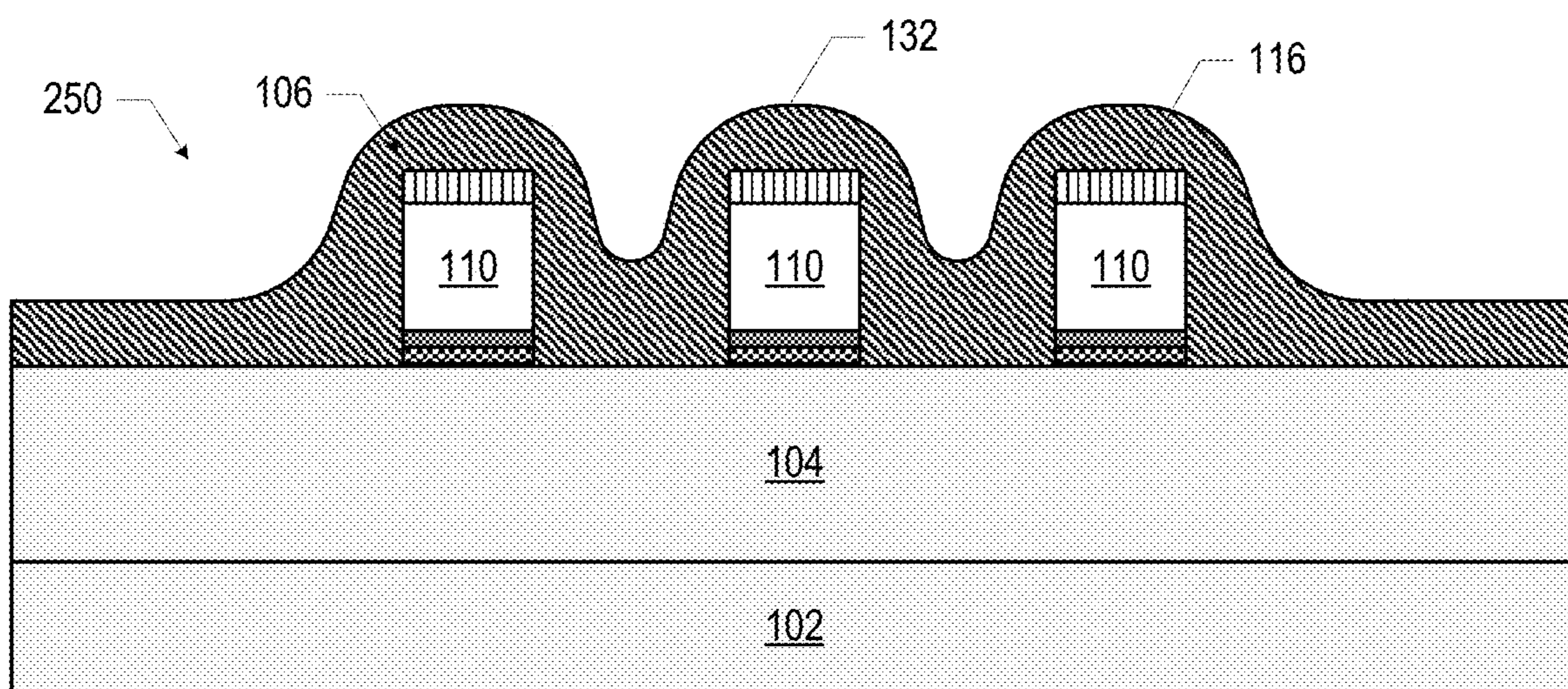


FIG. 41



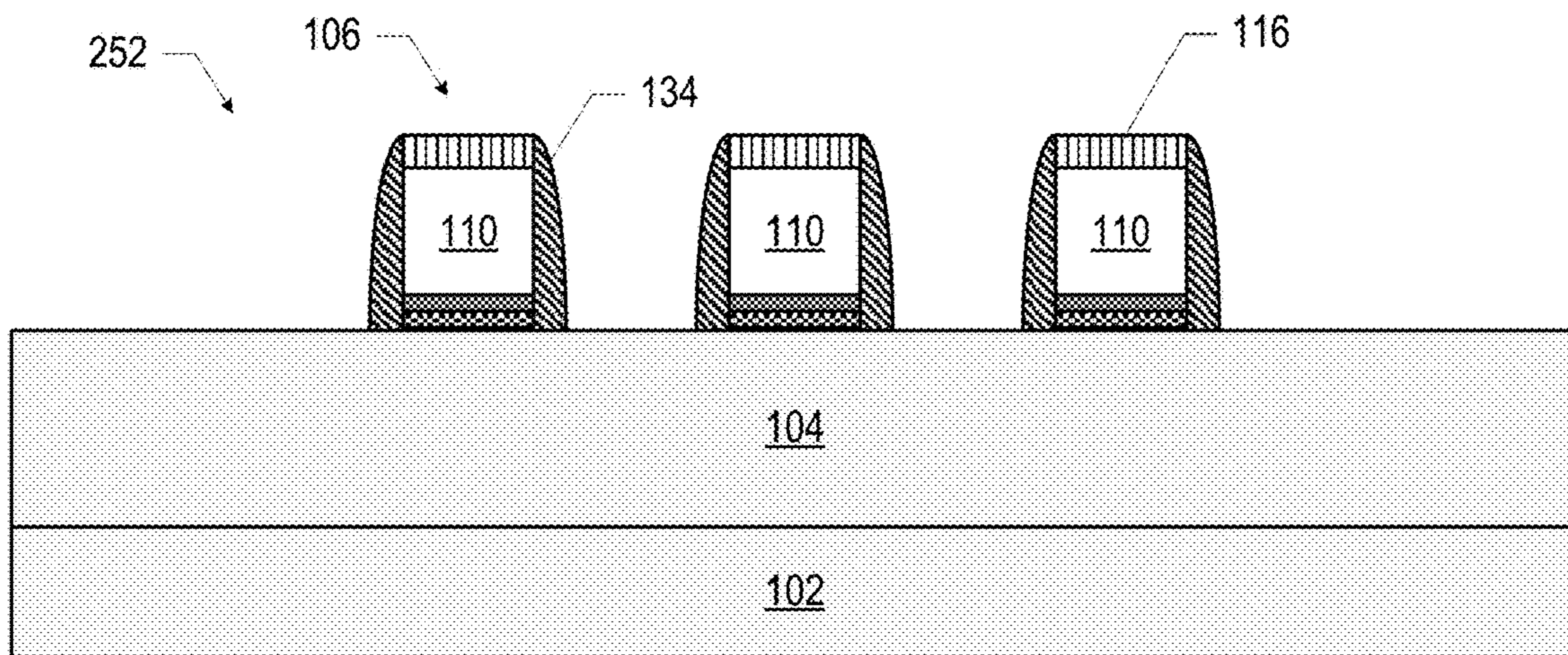


FIG. 42

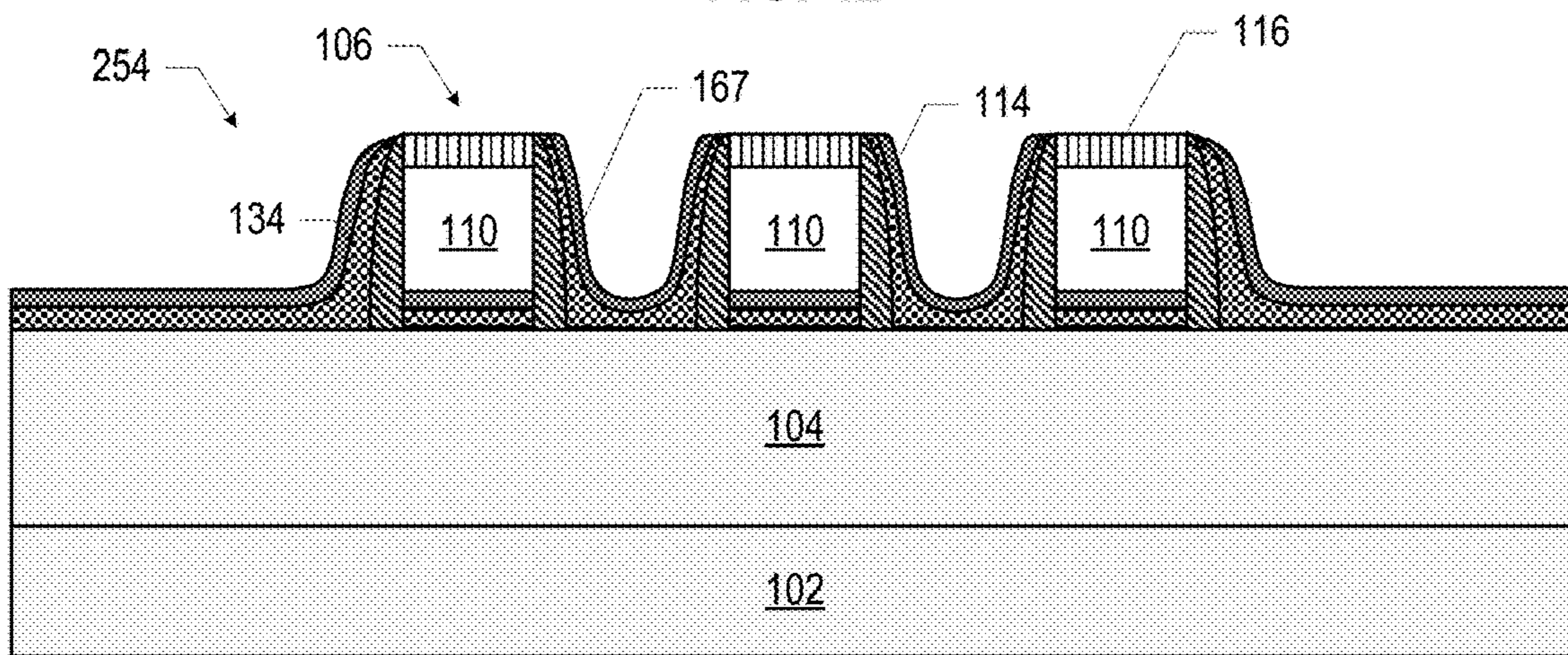


FIG. 43

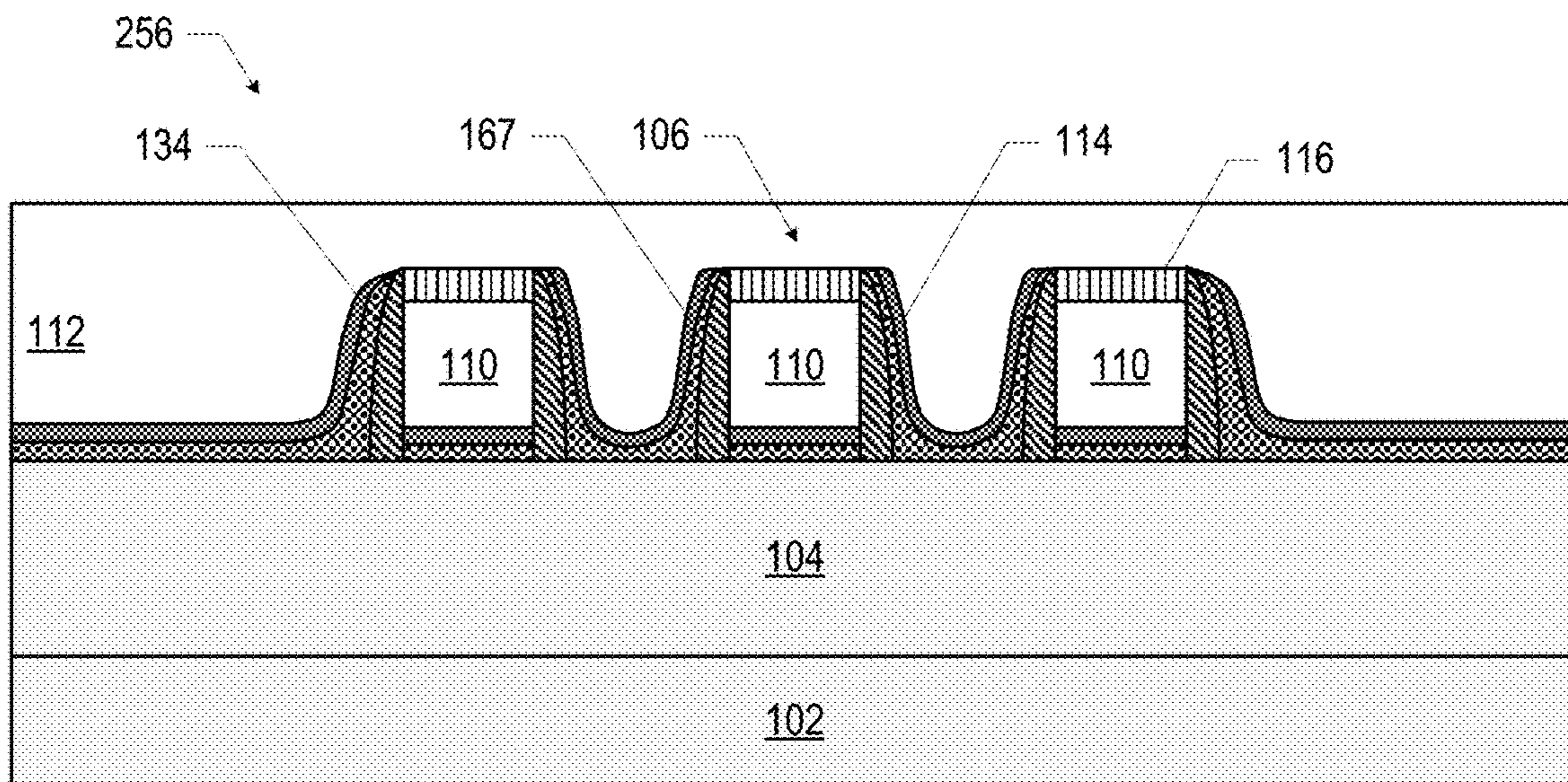


FIG. 44

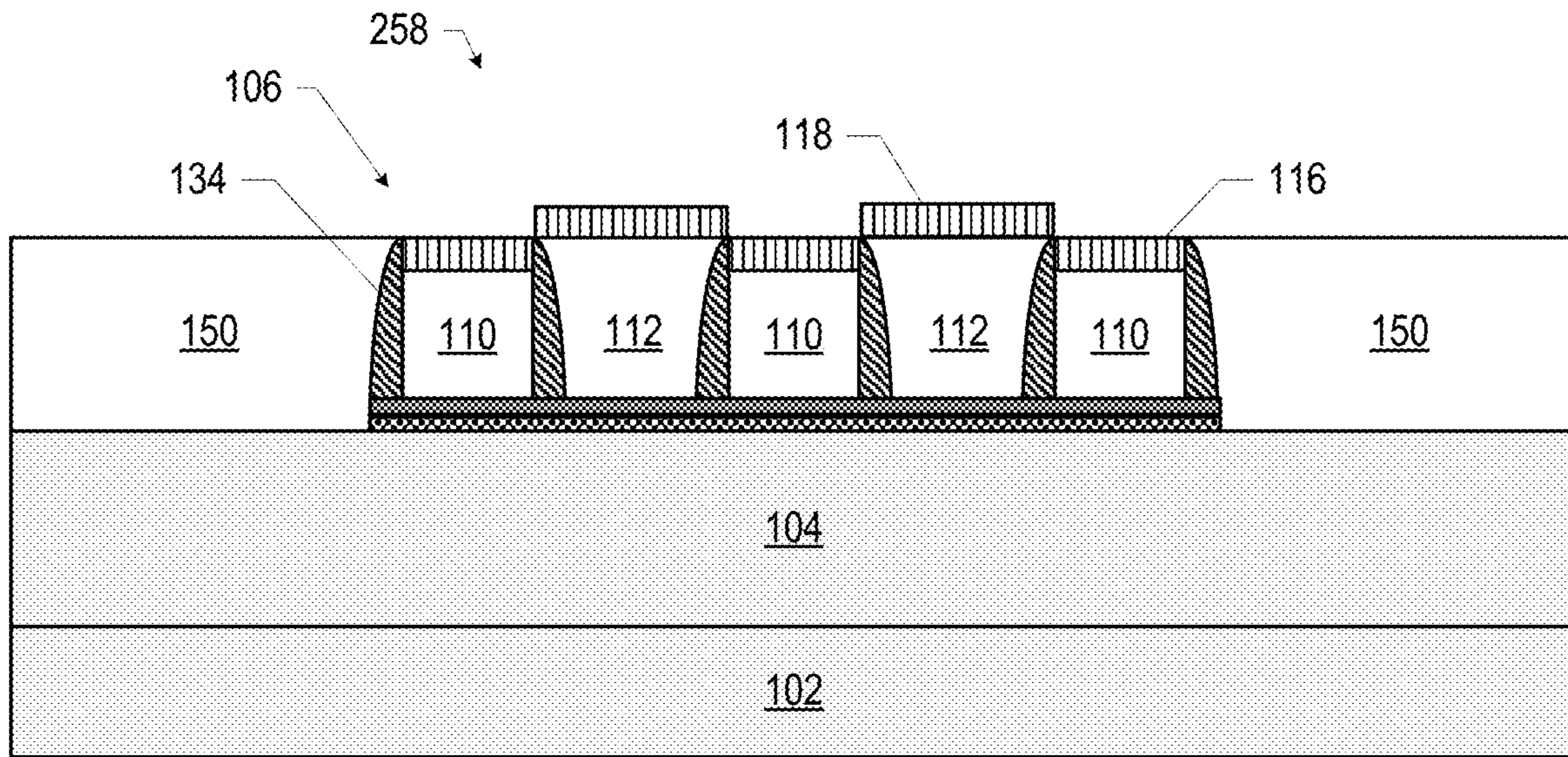


FIG. 45

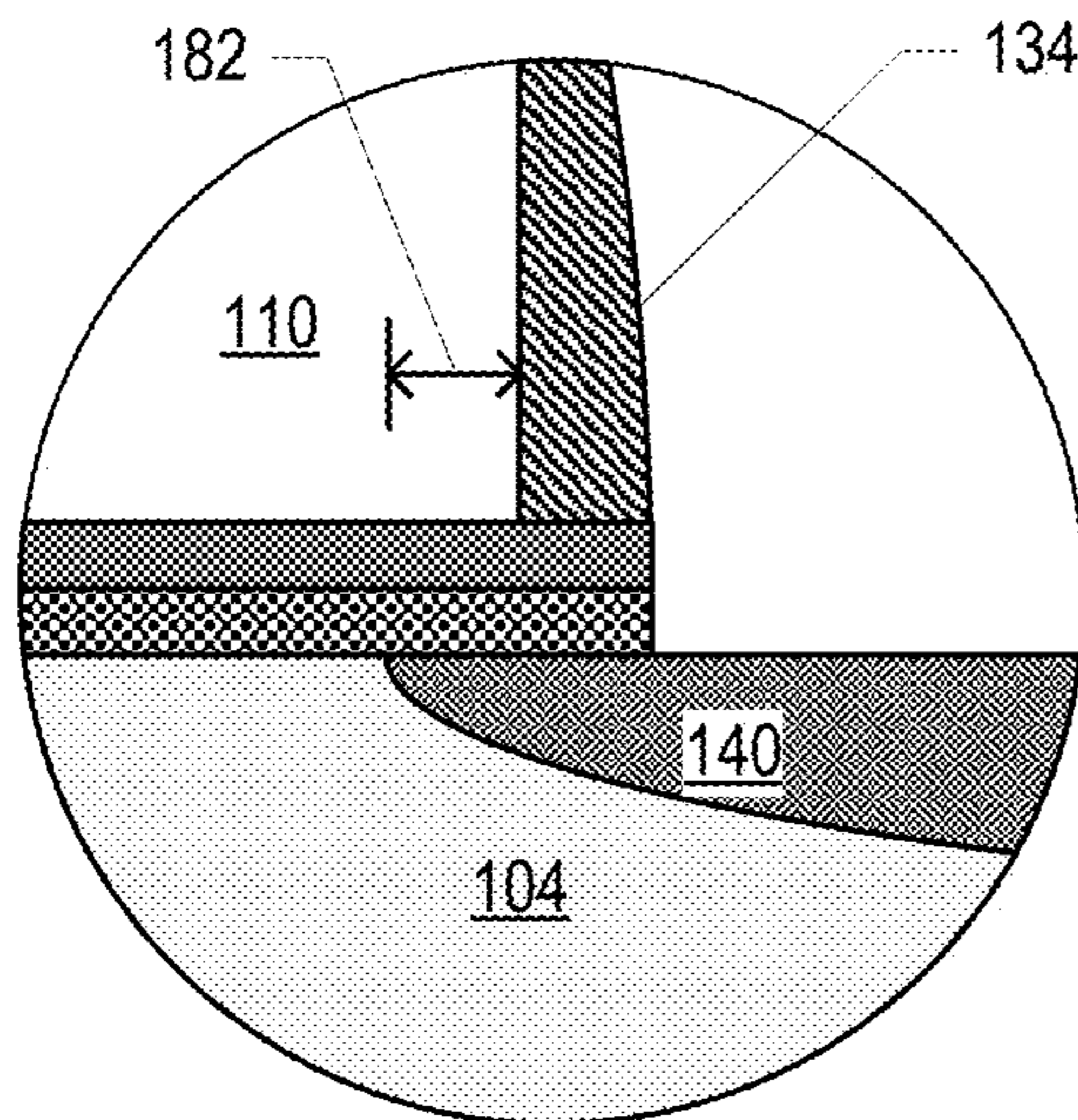


FIG. 46

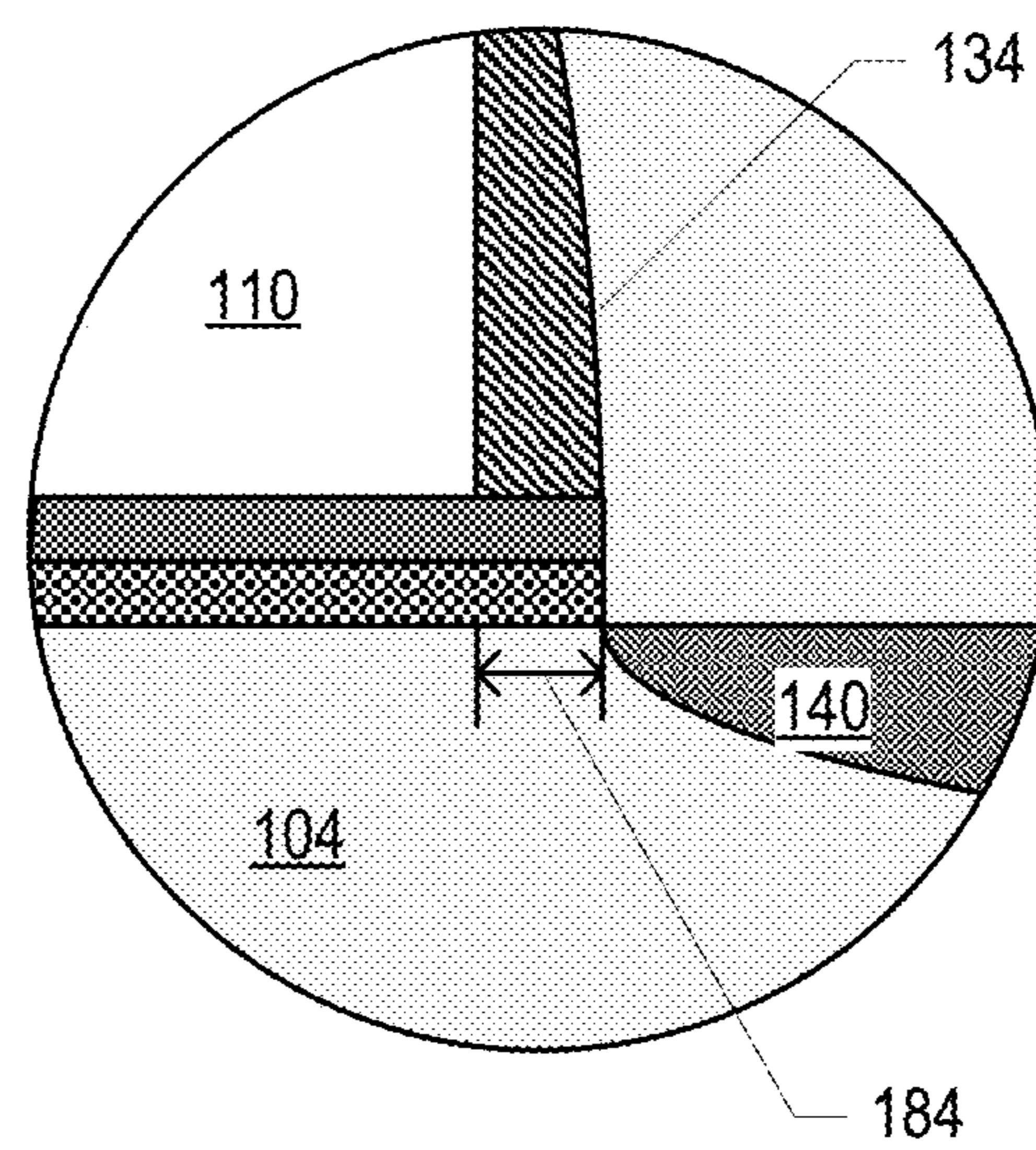


FIG. 47



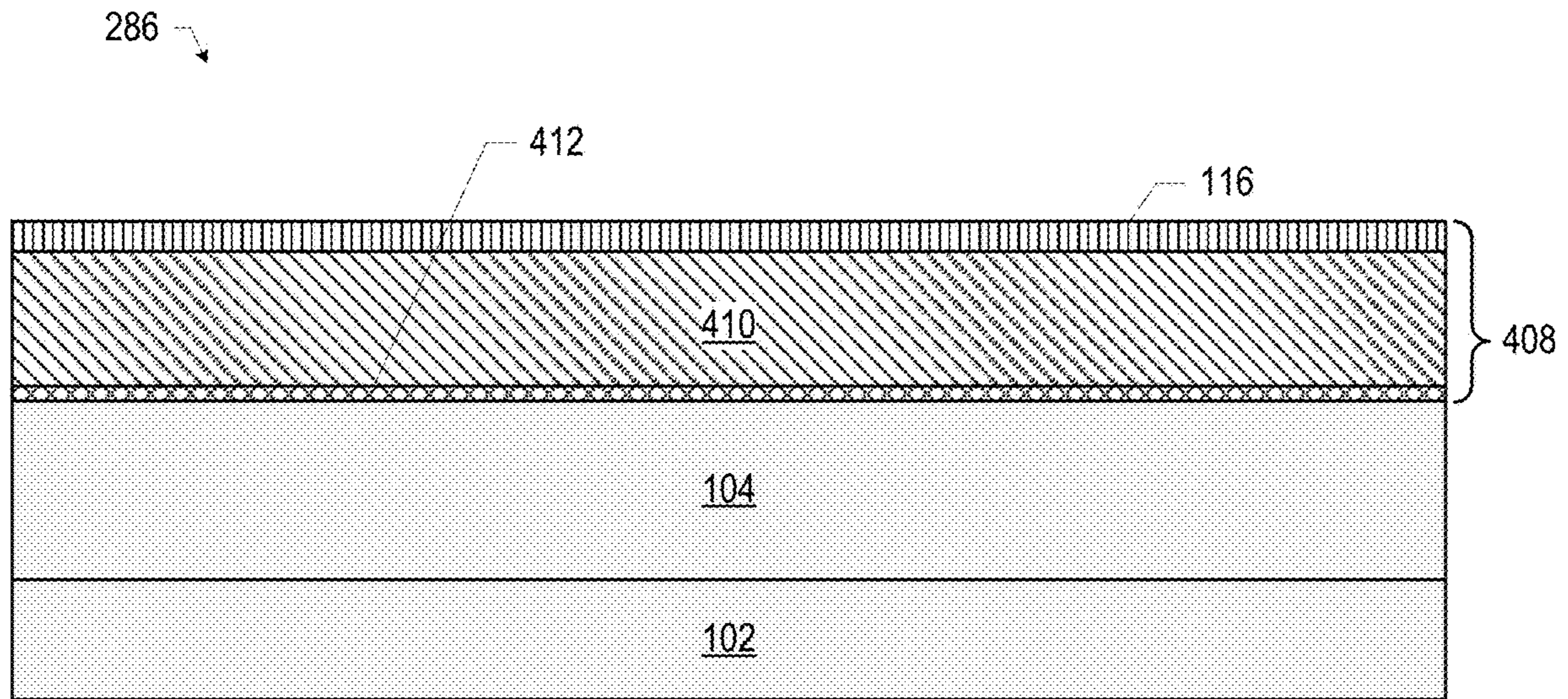


FIG. 48

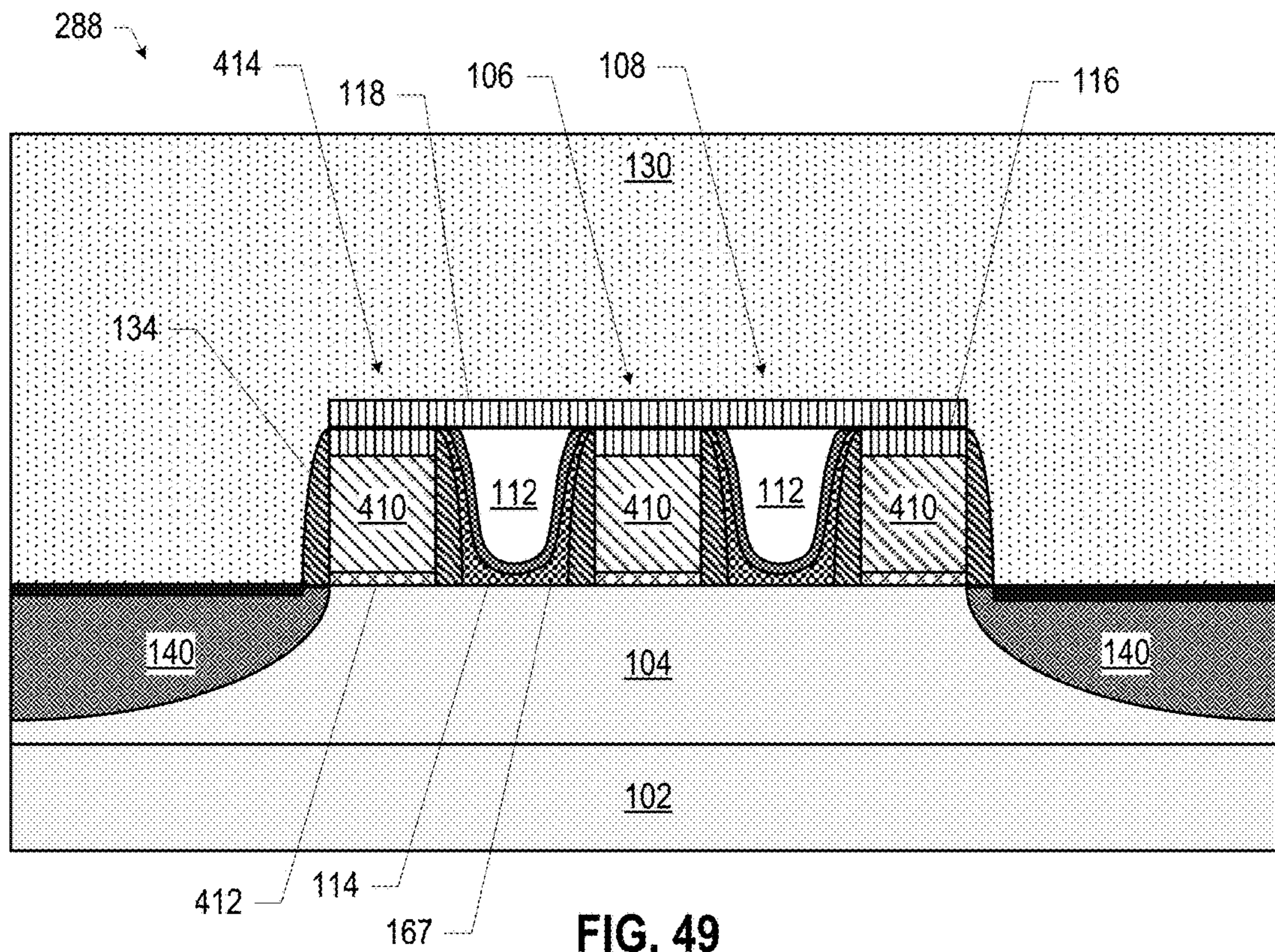


FIG. 49



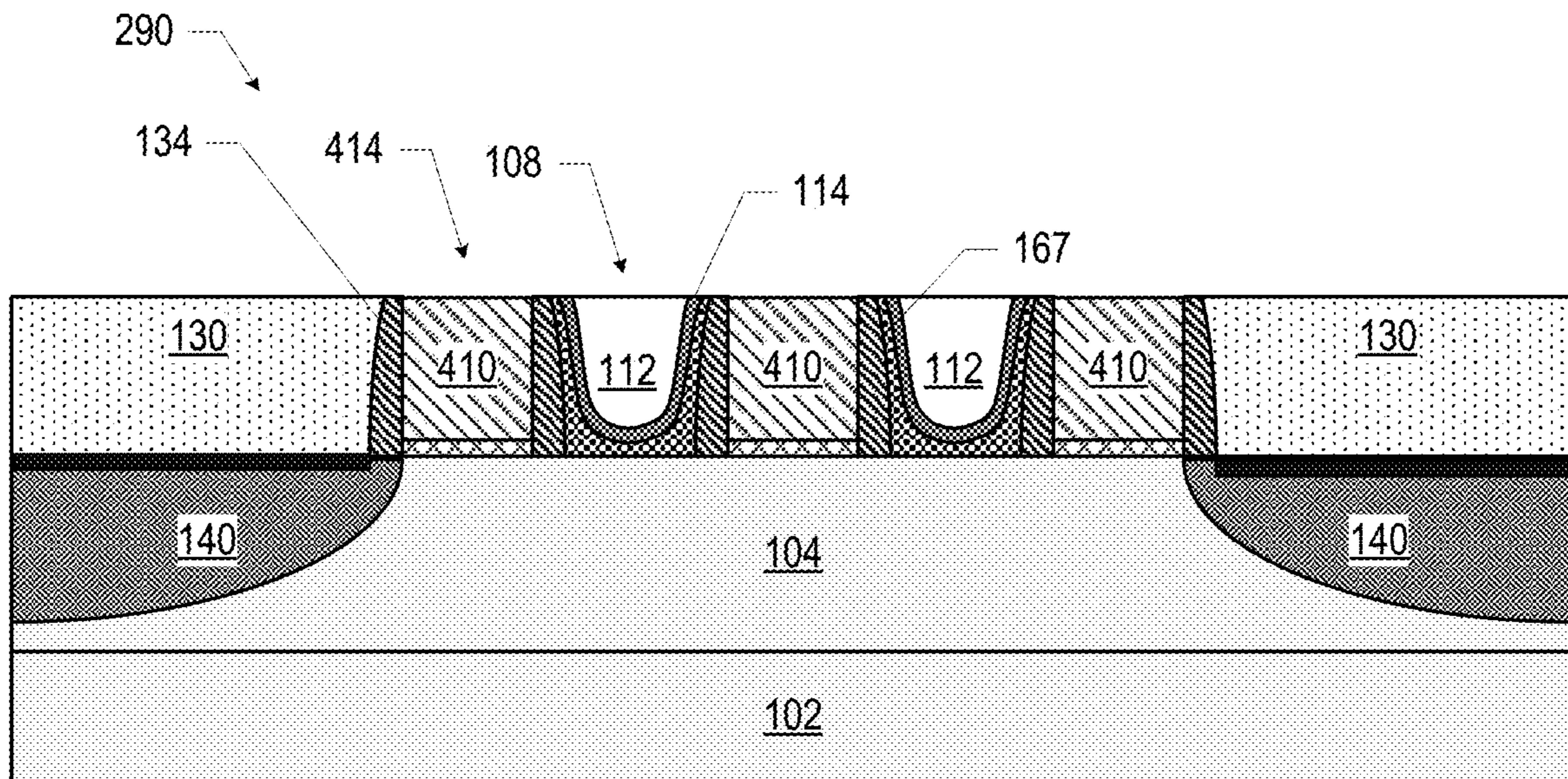


FIG. 50

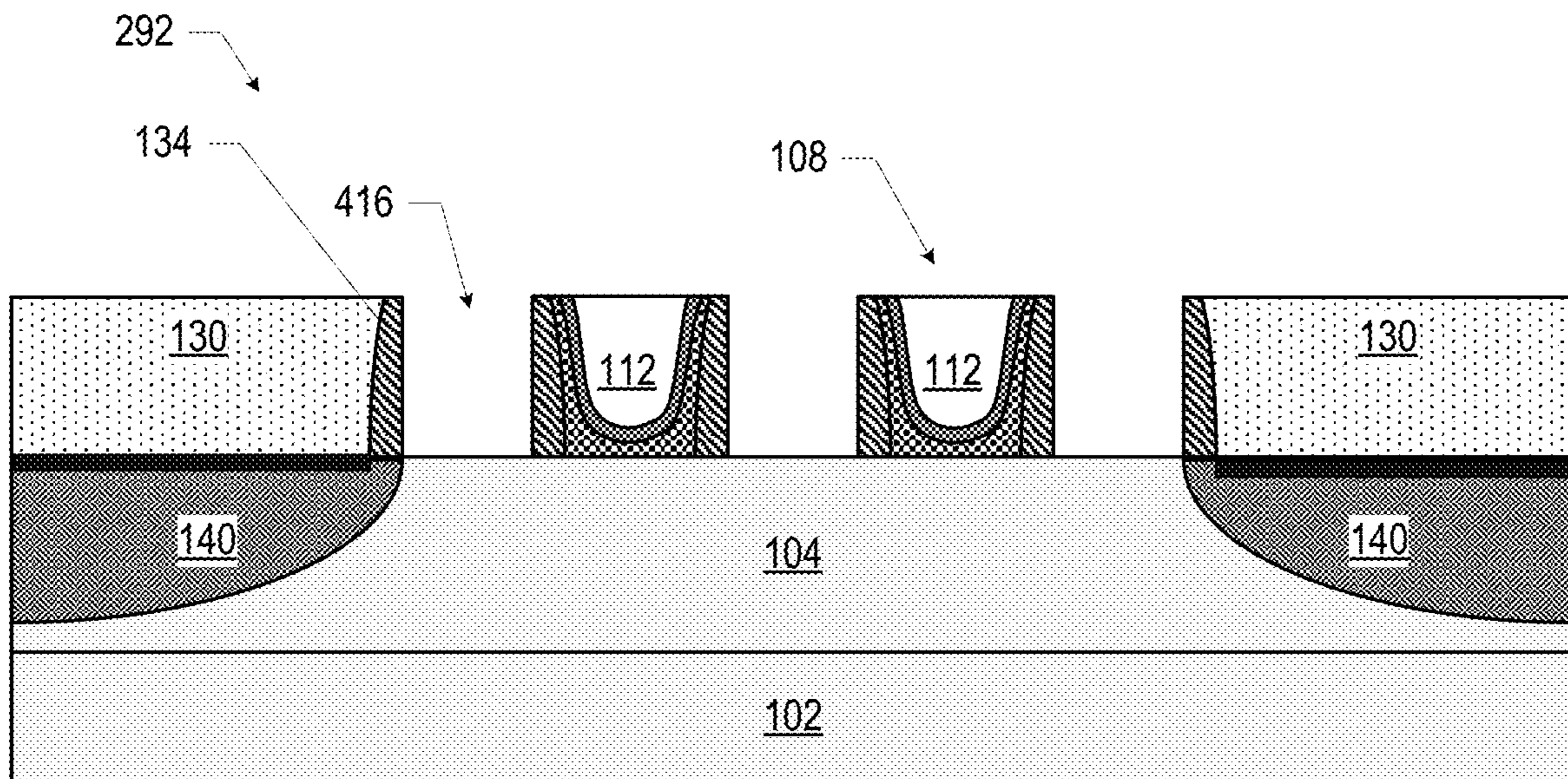


FIG. 51



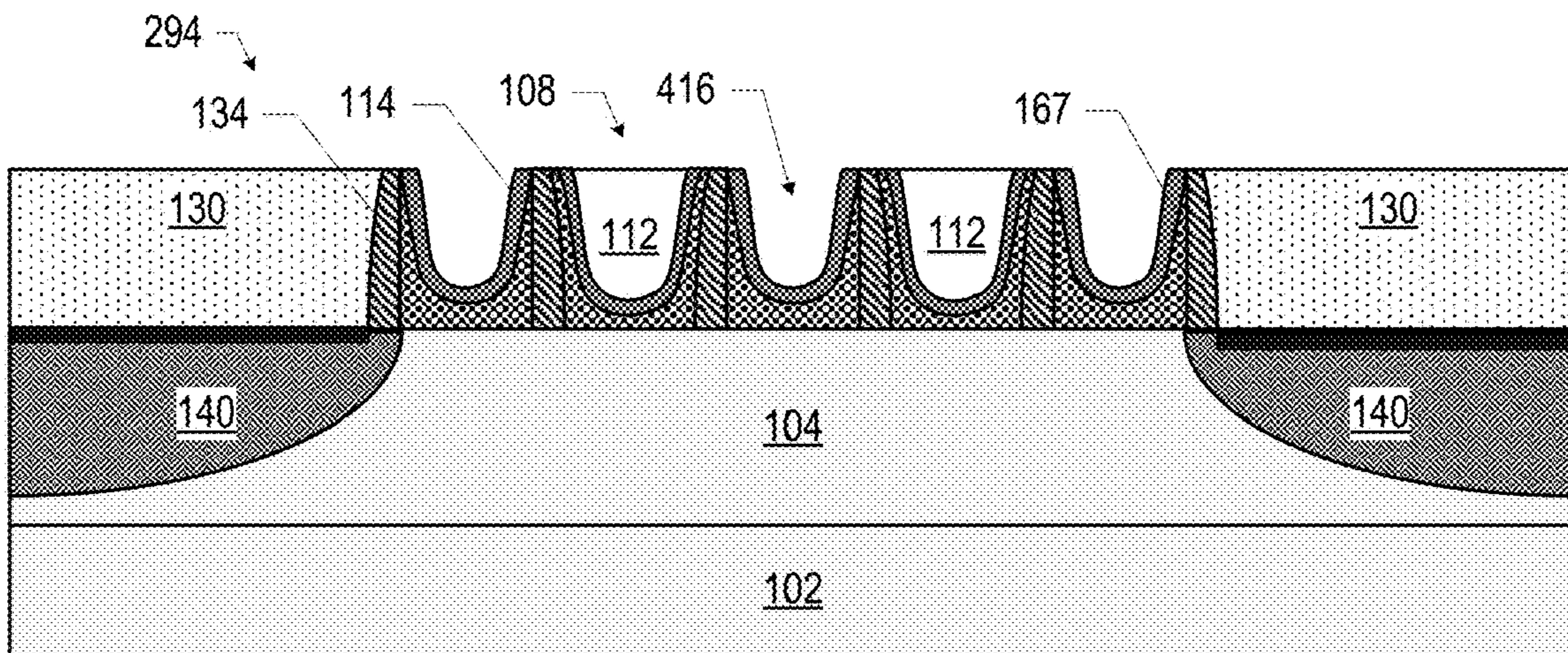


FIG. 52

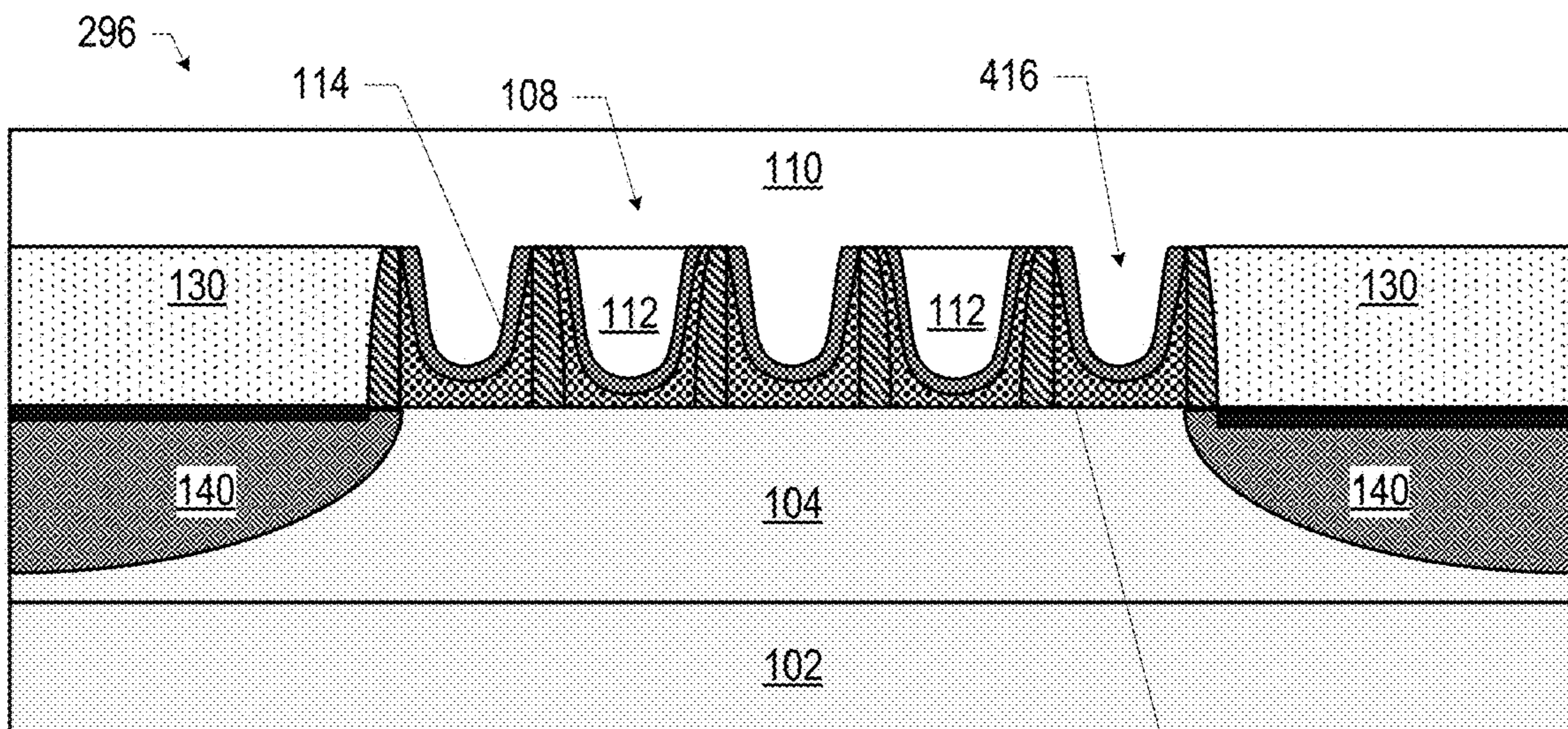


FIG. 53

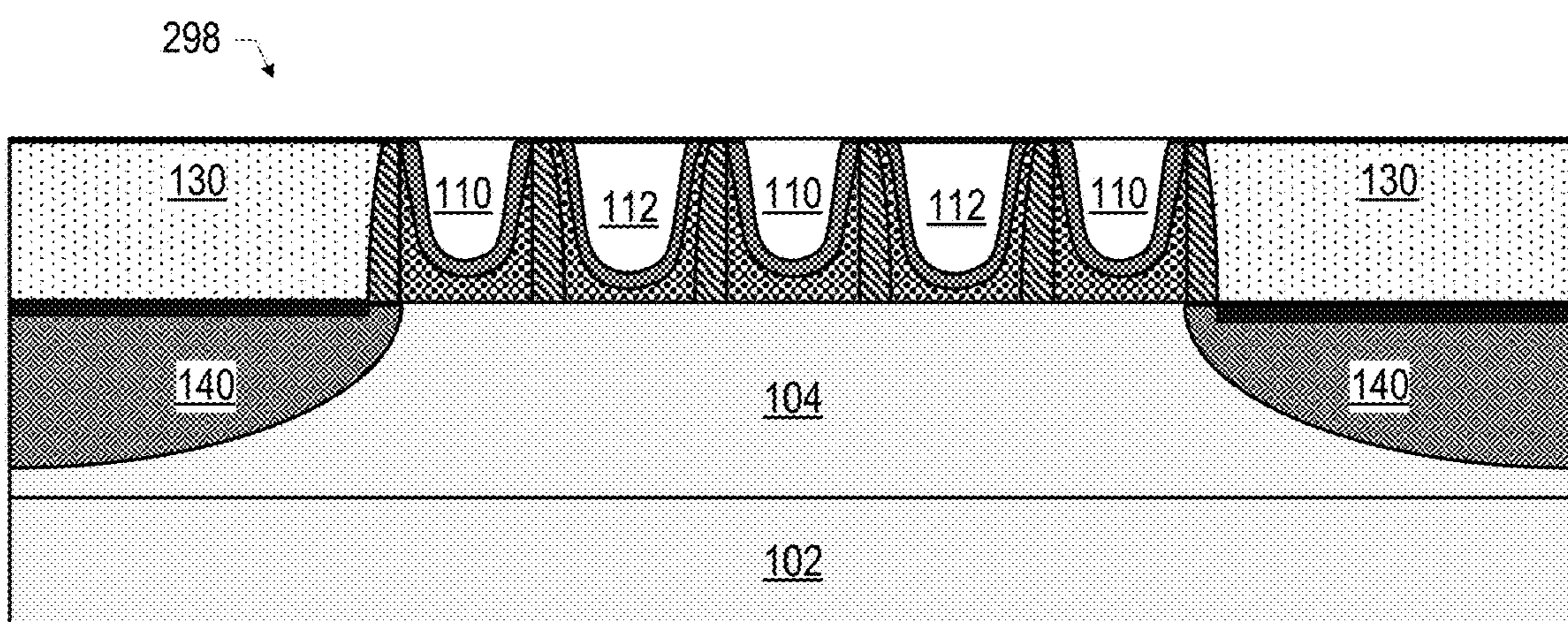


FIG. 54



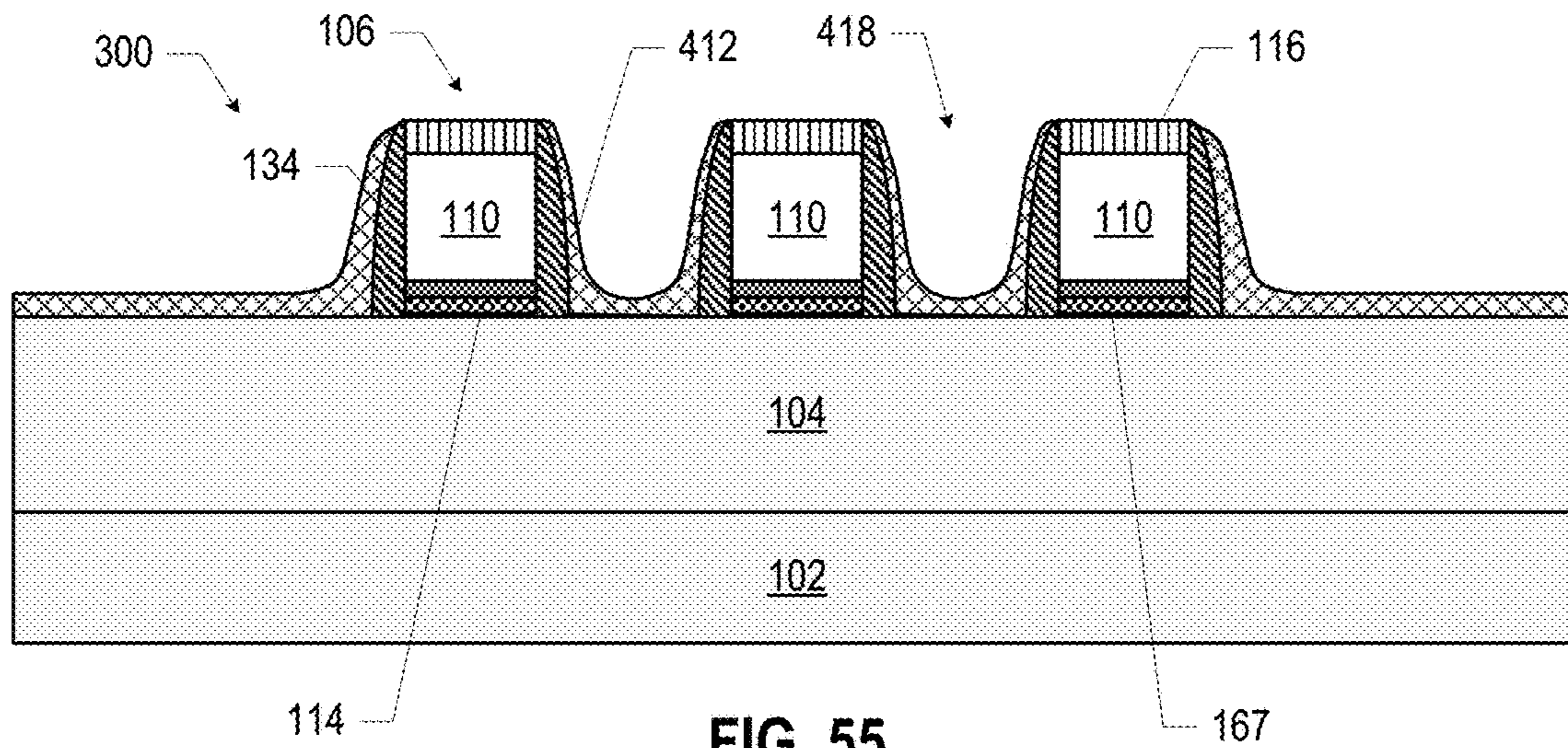


FIG. 55

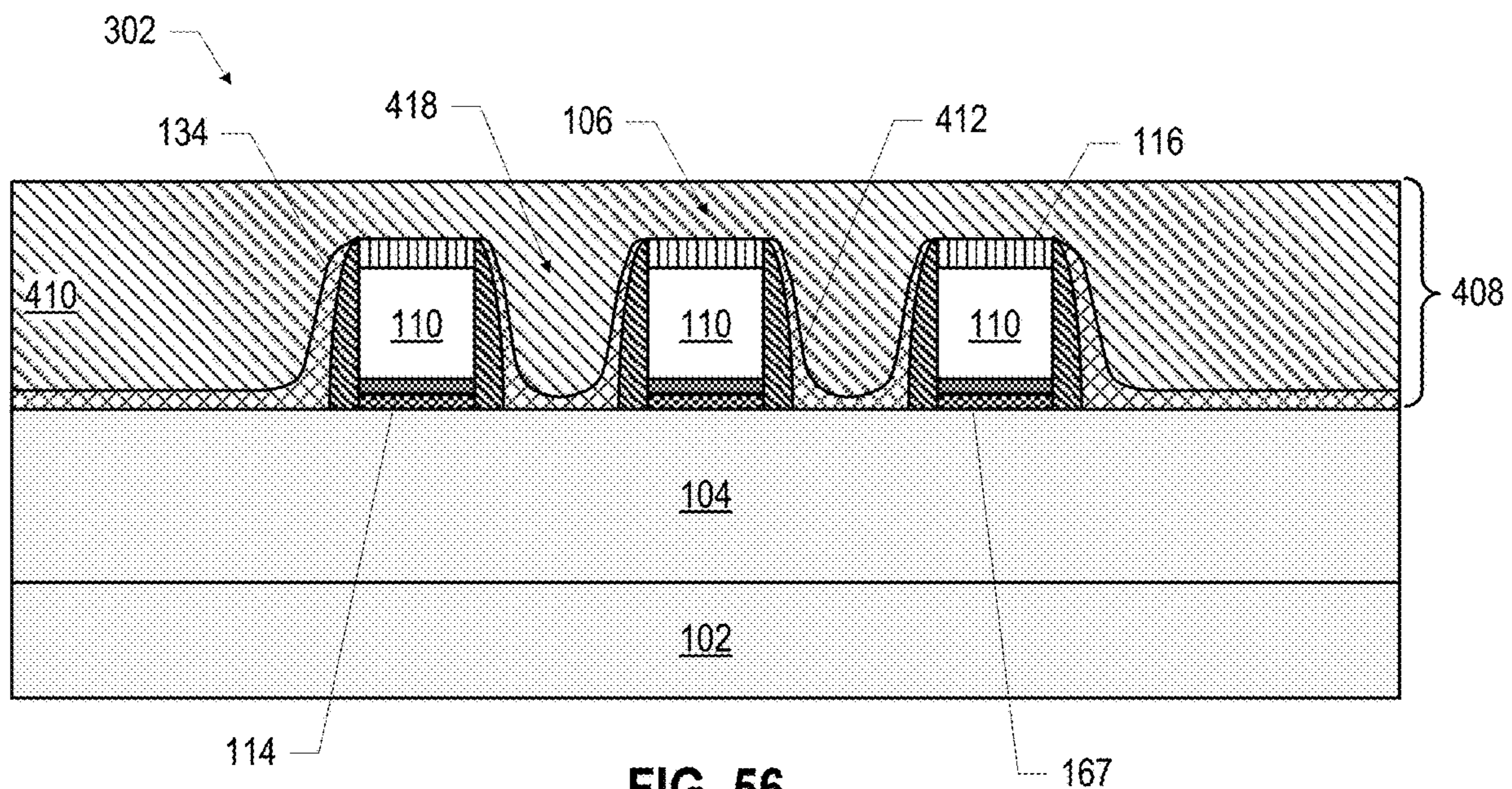


FIG. 56



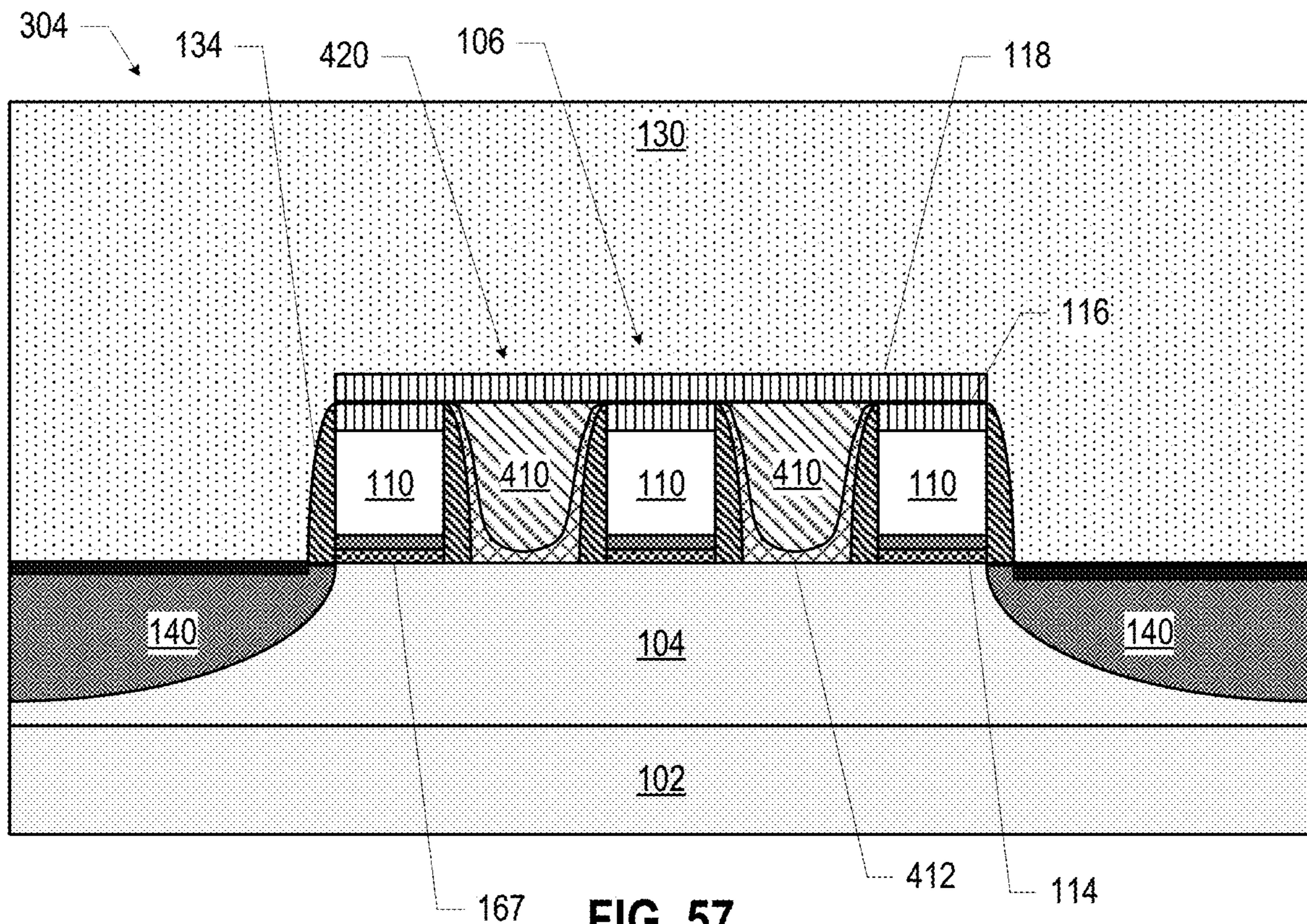


FIG. 57

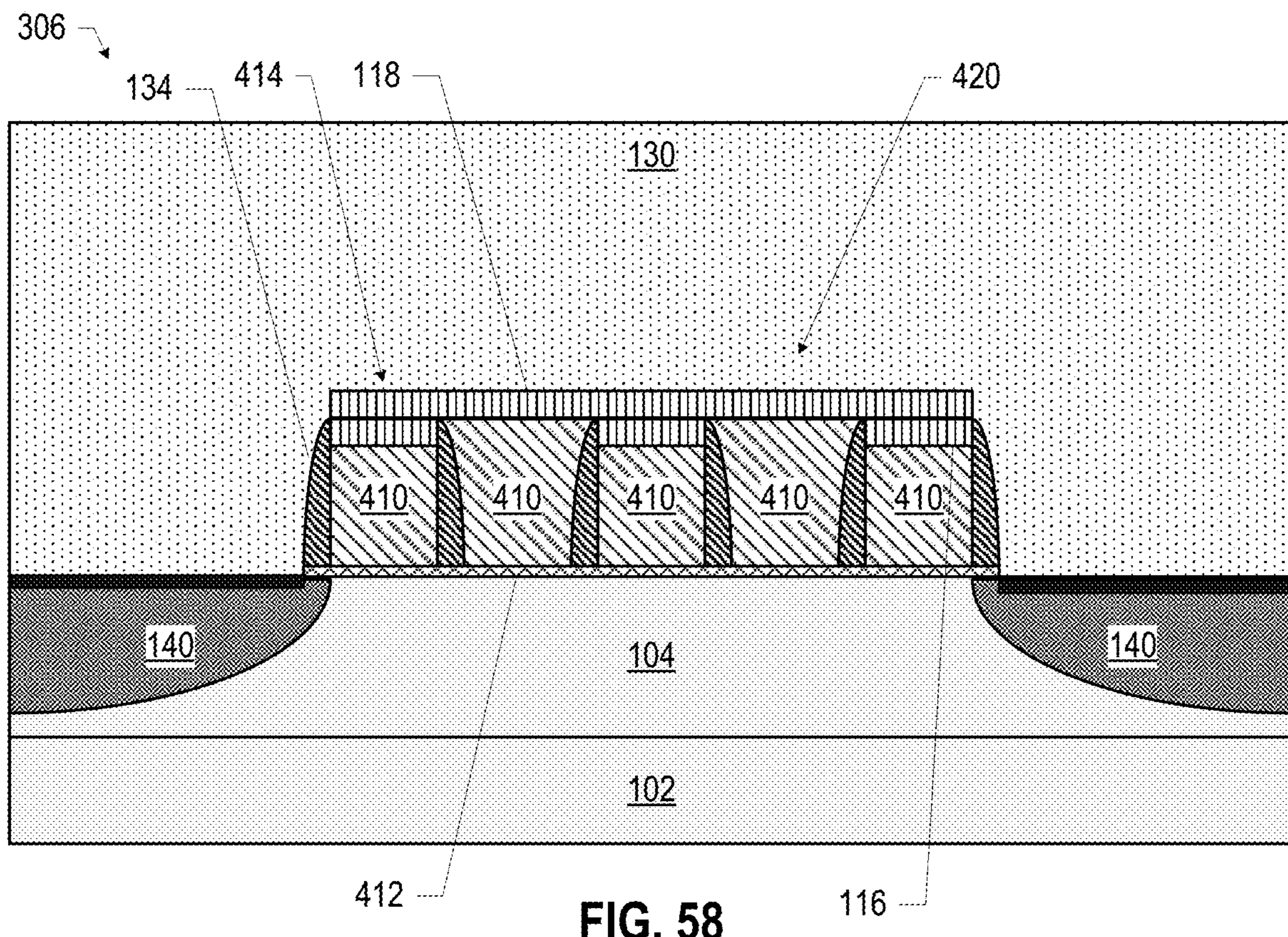
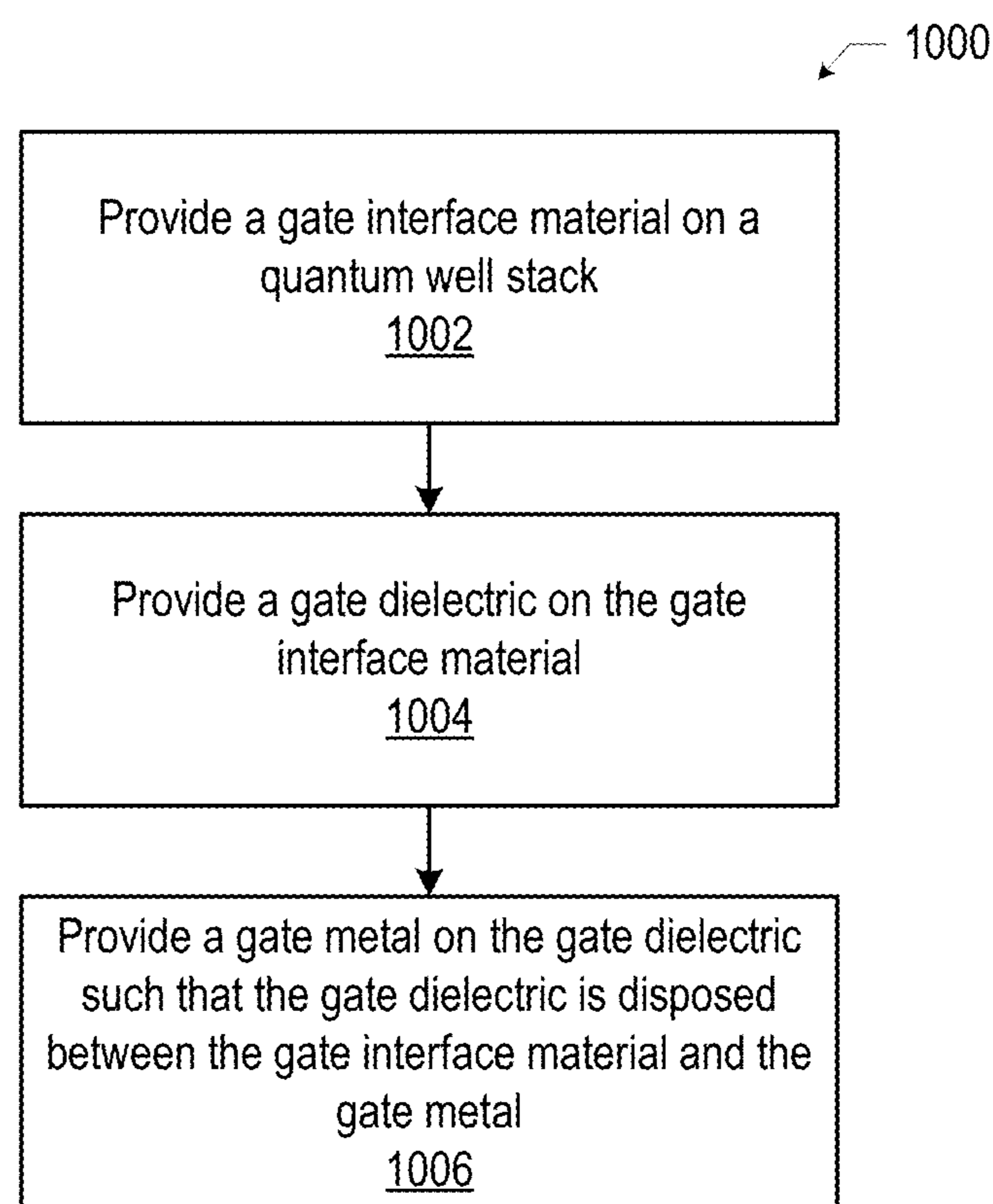
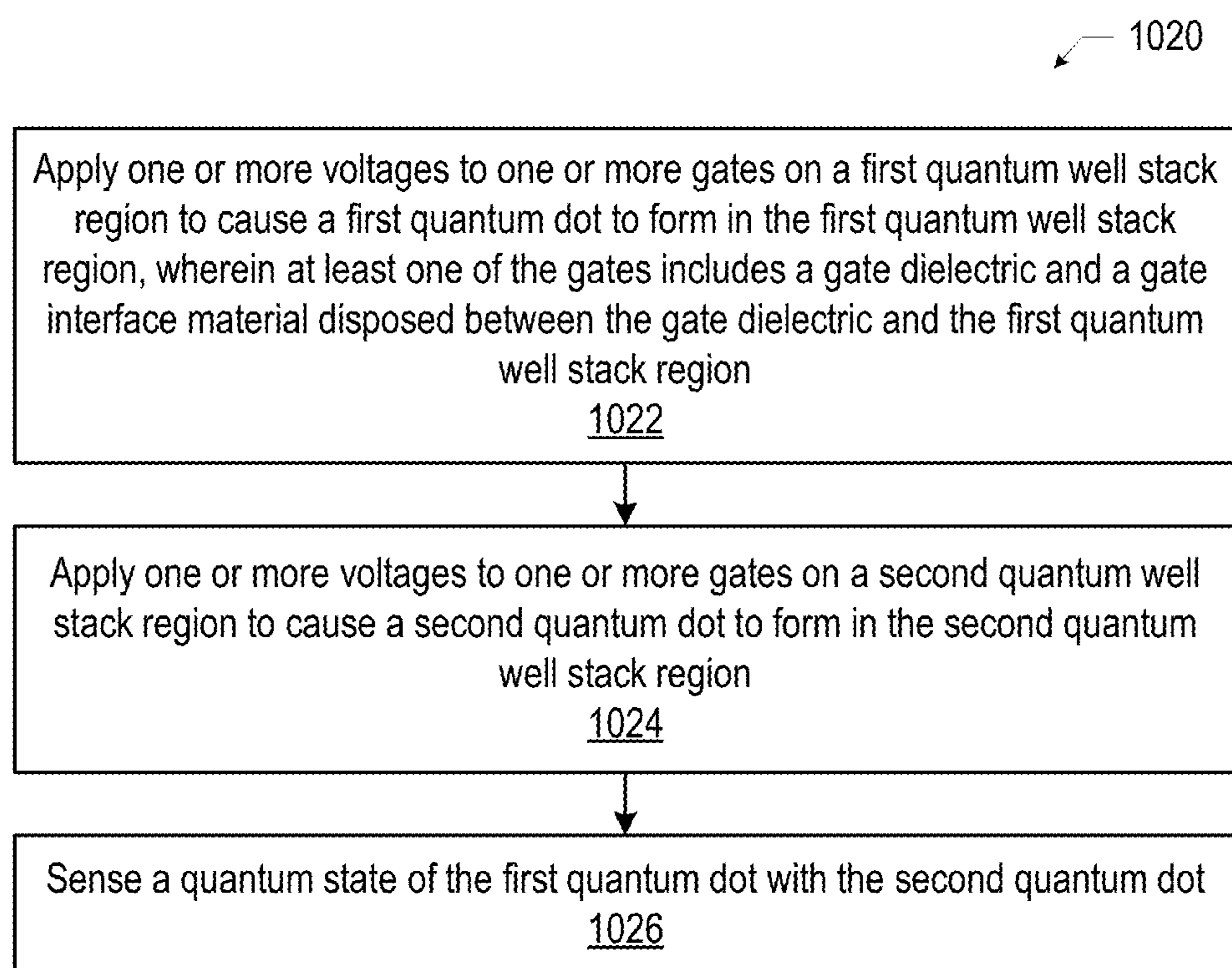


FIG. 58



**FIG. 59****FIG. 60**



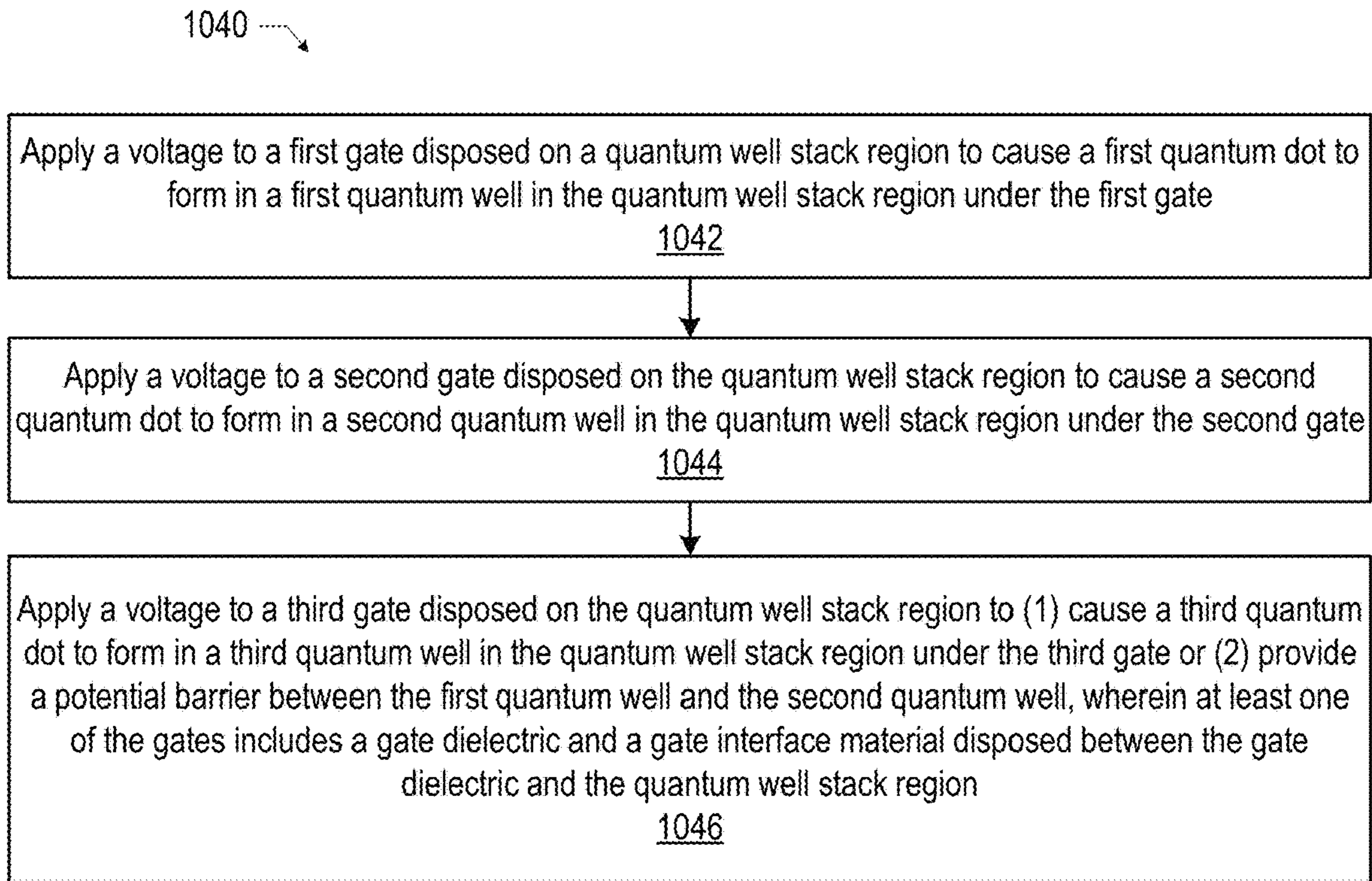


FIG. 61

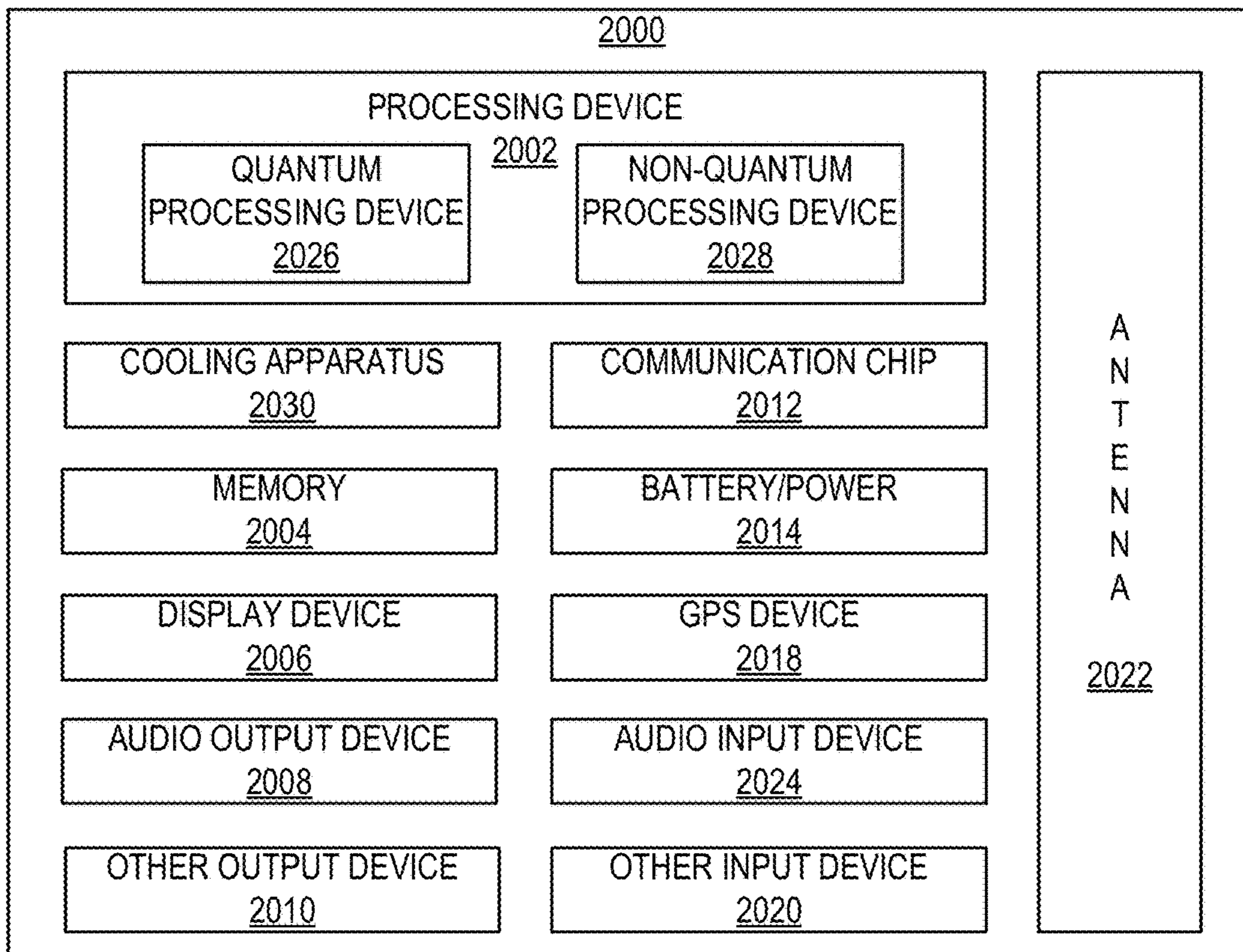


FIG. 62



## QUANTUM DOT DEVICES WITH GATE INTERFACE MATERIALS

### CROSS-REFERENCE TO RELATED APPLICATION

This application is a national stage application under 35 U.S.C. § 371 of PCT International Application Serial No. PCT/US2016/036829, filed on Jun. 10, 2016 and entitled “QUANTUM DOT DEVICES WITH GATE INTERFACE MATERIALS,” which is hereby incorporated herein by reference in its entirety.

### BACKGROUND

Quantum computing refers to the field of research related to computation systems that use quantum mechanical phenomena to manipulate data. These quantum mechanical phenomena, such as superposition (in which a quantum variable can simultaneously exist in multiple different states) and entanglement (in which multiple quantum variables have related states irrespective of the distance between them in space or time), do not have analogs in the world of classical computing, and thus cannot be implemented with classical computing devices.

### BRIEF DESCRIPTION OF THE DRAWINGS

Embodiments will be readily understood by the following detailed description in conjunction with the accompanying drawings. To facilitate this description, like reference numerals designate like structural elements. Embodiments are illustrated by way of example, and not by way of limitation, in the figures of the accompanying drawings.

FIGS. 1-3 are cross-sectional views of a quantum dot device, in accordance with various embodiments.

FIGS. 4-25 illustrate various example stages in the manufacture of a quantum dot device, in accordance with various embodiments.

FIGS. 26-28 are cross-sectional views of various examples of quantum well stacks that may be used in a quantum dot device, in accordance with various embodiments.

FIGS. 29-35 illustrate example base/fin arrangements that may be used in a quantum dot device, in accordance with various embodiments.

FIGS. 36-38 illustrate various example stages in the manufacture of alternative gate arrangements that may be included in a quantum dot device, in accordance with various embodiments.

FIG. 39 illustrates an embodiment of a quantum dot device having multiple groups of gates on a single fin, in accordance with various embodiments.

FIGS. 40-44 illustrate various alternative stages in the manufacture of a quantum dot device, in accordance with various embodiments.

FIG. 45 illustrates an example alternative stage in the manufacture of a quantum dot device, in accordance with various embodiments.

FIGS. 46-47 illustrate detail views of various embodiments of a doped region in a quantum dot device.

FIGS. 48-58 illustrate various example stages in the manufacture of a quantum dot device using replacement gate techniques, in accordance with various embodiments.

FIG. 59 is a flow diagram of an illustrative method of manufacturing a quantum dot device, in accordance with various embodiments.

FIGS. 60-61 are flow diagrams of illustrative methods of operating a quantum dot device, in accordance with various embodiments.

FIG. 62 is a block diagram of an example quantum computing device that may include any of the quantum dot devices disclosed herein, in accordance with various embodiments.

### DETAILED DESCRIPTION

Disclosed herein are quantum dot devices with cap layers, as well as related computing devices and methods. For example, a quantum dot device may include a quantum well stack, a gate interface material, and a high-k gate dielectric. The gate interface material may be disposed between the high-k gate dielectric and the quantum well stack.

The quantum dot devices disclosed herein may enable the formation of quantum dots to serve as quantum bits (“qubits”) in a quantum computing device, as well as the control of these quantum dots to perform quantum logic operations. Unlike previous approaches to quantum dot formation and manipulation, various embodiments of the quantum dot devices disclosed herein provide strong spatial localization of the quantum dots (and therefore good control over quantum dot interactions and manipulation), good scalability in the number of quantum dots included in the device, and/or design flexibility in making electrical connections to the quantum dot devices to integrate the quantum dot devices in larger computing devices.

In the following detailed description, reference is made to the accompanying drawings that form a part hereof, and in which is shown, by way of illustration, embodiments that may be practiced. It is to be understood that other embodiments may be utilized and structural or logical changes may be made without departing from the scope of the present disclosure. Therefore, the following detailed description is not to be taken in a limiting sense.

Various operations may be described as multiple discrete actions or operations in turn in a manner that is most helpful in understanding the claimed subject matter. However, the order of description should not be construed as to imply that these operations are necessarily order dependent. In particular, these operations may not be performed in the order of presentation. Operations described may be performed in a different order from the described embodiment. Various additional operations may be performed, and/or described operations may be omitted in additional embodiments.

For the purposes of the present disclosure, the phrase “A and/or B” means (A), (B), or (A and B). For the purposes of the present disclosure, the phrase “A, B, and/or C” means (A), (B), (C), (A and B), (A and C), (B and C), or (A, B, and C). The term “between,” when used with reference to measurement ranges, is inclusive of the ends of the measurement ranges. As used herein, the notation “A/B/C” means (A), (B), and/or (C).

The description uses the phrases “in an embodiment” or “in embodiments,” which may each refer to one or more of the same or different embodiments. Furthermore, the terms “comprising,” “including,” “having,” and the like, as used with respect to embodiments of the present disclosure, are synonymous. The disclosure may use perspective-based descriptions such as “above,” “below,” “top,” “bottom,” and “side”; such descriptions are used to facilitate the discussion and are not intended to restrict the application of disclosed embodiments. The accompanying drawings are not neces-



sarily drawn to scale. As used herein, a “high-k dielectric” refers to a material having a higher dielectric constant than silicon oxide.

FIGS. 1-3 are cross-sectional views of a quantum dot device 100, in accordance with various embodiments. In particular, FIG. 2 illustrates the quantum dot device 100 taken along the section A-A of FIG. 1 (while FIG. 1 illustrates the quantum dot device 100 taken along the section C-C of FIG. 2), and FIG. 3 illustrates the quantum dot device 100 taken along the section B-B of FIG. 1 with a number of components not shown to more readily illustrate how the gates 106/108 may be patterned (while FIG. 1 illustrates a quantum dot device 100 taken along the section D-D of FIG. 3). Although FIG. 1 indicates that the cross-section illustrated in FIG. 2 is taken through the fin 104-1, an analogous cross section taken through the fin 104-2 may be identical, and thus the discussion of FIG. 2 refers generally to the “fin 104.”

The quantum dot device 100 may include a base 102 and multiple fins 104 extending away from the base 102. The base 102 and the fins 104 may include a substrate and a quantum well stack (not shown in FIGS. 1-3, but discussed below with reference to the substrate 144 and the quantum well stack 146), distributed in any of a number of ways between the base 102 and the fins 104. The base 102 may include at least some of the substrate, and the fins 104 may each include a quantum well layer of the quantum well stack (discussed below with reference to the quantum well layer 152). Examples of base/fin arrangements are discussed below with reference to the base fin arrangements 158 of FIGS. 29-35.

Although only two fins, 104-1 and 104-2, are shown in FIGS. 1-3, this is simply for ease of illustration, and more than two fins 104 may be included in the quantum dot device 100. In some embodiments, the total number of fins 104 included in the quantum dot device 100 is an even number, with the fins 104 organized into pairs including one active fin 104 and one read fin 104, as discussed in detail below. When the quantum dot device 100 includes more than two fins 104, the fins 104 may be arranged in pairs in a line (e.g., 2N fins total may be arranged in a 1×2N line, or a 2×N line) or in pairs in a larger array (e.g., 2N fins total may be arranged as a 4×N/2 array, a 6×N/3 array, etc.). The discussion herein will largely focus on a single pair of fins 104 for ease of illustration, but all the teachings of the present disclosure apply to quantum dot devices 100 with more fins 104.

As noted above, each of the fins 104 may include a quantum well layer (not shown in FIGS. 1-3, but discussed below with reference to the quantum well layer 152). The quantum well layer included in the fins 104 may be arranged normal to the z-direction, and may provide a layer in which a two-dimensional electron gas (2DEG) may form to enable the generation of a quantum dot during operation of the quantum dot device 100, as discussed in further detail below. The quantum well layer itself may provide a geometric constraint on the z-location of quantum dots in the fins 104, and the limited extent of the fins 104 (and therefore the quantum well layer) in the y-direction may provide a geometric constraint on the y-location of quantum dots in the fins 104. To control the x-location of quantum dots in the fins 104, voltages may be applied to gates disposed on the fins 104 to adjust the energy profile along the fins 104 in the x-direction and thereby constrain the x-location of quantum dots within quantum wells (discussed in detail below with reference to the gates 106/108). The dimensions of the fins 104 may take any suitable values. For example, in some

embodiments, the fins 104 may each have a width 162 between 10 and 30 nanometers. In some embodiments, the fins 104 may each have a height 164 between 200 and 400 nanometers (e.g., between 250 and 350 nanometers, or equal to 300 nanometers).

The fins 104 may be arranged in parallel, as illustrated in FIGS. 1 and 3, and may be spaced apart by an insulating material 128, which may be disposed on opposite faces of the fins 104. The insulating material 128 may be a dielectric material, such as silicon oxide. For example, in some embodiments, the fins 104 may be spaced apart by a distance 160 between 100 and 250 microns.

Multiple gates may be disposed on each of the fins 104. In the embodiment illustrated in FIG. 2, three gates 106 and two gates 108 are shown as distributed on the top of the fin 104. This particular number of gates is simply illustrative, and any suitable number of gates may be used. Additionally, as discussed below with reference to FIG. 39, multiple groups of gates (like the gates illustrated in FIG. 2) may be disposed on the fin 104.

As shown in FIG. 2, the gate 108-1 may be disposed between the gates 106-1 and 106-2, and the gate 108-2 may be disposed between the gates 106-2 and 106-3. Each of the gates 106/108 may include a gate interface material 167 and a gate dielectric 114; in the embodiment illustrated in FIG. 2, the gate interface material 167 and the gate dielectric 114 for all of the gates 106/108 are provided by a common layer of gate interface material and gate dielectric material, respectively. In other embodiments, the gate interface material 167 and the gate dielectric 114 for each of the gates 106/108 may be provided by separate portions of the gate interface material 167 and the gate dielectric 114, respectively (e.g., as discussed below with reference to FIGS. 40-44).

In some embodiments, the gate dielectric 114 may be a multilayer gate dielectric (e.g., with multiple materials used to improve the interface between the fin 104 and the corresponding gate metal). The gate dielectric 114 may be, for example, silicon oxide, aluminum oxide, or a high-k dielectric, such as hafnium oxide. More generally, the gate dielectric 114 may include elements such as hafnium, silicon, oxygen, titanium, tantalum, lanthanum, aluminum, zirconium, barium, strontium, yttrium, lead, scandium, niobium, and zinc. Examples of materials that may be used in the gate dielectric 114 may include, but are not limited to, hafnium oxide, hafnium silicon oxide, lanthanum oxide, lanthanum aluminum oxide, zirconium oxide, zirconium silicon oxide, tantalum oxide, titanium oxide, barium strontium titanium oxide, barium titanium oxide, strontium titanium oxide, yttrium oxide, aluminum oxide, tantalum oxide, tantalum silicon oxide, lead scandium tantalum oxide, and lead zinc niobate. In some embodiments, an annealing process may be carried out on the gate dielectric 114 to improve the quality of the gate dielectric 114.

The gate interface material 167 may provide an interface between the quantum well stack (discussed below with reference to the quantum well stacks 146) and the gate dielectric 114, and in particular, the gate interface material 167 may provide an interface between the quantum well stack and the gate dielectric 114 that has a low total interface trap density ( $D_{it}$ ), reducing the likelihood of scattering that may impede the coherence of the quantum dots 142 formed in the quantum dot device 100. The inclusion of the gate interface material 167 may thus improve performance relative to embodiments in which the gate interface material 167 is not included.



The gate interface material **167** may include any suitable material to improve the  $D_{it}$  of the gates **106/108** on the quantum well stack. In some embodiments, the gate interface material **167** may include silicon. Silicon may be a particularly useful material for the gate interface material **167** when the quantum well stack includes silicon germanium, and the gate interface material **167** is disposed on the silicon germanium. In some embodiments in which the gate interface material **167** includes silicon, the silicon may oxidize (e.g., due to air exposure before the gate dielectric **114** is formed) to form a layer of silicon oxide at the interface between the silicon of the gate interface material **167** and the gate dielectric **114**. In some embodiments, the gate interface material **167** may include aluminum nitride, aluminum oxynitride, or germanium oxide. In embodiments in which the gate interface material **167** includes germanium oxide, the gate interface material **167** may be formed by forming a layer of germanium, then allowing the layer of germanium to oxidize.

In some embodiments, the gate interface material **167** may be a thin layer grown by epitaxy on a quantum well stack. For example, in embodiments in which the quantum well stack includes a silicon germanium barrier between a quantum well layer and the gate **106/108** (e.g., as discussed below with reference to FIG. **28**), the gate interface material **167** (e.g., silicon) may be grown directly on the silicon germanium barrier. In some embodiments, the gate dielectric **114** (e.g., hafnium oxide) may be grown on top of the gate interface material **167**. The interface between the gate interface material **167** and the gate dielectric **114** may have fewer electrical defects than if the gate dielectric **114** were formed directly on the quantum well stack.

Each of the gates **106** may include a gate metal **110** and a hardmask **116**. The hardmask **116** may be formed of silicon nitride, silicon carbide, or another suitable material. The gate metal **110** may be disposed between the hardmask **116** and the gate dielectric **114**, and the gate dielectric **114** may be disposed between the gate metal **110** and the fin **104**. Only one portion of the hardmask **116** is labeled in FIG. **2** for ease of illustration. In some embodiments, the gate metal **110** may be a superconductor, such as aluminum, titanium nitride (e.g., deposited via atomic layer deposition), or niobium titanium nitride. In some embodiments, the hardmask **116** may not be present in the quantum dot device **100** (e.g., a hardmask like the hardmask **116** may be removed during processing, as discussed below). An example of embodiments in which the hardmask **116** is not present in the “final” quantum dot device **100** is discussed below with reference to FIGS. **48-58**). The sides of the gate metal **110** may be substantially parallel, as shown in FIG. **2**, and insulating spacers **134** may be disposed on the sides of the gate metal **110** and the hardmask **116**. As illustrated in FIG. **2**, the spacers **134** may be thicker closer to the fin **104** and thinner farther away from the fin **104**. In some embodiments, the spacers **134** may have a convex shape. The spacers **134** may be formed of any suitable material, such as a carbon-doped oxide, silicon nitride, silicon oxide, or other carbides or nitrides (e.g., silicon carbide, silicon nitride doped with carbon, and silicon oxynitride). The gate metal **110** may be any suitable metal, such as titanium nitride.

Each of the gates **108** may include a gate metal **112** and a hardmask **118**. The hardmask **118** may be formed of silicon nitride, silicon carbide, or another suitable material. The gate metal **112** may be disposed between the hardmask **118** and the gate dielectric **114**, and the gate dielectric **114** may be disposed between the gate metal **112** and the fin **104**. In the embodiment illustrated in FIG. **2**, the hardmask **118** may

extend over the hardmask **116** (and over the gate metal **110** of the gates **106**), while in other embodiments, the hardmask **118** may not extend over the gate metal **110** (e.g., as discussed below with reference to FIG. **45**). In some embodiments, the gate metal **112** may be a different metal from the gate metal **110**; in other embodiments, the gate metal **112** and the gate metal **110** may have the same material composition. In some embodiments, the gate metal **112** may be a superconductor, such as aluminum, titanium nitride (e.g., deposited via atomic layer deposition), or niobium titanium nitride. In some embodiments, the hardmask **118** may not be present in the quantum dot device **100** (e.g., a hardmask like the hardmask **118** may be removed during processing, as discussed below). An example of embodiments in which the hardmask **118** is not present in the “final” quantum dot device **100** is discussed below with reference to FIGS. **48-58**).

The gate **108-1** may extend between the proximate spacers **134** on the sides of the gate **106-1** and the gate **106-2**, as shown in FIG. **2**. In some embodiments, the gate metal **112** of the gate **108-1** may extend between the spacers **134** on the sides of the gate **106-1** and the gate **106-2**. Thus, the gate metal **112** of the gate **108-1** may have a shape that is substantially complementary to the shape of the spacers **134**, as shown. Similarly, the gate **108-2** may extend between the proximate spacers **134** on the sides of the gate **106-2** and the gate **106-3**. In some embodiments in which the gate interface material **167** and/or the gate dielectric **114** is/are not layers shared commonly between the gates **108** and **106**, but instead is/are separately deposited on the fin **104** between the spacers **134** (e.g., as discussed below with reference to FIGS. **40-44**), the gate interface material **167** and/or the gate dielectric **114** may extend at least partially up the sides of the spacers **134**, and the gate metal **112** may extend between the portions of gate dielectric **114** on the spacers **134**. The gate metal **112**, like the gate metal **110**, may be any suitable metal, such as titanium nitride.

The dimensions of the gates **106/108** may take any suitable values. For example, in some embodiments, the z-height **166** of the gate metal **110** may be between 40 and 75 nanometers (e.g., approximately 50 nanometers); the z-height of the gate metal **112** may be in the same range. In embodiments like the ones illustrated in FIGS. **2**, **38**, and **45**, the z-height of the gate metal **112** may be greater than the z-height of the gate metal **110**. In some embodiments, the length **168** of the gate metal **110** (i.e., in the x-direction) may be between 20 and 40 nanometers (e.g., 30 nanometers). In some embodiments, the distance **170** between adjacent ones of the gates **106** (e.g., as measured from the gate metal **110** of one gate **106** to the gate metal **110** of an adjacent gate **106** in the x-direction, as illustrated in FIG. **2**) may be between 40 and 60 nanometers (e.g., 50 nanometers). In some embodiments, the thickness **172** of the spacers **134** may be between 1 and 10 nanometers (e.g., between 3 and 5 nanometers, between 4 and 6 nanometers, or between 4 and 7 nanometers). The length of the gate metal **112** (i.e., in the x-direction) may depend on the dimensions of the gates **106** and the spacers **134**, as illustrated in FIG. **2**. As indicated in FIG. **1**, the gates **106/108** on one fin **104** may extend over the insulating material **128** beyond their respective fins **104** and towards the other fin **104**, but may be isolated from their counterpart gates by the intervening insulating material **130** and spacers **134**. The gate interface material **167** may have any suitable thickness (i.e., in the z-direction). For example, in some embodiments, the thickness of the gate interface material **167** may range between a monolayer and a few



nanometers thick (e.g., between a few angstroms and tens of angstroms, between 1 and 3 nanometers, or between 1 and 2 nanometers).

As shown in FIG. 2, the gates **106** and **108** may be alternatingly arranged along the fin **104** in the x-direction. During operation of the quantum dot device **100**, voltages may be applied to the gates **106/108** to adjust the potential energy in the quantum well layer (not shown) in the fin **104** to create quantum wells of varying depths in which quantum dots **142** may form. Only one quantum dot **142** is labeled with a reference numeral in FIGS. 2 and 3 for ease of illustration, but five are indicated as dotted circles in each fin **104**. The location of the quantum dots **142** in FIG. 2 is not intended to indicate a particular geometric positioning of the quantum dots **142**. The spacers **134** may themselves provide “passive” barriers between quantum wells under the gates **106/108** in the quantum well layer, and the voltages applied to different ones of the gates **106/108** may adjust the potential energy under the gates **106/108** in the quantum well layer; decreasing the potential energy may form quantum wells, while increasing the potential energy may form quantum barriers.

The fins **104** may include doped regions **140** that may serve as a reservoir of charge carriers for the quantum dot device **100**. For example, an n-type doped region **140** may supply electrons for electron-type quantum dots **142**, and a p-type doped region **140** may supply holes for hole-type quantum dots **142**. In some embodiments, a doped region interface material **141** may be disposed at a surface of a doped region **140**, as shown. The doped region interface material **141** may facilitate electrical coupling between a conductive contact (e.g., a conductive via **136**, as discussed below) and the doped region **140**. The doped region interface material **141** may be any suitable metal-semiconductor ohmic contact material; for example, in embodiments in which the doped region **140** includes silicon, the doped region interface material **141** may include nickel silicide, aluminum silicide, titanium silicide, molybdenum silicide, cobalt silicide, tungsten silicide, or platinum silicide (e.g., as discussed below with reference to FIGS. 22-23). In some embodiments, the doped region interface material **141** may be a non-silicide compound, such as titanium nitride. In some embodiments, the doped region interface material **141** may be a metal (e.g., aluminum, tungsten, or indium).

The quantum dot devices **100** disclosed herein may be used to form electron-type or hole-type quantum dots **142**. Note that the polarity of the voltages applied to the gates **106/108** to form quantum wells/barriers depend on the charge carriers used in the quantum dot device **100**. In embodiments in which the charge carriers are electrons (and thus the quantum dots **142** are electron-type quantum dots), apply negative voltages applied to a gate **106/108** may increase the potential barrier under the gate **106/108**, and apply positive voltages applied to a gate **106/108** may decrease the potential barrier under the gate **106/108** (thereby forming a potential well in which an electron-type quantum dot **142** may form). In embodiments in which the charge carriers are holes (and thus the quantum dots **142** are hole-type quantum dots), apply positive voltages applied to a gate **106/108** may increase the potential barrier under the gate **106/108**, and apply negative voltages applied to a gate **106** and **108** may decrease the potential barrier under the gate **106/108** (thereby forming a potential well in which a hole-type quantum dot **142** may form). The quantum dot devices **100** disclosed herein may be used to form electron-type or hole-type quantum dots.

Voltages may be applied to each of the gates **106** and **108** separately to adjust the potential energy in the quantum well layer under the gates **106** and **108**, and thereby control the formation of quantum dots **142** under each of the gates **106** and **108**. Additionally, the relative potential energy profiles under different ones of the gates **106** and **108** allow the quantum dot device **100** to tune the potential interaction between quantum dots **142** under adjacent gates. For example, if two adjacent quantum dots **142** (e.g., one quantum dot **142** under a gate **106** and another quantum dot **142** under a gate **108**) are separated by only a short potential barrier, the two quantum dots **142** may interact more strongly than if they were separated by a taller potential barrier. Since the depth of the potential wells/height of the potential barriers under each gate **106/108** may be adjusted by adjusting the voltages on the respective gates **106/108**, the differences in potential between adjacent gates **106/108** may be adjusted, and thus the interaction tuned.

In some applications, the gates **108** may be used as plunger gates to enable the formation of quantum dots **142** under the gates **108**, while the gates **106** may be used as barrier gates to adjust the potential barrier between quantum dots **142** formed under adjacent gates **108**. In other applications, the gates **108** may be used as barrier gates, while the gates **106** are used as plunger gates. In other applications, quantum dots **142** may be formed under all of the gates **106** and **108**, or under any desired subset of the gates **106** and **108**.

Conductive vias and lines may make contact with the gates **106/108**, and to the doped regions **140**, to enable electrical connection to the gates **106/108** and the doped regions **140** to be made in desired locations. As shown in FIGS. 1-3, the gates **106** may extend away from the fins **104**, and conductive vias **120** may contact the gates **106** (and are drawn in dashed lines in FIG. 2 to indicate their location behind the plane of the drawing). The conductive vias **120** may extend through the hardmask **116** and the hardmask **118** to contact the gate metal **110** of the gates **106**. The gates **108** may extend away from the fins **104**, and conductive vias **122** may contact the gates **108** (also drawn in dashed lines in FIG. 2 to indicate their location behind the plane of the drawing). The conductive vias **122** may extend through the hardmask **118** to contact the gate metal **112** of the gates **108**. Conductive vias **136** may contact the doped region interface material **141** and may thereby make electrical contact with the doped regions **140**. The quantum dot device **100** may include further conductive vias and/or lines (not shown) to make electrical contact to the gates **106/108** and/or the doped regions **140**, as desired. The conductive vias and lines included in a quantum dot device **100** may include any suitable materials, such as copper, tungsten (deposited, e.g., by CVD), or a superconductor (e.g., aluminum, tin, titanium nitride, niobium titanium nitride, tantalum, niobium, or other niobium compounds such as niobium tin and niobium germanium).

During operation, a bias voltage may be applied to the doped regions **140** (e.g., via the conductive vias **136** and the doped region interface material **141**) to cause current to flow through the doped regions **140**. When the doped regions **140** are doped with an n-type material, this voltage may be positive; when the doped regions **140** are doped with a p-type material, this voltage may be negative. The magnitude of this bias voltage may take any suitable value (e.g., between 0.25 volts and 2 volts).

The conductive vias **120**, **122**, and **136** may be electrically isolated from each other by an insulating material **130**. The insulating material **130** may be any suitable material, such as



an interlayer dielectric (ILD). Examples of the insulating material **130** may include silicon oxide, silicon nitride, aluminum oxide, carbon-doped oxide, and/or silicon oxynitride. As known in the art of integrated circuit manufacturing, conductive vias and lines may be formed in an iterative process in which layers of structures are formed on top of each other. In some embodiments, the conductive vias **120/122/136** may have a width that is 20 nanometers or greater at their widest point (e.g., 30 nanometers), and a pitch of 80 nanometers or greater (e.g., 100 nanometers). In some embodiments, conductive lines (not shown) included in the quantum dot device **100** may have a width that is 100 nanometers or greater, and a pitch of 100 nanometers or greater. The particular arrangement of conductive vias shown in FIGS. 1-3 is simply illustrative, and any electrical routing arrangement may be implemented.

As discussed above, the structure of the fin **104-1** may be the same as the structure of the fin **104-2**; similarly, the construction of gates **106/108** on the fin **104-1** may be the same as the construction of gates **106/108** on the fin **104-2**. The gates **106/108** on the fin **104-1** may be mirrored by corresponding gates **106/108** on the parallel fin **104-2**, and the insulating material **130** may separate the gates **106/108** on the different fins **104-1** and **104-2**. In particular, quantum dots **142** formed in the fin **104-1** (under the gates **106/108**) may have counterpart quantum dots **142** in the fin **104-2** (under the corresponding gates **106/108**). In some embodiments, the quantum dots **142** in the fin **104-1** may be used as “active” quantum dots in the sense that these quantum dots **142** act as qubits and are controlled (e.g., by voltages applied to the gates **106/108** of the fin **104-1**) to perform quantum computations. The quantum dots **142** in the fin **104-2** may be used as “read” quantum dots in the sense that these quantum dots **142** may sense the quantum state of the quantum dots **142** in the fin **104-1** by detecting the electric field generated by the charge in the quantum dots **142** in the fin **104-1**, and may convert the quantum state of the quantum dots **142** in the fin **104-1** into electrical signals that may be detected by the gates **106/108** on the fin **104-2**. Each quantum dot **142** in the fin **104-1** may be read by its corresponding quantum dot **142** in the fin **104-2**. Thus, the quantum dot device **100** enables both quantum computation and the ability to read the results of a quantum computation.

The quantum dot devices **100** disclosed herein may be manufactured using any suitable techniques. FIGS. 4-25 illustrate various example stages in the manufacture of the quantum dot device **100** of FIGS. 1-3, in accordance with various embodiments. Although the particular manufacturing operations discussed below with reference to FIGS. 4-25 are illustrated as manufacturing a particular embodiment of the quantum dot device **100**, these operations may be applied to manufacture many different embodiments of the quantum dot device **100**, as discussed herein. Any of the elements discussed below with reference to FIGS. 4-25 may take the form of any of the embodiments of those elements discussed above (or otherwise disclosed herein).

FIG. 4 illustrates a cross-sectional view of an assembly **200** including a substrate **144**. The substrate **144** may include any suitable semiconductor material or materials. In some embodiments, the substrate **144** may include a semiconductor material. For example, the substrate **144** may include silicon (e.g., may be formed from a silicon wafer).

FIG. 5 illustrates a cross-sectional view of an assembly **202** subsequent to providing a quantum well stack **146** on the substrate **144** of the assembly **200** (FIG. 4). The quantum well stack **146** may include a quantum well layer (not shown) in which a 2DEG may form during operation of the

quantum dot device **100**. Various embodiments of the quantum well stack **146** are discussed below with reference to FIGS. 26-28.

FIG. 6 illustrates a cross-sectional view of an assembly **204** subsequent to forming fins **104** in the assembly **202** (FIG. 5). The fins **104** may extend from a base **102**, and may be formed in the assembly **202** by patterning and then etching the assembly **202**, as known in the art. For example, a combination of dry and wet etch chemistry may be used to form the fins **104**, and the appropriate chemistry may depend on the materials included in the assembly **202**, as known in the art. At least some of the substrate **144** may be included in the base **102**, and at least some of the quantum well stack **146** may be included in the fins **104**. In particular, the quantum well layer (not shown) of the quantum well stack **146** may be included in the fins **104**. Example arrangements in which the quantum well stack **146** and the substrate **144** are differently included in the base **102** and the fins **104** are discussed below with reference to FIGS. 29-35.

FIG. 7 illustrates a cross-sectional view of an assembly **206** subsequent to providing an insulating material **128** to the assembly **204** (FIG. 6). Any suitable material may be used as the insulating material **128** to electrically insulate the fins **104** from each other. As noted above, in some embodiments, the insulating material **128** may be a dielectric material, such as silicon oxide.

FIG. 8 illustrates a cross-sectional view of an assembly **208** subsequent to planarizing the assembly **206** (FIG. 7) to remove the insulating material **128** above the fins **104**. In some embodiments, the assembly **206** may be planarized using a chemical mechanical polishing (CMP) technique.

FIG. 9 is a perspective view of at least a portion of the assembly **208**, showing the fins **104** extending from the base **102** and separated by the insulating material **128**. The cross-sectional views of FIGS. 4-8 are taken parallel to the plane of the page of the perspective view of FIG. 9. FIG. 10 is another cross-sectional view of the assembly **208**, taken along the dashed line along the fin **104-1** in FIG. 9. The cross-sectional views illustrated in FIGS. 11-25 are taken along the same cross-section as FIG. 10.

FIG. 11 is a cross-sectional view of an assembly **210** subsequent to forming a gate stack **174** on the fins **104** of the assembly **208** (FIGS. 8-10). The gate stack **174** may include the gate interface material **167**, the gate dielectric **114**, the gate metal **110**, and a hardmask **116**. The hardmask **116** may be formed of an electrically insulating material, such as silicon nitride or carbon-doped nitride. In some embodiments, the fins **104** may include a layer of silicon germanium (e.g., silicon germanium film), and the gate interface material **167** (e.g., silicon) may be formed on the layer of silicon germanium. In some embodiments, the gate interface material **167** may be grown on top of the fins **104** using epitaxy. In some embodiments, the gate dielectric **114** (e.g., hafnium oxide) may be grown on top of the gate interface material **167**. As discussed above, in some embodiments, the gate interface material **167** may be partially oxidized prior to formation of the gate dielectric **114**, and thus when the gate interface material **167** includes silicon, silicon oxide may be present at the interface between the gate interface material **167** and the gate dielectric **114**.

FIG. 12 is a cross-sectional view of an assembly **212** subsequent to patterning the hardmask **116** of the assembly **210** (FIG. 11). The pattern applied to the hardmask **116** may correspond to the locations for the gates **106**, as discussed below. The hardmask **116** may be patterned by applying a



## 11

resist, patterning the resist using lithography, and then etching the hardmask (using dry etching or any appropriate technique).

FIG. 13 is a cross-sectional view of an assembly 214 subsequent to etching the assembly 212 (FIG. 12) to remove the gate metal 110 that is not protected by the patterned hardmask 116 to form the gates 106. In some embodiments, as illustrated in FIG. 13, the gate interface material 167 and the gate dielectric 114 may remain after the etched gate metal 110 is etched away; in other embodiments, the gate interface material 167 and the gate dielectric 114 may also be etched during the etching of the gate metal 110. Examples of such embodiments are discussed below with reference to FIGS. 40-44.

FIG. 14 is a cross-sectional view of an assembly 216 subsequent to providing spacer material 132 on the assembly 214 (FIG. 13). The spacer material 132 may include any of the materials discussed above with reference to the spacers 134, for example, and may be deposited using any suitable technique. For example, the spacer material 132 may be a nitride material (e.g., silicon nitride) deposited by sputtering.

FIG. 15 is a cross-sectional view of an assembly 218 subsequent to etching the spacer material 132 of the assembly 216 (FIG. 14), leaving spacers 134 formed of the spacer material 132 on the sides of the gates 106 (e.g., on the sides of the hardmask 116 and the gate metal 110). The etching of the spacer material 132 may be an anisotropic etch, etching the spacer material 132 "downward" to remove the spacer material 132 on top of the gates 106 and in some of the area between the gates 106, while leaving the spacers 134 on the sides of the gates 106. In some embodiments, the anisotropic etch may be a dry etch.

FIG. 16 is a cross-sectional view of an assembly 220 subsequent to providing the gate metal 112 on the assembly 218 (FIG. 15). The gate metal 112 may fill the areas between adjacent ones of the gates 106, and may extend over the tops of the gates 106.

FIG. 17 is a cross-sectional view of an assembly 222 subsequent to planarizing the assembly 220 (FIG. 16) to remove the gate metal 112 above the gates 106. In some embodiments, the assembly 220 may be planarized using a CMP technique. Some of the remaining gate metal 112 may fill the areas between adjacent ones of the gates 106, while other portions 150 of the remaining gate metal 112 may be located "outside" of the gates 106.

FIG. 18 is a cross-sectional view of an assembly 224 subsequent to providing a hardmask 118 on the planarized surface of the assembly 222 (FIG. 17). The hardmask 118 may be formed of any of the materials discussed above with reference to the hardmask 116, for example.

FIG. 19 is a cross-sectional view of an assembly 226 subsequent to patterning the hardmask 118 of the assembly 224 (FIG. 18). The pattern applied to the hardmask 118 may extend over the hardmask 116 (and over the gate metal 110 of the gates 106, as well as over the locations for the gates 108 (as illustrated in FIG. 2). The hardmask 118 may be non-coplanar with the hardmask 116, as illustrated in FIG. 19. The hardmask 118 illustrated in FIG. 19 may thus be a common, continuous portion of hardmask 118 that extends over all of the hardmask 116. Examples of embodiments in which the hardmask 118 is not disposed over the entirety of the hardmask 116 are discussed below with reference to FIGS. 36-38 and 45. The hardmask 118 may be patterned using any of the techniques discussed above with reference to the patterning of the hardmask 116, for example.

FIG. 20 is a cross-sectional view of an assembly 228 subsequent to etching the assembly 226 (FIG. 19) to remove

## 12

the portions 150 that are not protected by the patterned hardmask 118 to form the gates 108. Portions of the hardmask 118 may remain on top of the hardmask 116, as shown. The operations performed on the assembly 226 may include removing any gate interface material 167 and gate dielectric 114 that is "exposed" on the fin 104, as shown. The excess gate interface material 167 and gate dielectric 114 may be removed using any suitable technique, such as chemical etching or silicon bombardment.

FIG. 21 is a cross-sectional view of an assembly 230 subsequent to doping the fins 104 of the assembly 228 (FIG. 20) to form doped regions 140 in the portions of the fins 104 "outside" of the gates 106/108. The type of dopant used to form the doped regions 140 may depend on the type of quantum dot desired, as discussed above. In some embodiments, the doping may be performed by ion implantation. For example, when the quantum dot 142 is to be an electron-type quantum dot 142, the doped regions 140 may be formed by ion implantation of phosphorous, arsenic, or another n-type material. When the quantum dot 142 is to be a hole-type quantum dot 142, the doped regions 140 may be formed by ion implantation of boron or another p-type material. An annealing process that activates the dopants and causes them to diffuse farther into the fins 104 may follow the ion implantation process. The depth of the doped regions 140 may take any suitable value; for example, in some embodiments, the doped regions 140 may extend into the fin 104 to a depth 115 between 500 and 1000 Angstroms.

The outer spacers 134 on the outer gates 106 may provide a doping boundary, limiting diffusion of the dopant from the doped regions 140 into the area under the gates 106/108. As shown, the doped regions 140 may extend under the adjacent outer spacers 134. In some embodiments, the doped regions 140 may extend past the outer spacers 134 and under the gate metal 110 of the outer gates 106, may extend only to the boundary between the outer spacers 134 and the adjacent gate metal 110, or may terminate under the outer spacers 134 and not reach the boundary between the outer spacers 134 and the adjacent gate metal 110. Examples of such embodiments are discussed below with reference to FIGS. 46 and 47. The doping concentration of the doped regions 140 may, in some embodiments, be between  $10^{17}/\text{cm}^3$  and  $10^{20}/\text{cm}^3$ .

FIG. 22 is a cross-sectional side view of an assembly 232 subsequent to providing a layer of nickel or other material 143 over the assembly 230 (FIG. 21). The nickel or other material 143 may be deposited on the assembly 230 using any suitable technique (e.g., a plating technique, chemical vapor deposition, or atomic layer deposition).

FIG. 23 is a cross-sectional side view of an assembly 234 subsequent to annealing the assembly 232 (FIG. 22) to cause the material 143 to interact with the doped regions 140 to form the interface material 141, then removing the unreacted material 143. When the doped regions 140 include silicon and the material 143 includes nickel, for example, the interface material 141 may be nickel silicide. Materials other than nickel may be deposited in the operations discussed above with reference to FIG. 22 in order to form other interface materials 141, including titanium, aluminum, molybdenum, cobalt, tungsten, or platinum, for example. More generally, the interface material 141 of the assembly 234 may include any of the materials discussed herein with reference to the interface material 141.

FIG. 24 is a cross-sectional view of an assembly 236 subsequent to providing an insulating material 130 on the assembly 234 (FIG. 23). The insulating material 130 may take any of the forms discussed above. For example, the insulating material 130 may be a dielectric material, such as



silicon oxide. The insulating material **130** may be provided on the assembly **234** using any suitable technique, such as spin coating, chemical vapor deposition (CVD), or plasma-enhanced CVD (PECVD). In some embodiments, the insulating material **130** may be polished back after deposition, and before further processing.

FIG. **25** is a cross-sectional view of an assembly **238** subsequent to forming, in the assembly **236** (FIG. **24**), conductive vias **120** through the insulating material **130** (and the hardmasks **116** and **118**) to contact the gate metal **110** of the gates **106**, conductive vias **122** through the insulating material **130** (and the hardmask **118**) to contact the gate metal **112** of the gates **108**, and conductive vias **136** through the insulating material **130** to contact the doped region interface material **141** of the doped regions **140**. Further conductive vias and/or lines may be formed on the assembly **238** using conventional interconnect techniques, if desired. The resulting assembly **238** may take the form of the quantum dot device **100** discussed above with reference to FIGS. **1-3**. In some embodiments, the assembly **236** may be planarized to remove the hardmasks **116** and **118**, then additional insulating material **130** may be provided on the planarized surface before forming the conductive vias **120**, **122**, and **136**; in such an embodiment, the hardmasks **116** and **118** would not be present in the quantum dot device **100**.

As discussed above, the base **102** and the fin **104** of a quantum dot device **100** may be formed from a substrate **144** and a quantum well stack **146** disposed on the substrate **144**. The quantum well stack **146** may include a quantum well layer in which a 2DEG may form during operation of the quantum dot device **100**. The gate interface material **167** may be formed on the quantum well stack **146**, and may act as an interface between the quantum well stack **146** and the gate dielectric **114**. The quantum well stack **146** may take any of a number of forms, several of which are illustrated in FIGS. **26-28**. The various layers in the quantum well stacks **146** discussed below may be grown on the substrate **144** (e.g., using epitaxial processes).

FIG. **26** is a cross-sectional view of a quantum well stack **146** including only a quantum well layer **152**. The quantum well layer **152** may be disposed on the substrate **144** (e.g., as discussed above with reference to FIG. **5**), and may be formed of a material such that, during operation of the quantum dot device **100**, a 2DEG may form in the quantum well layer **152** proximate to the upper surface of the quantum well layer **152**. The gate dielectric **114** of the gates **106/108** may be disposed on the upper surface of the quantum well layer **152** (e.g., as discussed above with reference to FIG. **11**). In some embodiments, the quantum well layer **152** of FIG. **26** may be formed of intrinsic silicon, and the gate dielectric **114** may be formed of silicon oxide; in such an arrangement, during use of the quantum dot device **100**, a 2DEG may form in the intrinsic silicon at the interface between the intrinsic silicon and the silicon oxide. Embodiments in which the quantum well layer **152** of FIG. **26** is formed of intrinsic silicon may be particularly advantageous for electron-type quantum dot devices **100**. In some embodiments, the quantum well layer **152** of FIG. **26** may be formed of intrinsic germanium, and the gate dielectric **114** may be formed of germanium oxide; in such an arrangement, during use of the quantum dot device **100**, a 2DEG may form in the intrinsic germanium at the interface between the intrinsic germanium and the germanium oxide. Such embodiments may be particularly advantageous for hole-type quantum dot devices **100**. In some embodiments, the quantum well layer **152** may be strained, while in other embodiments, the quantum well layer **152** may not be

strained. The thicknesses (i.e., z-heights) of the layers in the quantum well stack **146** of FIG. **26** may take any suitable values. For example, in some embodiments, the thickness of the quantum well layer **152** (e.g., intrinsic silicon or germanium) may be between 0.8 and 1.2 microns.

FIG. **27** is a cross-sectional view of a quantum well stack **146** including a quantum well layer **152** and a barrier layer **154**. The quantum well stack **146** may be disposed on a substrate **144** (e.g., as discussed above with reference to FIG. **5**) such that the barrier layer **154** is disposed between the quantum well layer **152** and the substrate **144**. The barrier layer **154** may provide a potential barrier between the quantum well layer **152** and the substrate **144**. As discussed above with reference to FIG. **26**, the quantum well layer **152** of FIG. **27** may be formed of a material such that, during operation of the quantum dot device **100**, a 2DEG may form in the quantum well layer **152** proximate to the upper surface of the quantum well layer **152**. For example, in some embodiments in which the substrate **144** is formed of silicon, the quantum well layer **152** of FIG. **27** may be formed of silicon, and the barrier layer **154** may be formed of silicon germanium. The germanium content of this silicon germanium may be 20-80% (e.g., 30%). In some embodiments in which the quantum well layer **152** is formed of germanium, the barrier layer **154** may be formed of silicon germanium (with a germanium content of 20-80% (e.g., 70%)). The thicknesses (i.e., z-heights) of the layers in the quantum well stack **146** of FIG. **27** may take any suitable values. For example, in some embodiments, the thickness of the barrier layer **154** (e.g., silicon germanium) may be between 0 and 400 nanometers. In some embodiments, the thickness of the quantum well layer **152** (e.g., silicon or germanium) may be between 5 and 30 nanometers.

FIG. **28** is a cross-sectional view of a quantum well stack **146** including a quantum well layer **152** and a barrier layer **154-1**, as well as a buffer layer **176** and an additional barrier layer **154-2**. In some embodiments, the gate interface material **167** may be grown on the barrier layer **154-2**. The quantum well stack **146** may be disposed on the substrate **144** (e.g., as discussed above with reference to FIG. **5**) such that the buffer layer **176** is disposed between the barrier layer **154-1** and the substrate **144**. The buffer layer **176** may be formed of the same material as the barrier layer **154**, and may be present to trap defects that form in this material as it is grown on the substrate **144**. In some embodiments, the buffer layer **176** may be grown under different conditions (e.g., deposition temperature or growth rate) from the barrier layer **154-1**. In particular, the barrier layer **154-1** may be grown under conditions that achieve fewer defects than the buffer layer **176**. In some embodiments in which the buffer layer **176** includes silicon germanium, the silicon germanium of the buffer layer **176** may have a germanium content that varies from the substrate **144** to the barrier layer **154-1**; for example, the silicon germanium of the buffer layer **176** may have a germanium content that varies from zero percent at the silicon substrate **144** to a nonzero percent (e.g., 30%) at the barrier layer **154-1**. The thicknesses (i.e., z-heights) of the layers in the quantum well stack **146** of FIG. **28** may take any suitable values. For example, in some embodiments, the thickness of the buffer layer **176** (e.g., silicon germanium) may be between 0.3 and 4 microns (e.g., 0.3-2 microns, or 0.5 microns). In some embodiments, the thickness of the barrier layer **154-1** (e.g., silicon germanium) may be between 0 and 400 nanometers. In some embodiments, the thickness of the quantum well layer **152** (e.g., silicon or germanium) may be between 5 and 30 nanometers (e.g., 10 nanometers). The barrier layer **154-2**, like the barrier layer



**154-1**, may provide a potential energy barrier around the quantum well layer **152**, and may take the form of any of the embodiments of the barrier layer **154-1**. In some embodiments, the thickness of the barrier layer **154-2** (e.g., silicon germanium) may be between 25 and 75 nanometers (e.g., 32 nanometers). As discussed above, in some embodiments, the gate interface material **167** (e.g., silicon) may be grown on a silicon germanium barrier layer **154-2**.

As discussed above with reference to FIG. **27**, the quantum well layer **152** of FIG. **28** may be formed of a material such that, during operation of the quantum dot device **100**, a 2DEG may form in the quantum well layer **152** proximate to the upper surface of the quantum well layer **152**. For example, in some embodiments in which the substrate **144** is formed of silicon, the quantum well layer **152** of FIG. **28** may be formed of silicon, and the barrier layer **154-1** and the buffer layer **176** may be formed of silicon germanium. In some such embodiments, the silicon germanium of the buffer layer **176** may have a germanium content that varies from the substrate **144** to the barrier layer **154-1**; for example, the silicon germanium of the buffer layer **176** may have a germanium content that varies from zero percent at the silicon substrate **144** to a nonzero percent (e.g., 30%) at the barrier layer **154-1**. The barrier layer **154-1** may in turn have a germanium content equal to the nonzero percent. In other embodiments, the buffer layer **176** may have a germanium content equal to the germanium content of the barrier layer **154-1** but may be thicker than the barrier layer **154-1** so as to absorb the defects that arise during growth.

In some embodiments, the quantum well layer **152** of FIG. **28** may be formed of germanium, and the buffer layer **176** and the barrier layer **154-1** may be formed of silicon germanium. In some such embodiments, the silicon germanium of the buffer layer **176** may have a germanium content that varies from the substrate **144** to the barrier layer **154-1**; for example, the silicon germanium of the buffer layer **176** may have a germanium content that varies from zero percent at the substrate **144** to a nonzero percent (e.g., 70%) at the barrier layer **154-1**. The barrier layer **154-1** may in turn have a germanium content equal to the nonzero percent. In other embodiments, the buffer layer **176** may have a germanium content equal to the germanium content of the barrier layer **154-1** but may be thicker than the barrier layer **154-1** so as to absorb the defects that arise during growth. In some embodiments of the quantum well stack **146** of FIG. **28**, the buffer layer **176** and/or the barrier layer **154-2** may be omitted.

The substrate **144** and the quantum well stack **146** may be distributed between the base **102** and the fins **104** of the quantum dot device **100**, as discussed above. This distribution may occur in any of a number of ways. For example, FIGS. **29-35** illustrate example base/fin arrangements **158** that may be used in a quantum dot device **100**, in accordance with various embodiments.

In the base/fin arrangement **158** of FIG. **29**, the quantum well stack **146** may be included in the fins **104**, but not in the base **102**. The substrate **144** may be included in the base **102**, but not in the fins **104**. When the base/fin arrangement **158** of FIG. **29** is used in the manufacturing operations discussed with reference to FIGS. **5-6**, the fin etching may etch through the quantum well stack **146**, and stop when the substrate **144** is reached.

In the base/fin arrangement **158** of FIG. **30**, the quantum well stack **146** may be included in the fins **104**, as well as in a portion of the base **102**. A substrate **144** may be included in the base **102** as well, but not in the fins **104**. When the base/fin arrangement **158** of FIG. **30** is used in the manu-

facturing operations discussed with reference to FIGS. **5-6**, the fin etching may etch partially through the quantum well stack **146**, and stop before the substrate **144** is reached. FIG. **31** illustrates a particular embodiment of the base/fin arrangement **158** of FIG. **30**. In the embodiment of FIG. **31**, the quantum well stack **146** of FIG. **28** is used; the fins **104** include the barrier layer **154-1**, the quantum well layer **152**, and the barrier layer **154-2**, while the base **102** includes the buffer layer **176** and the substrate **144**.

In the base/fin arrangement **158** of FIG. **32**, the quantum well stack **146** may be included in the fins **104**, but not the base **102**. The substrate **144** may be partially included in the fins **104**, as well as in the base **102**. When the base/fin arrangement **158** of FIG. **32** is used in the manufacturing operations discussed with reference to FIGS. **5-6**, the fin etching may etch through the quantum well stack **146** and into the substrate **144** before stopping. FIG. **33** illustrates a particular embodiment of the base/fin arrangement **158** of FIG. **32**. In the embodiment of FIG. **33**, the quantum well stack **146** of FIG. **28** is used; the fins **104** include the quantum well stack **146** and a portion of the substrate **144**, while the base **102** includes the remainder of the substrate **144**.

Although the fins **104** have been illustrated in many of the preceding figures as substantially rectangular with parallel sidewalls, this is simply for ease of illustration, and the fins **104** may have any suitable shape (e.g., shape appropriate to the manufacturing processes used to form the fins **104**). For example, as illustrated in the base/fin arrangement **158** of FIG. **34**, in some embodiments, the fins **104** may be tapered. In some embodiments, the fins **104** may taper by 3-10 nanometers in x-width for every 100 nanometers in z-height (e.g., 5 nanometers in x-width for every 100 nanometers in z-height). When the fins **104** are tapered, the wider end of the fins **104** may be the end closest to the base **102**, as illustrated in FIG. **34**. FIG. **35** illustrates a particular embodiment of the base/fin arrangement **158** of FIG. **34**. In FIG. **35**, the quantum well stack **146** is included in the tapered fins **104** while a portion of the substrate **144** is included in the tapered fins and a portion of the substrate **144** provides the base **102**.

In the embodiment of the quantum dot device **100** illustrated in FIG. **2**, the z-height of the gate metal **112** of the gates **108** may be approximately equal to the sum of the z-height of the gate metal **110** and the z-height of the hardmask **116**, as shown. Also in the embodiment of FIG. **2**, the gate metal **112** of the gates **108** may not extend in the x-direction beyond the adjacent spacers **134**. In other embodiments, the z-height of the gate metal **112** of the gates **108** may be greater than the sum of the z-height of the gate metal **110** and the z-height of the hardmask **116**, and in some such embodiments, the gate metal **112** of the gates may extend beyond the spacers **134** in the x-direction. FIGS. **36-38** illustrate various example stages in the manufacture of alternative gate arrangements that may be included in a quantum dot device **100**, in accordance with various embodiments.

FIG. **36** illustrates an assembly **242** subsequent to providing the gate metal **112** and a hardmask **118** on the assembly **218** (FIG. **15**). The assembly **242** may be similar to the assembly **224** of FIG. **18** (and may be formed using any of the techniques discussed above with reference to FIGS. **16-18**), but may include additional gate metal **112** between the hardmask **116** and the hardmask **118**, of any desired thickness. In some embodiments, the gate metal **112** may be planarized prior to provision of the hardmask **118**,



but the hardmask **118** may still be spaced away from the hardmask **116** in the z-direction by the gate metal **112**, as shown in FIG. **36**.

FIG. **37** illustrates an assembly **244** subsequent to patterning the hardmask **118** of the assembly **242** (FIG. **36**). The pattern applied to the hardmask **118** may include the locations for the gates **108**, as discussed below. The hardmask **118** may be non-coplanar with the hardmask **116**, as illustrated in FIG. **36**, and may extend “over” at least a portion of the hardmask **116** (and thus over the gate metal **110** of the gates **106**).

FIG. **38** illustrates an assembly **246** subsequent to etching the assembly **244** (FIG. **37**) to remove the portions **150** that are not protected by the patterned hardmask **118** to form the gates **108**. The gate metal **112** of the gates **106** may extend “over” the hardmask **116** of the gates **108**, and may be electrically insulated from the gate metal **110** by the hardmask **116**. In the embodiment illustrated in FIG. **38**, the z-height of the gate metal **112** of the gates **108** may be greater than the sum of the z-height of the gate metal **110** and the z-height of the hardmask **116** of the gates **106**. Additionally, the gate metal **112** of the gates **108** may extend beyond the spacers **134** in the x-direction, as shown. Further manufacturing operations may be performed on the assembly **246**, as discussed above with reference to FIGS. **21-25**.

As noted above, a single fin **104** may include multiple groups of gates **106/108**, spaced apart along the fin by a doped region **140**. FIG. **39** is a cross-sectional view of an example of such a quantum dot device **100** having multiple groups of gates **180** on a single fin **104**, in accordance with various embodiments. Each of the groups **180** may include gates **106/108** (not labeled in FIG. **39** for ease of illustration) that may take the form of any of the embodiments of the gates **106/108** discussed herein. A doped region **140** (and its doped region interface material **141**) may be disposed between two adjacent groups **180** (labeled in FIG. **39** as groups **180-1** and **180-2**), and may provide a common reservoir for both groups **180**. In some embodiments, this “common” doped region **140** may be electrically contacted by a single conductive via **136**. The particular number of gates **106/108** illustrated in FIG. **39**, and the particular number of groups **180**, is simply illustrative, and a fin **104** may include any suitable number of gates **106/108** arranged in any suitable number of groups **180**.

As discussed above with reference to FIGS. **1-3**, in some embodiments in which the gate interface material **167** and the gate dielectric **114** is not a layer shared commonly between the gates **108** and **106**, but instead is separately deposited on the fin **104** between the spacers **134**, the gate interface material **167** and the gate dielectric **114** may extend at least partially up the sides of the spacers **134**, and the gate metal **112** may extend between the portions of the gate interface material **167**/gate dielectric **114** on the spacers **134**. FIGS. **40-44** illustrate various alternative stages in the manufacture of such an embodiment of a quantum dot device **100**, in accordance with various embodiments. In particular, the operations illustrated in FIGS. **40-44** may take the place of the operations illustrated in FIGS. **13-15**.

FIG. **40** is a cross-sectional view of an assembly **248** subsequent to etching the assembly **212** (FIG. **12**) to remove the gate metal **110**, and the gate interface material **167**/gate dielectric **114** that is not protected by the patterned hardmask **116**, to form the gates **106**.

FIG. **41** is a cross-sectional view of an assembly **250** subsequent to providing spacer material **132** on the assembly

**248** (FIG. **40**). The deposition of the spacer material **132** may take any of the forms discussed above with reference to FIG. **14**, for example.

FIG. **42** is a cross-sectional view of an assembly **252** subsequent to etching the spacer material **132** of the assembly **250** (FIG. **41**), leaving spacers **134** formed of the spacer material **132** on the sides of the gates **106** (e.g., on the sides of the hardmask **116**, the gate metal **110**, the gate dielectric **114**, and the gate interface material **167**). The etching of the spacer material **132** may take any of the forms discussed above with reference to FIG. **15**, for example.

FIG. **43** is a cross-sectional view of an assembly **254** subsequent to providing a gate interface material **167** and a gate dielectric **114** on the fin **104** between the gates **106** of the assembly **252** (FIG. **42**). In some embodiments, the gate interface material **167** is first provided between the gates **106** of the assembly **252** by atomic layer deposition (ALD), and then the gate dielectric **114** may be provided on the gate interface material **167** between the gates **106** by ALD. As illustrated in FIG. **43**, the gate interface material **167** and the gate dielectric **114** may cover the exposed fin **104** between the gates **106**, and may extend onto the adjacent spacers **134**. As illustrated in FIG. **43**, the gate interface material **167** and the gate dielectric **114** provided between the gates **106** of the assembly **252** may have U-shaped cross-sections.

FIG. **44** is a cross-sectional view of an assembly **256** subsequent to providing the gate metal **112** on the assembly **254** (FIG. **43**). The gate metal **112** may fill the areas between adjacent ones of the gates **106**, and may extend over the tops of the gates **106**, as shown. The provision of the gate metal **112** may take any of the forms discussed above with reference to FIG. **16**, for example. The assembly **256** may be further processed as discussed above with reference to FIGS. **17-25** to form gates **108** with the gate metal **112**.

As discussed above with reference to FIG. **19**, in some embodiments, the pattern applied to the hardmask **118** (used for patterning the gates **108**) may not result in a common, continuous portion of hardmask **118** that extends over all of the hardmask **116**. One such example was discussed above with reference to FIGS. **36-38**, and another example of such an embodiment is illustrated in FIG. **45**. In particular, FIG. **45** is a cross-sectional view of an assembly **258** in which the hardmask **118** of the assembly **224** (FIG. **18**) is not patterned to extend over the gates **106**, but instead is patterned so as not to extend over the gate metal **110**. The assembly **258** may be further processed as discussed above with reference to FIGS. **20-25** (e.g., etching away the excess portions **150**, etc.). In some embodiments, the hardmasks **116** and **118** may remain in the quantum dot device **100** as part of the gates **106/108**, while in other embodiments, the hardmasks **116** and **118** may be removed.

As discussed above with reference to FIGS. **2** and **21**, the outer spacers **134** on the outer gates **106** may provide a doping boundary, limiting diffusion of the dopant from the doped regions **140** into the area under the gates **106/108**. In some embodiments, the doped regions **140** may extend past the outer spacers **134** and under the outer gates **106**. For example, as illustrated in FIG. **46**, the doped region **140** may extend past the outer spacers **134** and under the outer gates **106** by a distance **182** between **0** and **10** nanometers. In some embodiments, the doped regions **140** may not extend past the outer spacers **134** toward the outer gates **106**, but may instead “terminate” under the outer spacers **134**. For example, as illustrated in FIG. **47**, the doped regions **140** may be spaced away from the interface between the outer spacers **134** and the outer gates **106** by a distance **184**



between 0 and 10 nanometers. The doped region interface material **141** is omitted from FIGS. **46** and **47** for ease of illustration.

In some embodiments, the gate stack formed on the fin **104** (e.g., as discussed above with reference to the gate stack **174** of FIG. **11**) may not be a “real” gate stack (e.g., a gate stack consisting of a gate metal and gate dielectric that will be included in the final quantum dot device **100**), but may be a “dummy” gate stack of other materials. Many of the processing operations performed as discussed herein on the gate stack **174** may instead be performed on this dummy gate stack, and at an appropriate time, the dummy gate stack may be replaced with “real” gate materials. In some embodiments, the gates **106** may first be formed with dummy materials, then replaced with real materials, or the gates **108** may be formed with dummy materials then replaced with real materials, or both the gates **106** and the gates **108** may first be formed with dummy materials and then replaced with real materials. These replacement gate techniques may be advantageous when the processing operations that come after initial gate formation (e.g., as part of a front-end process) involve high temperatures (e.g., during thermal activation of the doped regions **140**). Under such high temperatures, some materials that may be included in the gate metal **110** and/or the gate dielectric **114** may degrade (e.g., by changing the work function of the gate metal **110** and/or the quality of the gate dielectric **114**). Thus, it may be preferable to perform many of the manufacturing operations disclosed herein with dummy gate stacks and replace the dummy materials with real materials after the high temperature operations are complete. Examples of each of these embodiments are discussed below with reference to FIGS. **48-58**.

FIGS. **48-58** illustrate example stages in a manufacturing process in which the gates **106** are first formed of dummy materials, while the gates **108** are first formed of real materials. In particular, FIG. **48** is a cross-sectional view of an assembly **286** subsequent to forming a dummy gate stack **408** on the fins **104** of the assembly **208** (FIGS. **8-10**). The dummy gate stack **408** may include a dummy dielectric **412**, a dummy fill **410**, and a hardmask **116**. The hardmask **116** of the assembly **286** may take the form of any of the embodiments of the hardmask **116** disclosed herein. The dummy fill **410** may include any suitable material, such as polysilicon, silicon nitride (or other nitrides), or an appropriate oxide. The dummy dielectric **412** may include any suitable material, such as a silicon oxide (deposited, e.g., using chemical vapor deposition).

FIG. **49** is a cross-sectional view of an assembly **288** subsequent to processing the assembly **286** (FIG. **48**) in accordance with the operations illustrated in FIGS. **12**, **40-44**, and **17-24**. In particular, the dummy gate stack **408** may be patterned to form dummy gate stacks **414** including the dummy dielectric **412** and the dummy fill **410**. The assembly **288** of FIG. **49** may have a structure that is similar to assembly **236** (FIG. **24**), but in the assembly **288**, the gates **108** may take the form discussed above with reference to FIG. **44**, and the assembly **288** may include dummy gate stacks **414** (including the dummy dielectric **412** and the dummy fill **410**) instead of the gates **106** (including the gate interface material **167**, the gate dielectric **114**, and the gate metal **110**). The dimensions of the dummy gate stacks **414** may take the form of any of the embodiments of the gates **106** disclosed herein.

FIG. **50** is a cross-sectional view of an assembly **290** subsequent to planarizing the assembly **288** (FIG. **49**) to remove the hardmask **118** and the hardmask **116** and thereby

expose the dummy fill **410** (of the dummy gate stacks **414**) and the gate metal **112** (of the gates **108**). This planarization may be performed, for example, using a CMP technique.

FIG. **51** illustrates an assembly **292** subsequent to removing the dummy fill **410** and the dummy dielectric **412** from the assembly **290** (FIG. **50**) to form recesses **416**. These recesses **416** may extend down to the fin **104**, and may be bordered by spacers **134**. As illustrated in FIG. **51**, the curved surfaces of the spacers **134** may face away from the recesses **416**, while the flat surfaces of the spacers **134** may face the recesses **416** (because the spacers **134** were formed on the dummy gate stacks **414**).

FIG. **52** illustrates an assembly **294** subsequent to providing a gate interface material **167** and a gate dielectric **114** on the fin **104** in the recesses **416** of the assembly **292** (FIG. **51**). In some embodiments, the gate interface material **167** and the gate dielectric **114** provided in the recesses **416** of the assembly **292** may be formed by ALD and, as illustrated in FIG. **52**, may cover the exposed fin **104** in the recesses **416**, and may extend onto the adjacent spacers **134**. As illustrated in FIG. **52**, the gate interface material **167** and the gate dielectric **114** provided in the recesses **416** may have U-shaped cross-sections.

FIG. **53** illustrates an assembly **296** subsequent to providing the gate metal **110** on the assembly **294** (FIG. **52**). The gate metal **110** may fill the recesses **416**, and may extend over the tops of the gates **108**, as shown. The provision of the gate metal **110** may take any of the forms discussed above with reference to FIG. **16**, for example.

FIG. **54** illustrates an assembly **298** subsequent to planarizing the assembly **296** (FIG. **53**) to remove the excess gate metal **110** (e.g., using a CMP technique). The assembly **298** includes gates **106** and **108**, and may be further processed as discussed above with reference to FIGS. **24-25** (e.g., by depositing more insulating material **130** and then providing conductive contacts to the gates **106** and **108**) to form a quantum dot device **100**.

FIGS. **55-60** illustrate example stages in a manufacturing process in which the gates **108** are first formed of dummy materials, while the gates **106** are first formed of real materials. In particular, FIG. **55** is a cross-sectional view of an assembly **300** subsequent to providing a dummy dielectric **412** on the fin **104** in the recesses **418** between the gates **106** of the assembly **252** (FIG. **42**). In some embodiments, the dummy dielectric **412** provided between the gates **106** of the assembly **252** may be formed by ALD and, as illustrated in FIG. **55**, may cover the exposed fin **104** between the gates **106**, and may extend onto the adjacent spacers **134**. As illustrated in FIG. **55**, the dummy dielectric **412** provided between the gates **106** of the assembly **252** may have a U-shaped cross-section.

FIG. **56** is a cross-sectional view of an assembly **302** subsequent to providing a dummy fill **410** on the assembly **300** (FIG. **55**). The dummy fill **410** may fill the areas between adjacent ones of the gates **106** (e.g., in the recesses **418**), and may extend over the tops of the gates **106**, as shown. The provision of the dummy fill **410** may take any of the forms discussed above with reference to FIG. **16**, for example. The dummy fill **410** and the dummy dielectric **412** may provide a dummy gate stack **408**.

FIG. **57** is a cross-sectional view of an assembly **304** subsequent to processing the assembly **302** (FIG. **56**) in accordance with the operations illustrated in FIGS. **17-24** (e.g., planarizing, deposition of a hardmask, etc.). The resulting assembly **304** may include dummy gate stacks **420** including dummy fill **410** and dummy dielectric **412**. The assembly **304** of FIG. **57** may have a structure that is similar



to assembly 236 (FIG. 24), but in the assembly 304, the dummy gate stacks 420 may take the place of the gates 108 and may be the “dummy” versions of the structure discussed above with reference to the gates 108 of FIG. 44. The dimensions of the dummy gate stacks 420 may take the form of any of the embodiments of the gates 108 disclosed herein. The assembly 304 may then be further processed as discussed above with reference to FIGS. 49-54 to replace the dummy gate stacks 420 with “real” gates 108 that include the gate metal 112, the gate dielectric 114, and the gate interface material 167 (e.g., by planarizing, removing the dummy materials, replacing the dummy materials with real materials, etc.) and that have the form illustrated in FIG. 49.

In some embodiments, both the gates 106 and the gates 108 may be first formed of dummy materials, then later replaced by real materials. FIG. 58 illustrates an assembly 306 including dummy gate stacks 414 and dummy gate stacks 420 that may be formed by starting with the assembly 286 of FIG. 48 and processing the assembly 286 as described above with reference to FIGS. 11-24, except that instead of deposition of the gate metal 112 (e.g., as discussed above with reference to the assembly 220 of FIG. 16), the dummy fill 410 is deposited. The assembly 306 may be processed as described above with reference to FIGS. 49-54 to replace the dummy gate stacks 414 with real gates 106, and as discussed above with reference to FIG. 57 to replace the dummy gate stacks 420 with real gates 108. The dummy gate stacks 414 may be replaced before the dummy gate stacks 420, after the dummy gate stacks 420, or simultaneously with the dummy gate stacks 420, in various embodiments.

As noted above, any suitable techniques may be used to manufacture the quantum dot devices 100 disclosed herein. FIG. 59 is a flow diagram of an illustrative method 1000 of manufacturing a quantum dot device, in accordance with various embodiments. Although the operations discussed below with reference to the method 1000 are illustrated in a particular order and depicted once each, these operations may be repeated or performed in a different order (e.g., in parallel), as suitable. Additionally, various operations may be omitted, as suitable. Various operations of the method 1000 may be illustrated with reference to one or more of the embodiments discussed above, but the method 1000 may be used to manufacture any suitable quantum dot device (including any suitable ones of the embodiments disclosed herein).

At 1002, a gate interface material may be provided on a quantum well stack. For example, a gate interface material 167 may be provided on a quantum well stack 146 (e.g., as discussed above with reference to FIGS. 11 and 48-58).

At 1004, a gate dielectric may be provided on the gate interface material. For example, a gate dielectric 114 may be provided on a gate interface material 167 (e.g., as discussed above with reference to FIGS. 11 and 48-58).

At 1006, a gate metal may be provided such that the gate dielectric is disposed between the gate interface material and the gate metal. For example, a gate metal 110 or 112 may be provided such that the gate dielectric 114 is disposed between the gate interface material 167 and the gate metal 110 or 112 (e.g., as discussed above with reference to FIGS. 11, 16, 44, and 48-58).

A number of techniques are disclosed herein for operating a quantum dot device 100. FIGS. 60-61 are flow diagrams of particular illustrative methods 1020 and 1040, respectively, of operating a quantum dot device, in accordance with various embodiments. Although the operations discussed below with reference to the methods 1020 and 1040 are

illustrated in a particular order and depicted once each, these operations may be repeated or performed in a different order (e.g., in parallel), as suitable. Additionally, various operations may be omitted, as suitable. Various operations of the methods 1020 and 1040 may be illustrated with reference to one or more of the embodiments discussed above, but the methods 1020 and 1040 may be used to operate any suitable quantum dot device (including any suitable ones of the embodiments disclosed herein).

Turning to the method 1020 of FIG. 60, at 1022, one or more voltages may be applied to one or more gates on a first quantum well stack region to cause a first quantum dot to form in the first quantum well stack region. At least one gate on the first quantum well stack region may include a gate dielectric and a gate interface material disposed between the gate dielectric in the first quantum well stack region. For example, one or more voltages may be applied to the gates 106/108 (including the gate dielectric 114 and the gate interface material 167) on a fin 104-1 (extending away from the base 102) to cause at least one quantum dot 142 to form in the fin 104-1.

At 1024, one or more voltages may be applied to one or more gates on a second quantum well stack region to cause a second quantum dot to form in the second quantum well stack region. For example, one or more voltages may be applied to the gates 106/108 on a fin 104-2 (extending away from the base 102 and spaced apart from the fin 104-1 by the insulating material 128) to cause at least one quantum dot 142 to form in the fin 104-2.

At 1026, a quantum state of the first quantum dot may be sensed with the second quantum dot. For example, a quantum dot 142 in the fin 104-2 (the “read” fin) may sense the quantum state of a quantum dot 142 in the fin 104-1 (the “active” fin).

Turning to the method 1040 of FIG. 61, at 1042, a voltage may be applied to a first gate disposed on a quantum well stack region to cause a first quantum dot to form in a first quantum well in the quantum well stack region under the first gate. For example, a voltage may be applied to the gate 108-1 disposed on a fin 104 to cause a first quantum dot 142 to form in the quantum well layer 152 in the fin 104 under the gate 108-1. The fin 104 may extend away from the base 102, and the insulating material 128 may be disposed on side faces of the fin 104.

At 1044, a voltage may be applied to a second gate disposed on the quantum well stack region to cause a second quantum dot to form in a second quantum well in the quantum well stack region under the second gate. For example, a voltage may be applied to the gate 108-2 disposed on the fin 104 to cause a second quantum dot 142 to form in the quantum well layer 152 in the fin 104 under the gate 108-2.

At 1046, a voltage may be applied to a third gate disposed on the quantum well stack region to (1) cause a third quantum dot to form in a third quantum well in the quantum well stack region under the third gate or (2) provide a potential barrier between the first quantum well and the second quantum well. At least one gate on the quantum well stack region may include a gate dielectric and a gate interface material disposed between the gate dielectric in the first quantum well stack region (e.g., the gate dielectric 114 and the gate interface material 167). For example, a voltage may be applied to the gate 106-2 to (1) cause a third quantum dot 142 to form in the quantum well layer 152 in the fin 104 (e.g., when the gate 106-2 acts as a “plunger” gate) or (2) provide a potential barrier between the first quantum well



(under the gate **108-1**) and the second quantum well (under the gate **108-2**) (e.g., when the gate **106-2** acts as a “barrier” gate).

FIG. **62** is a block diagram of an example quantum computing device **2000** that may include any of the quantum dot devices disclosed herein. A number of components are illustrated in FIG. **62** as included in the quantum computing device **2000**, but any one or more of these components may be omitted or duplicated, as suitable for the application. In some embodiments, some or all of the components included in the quantum computing device **2000** may be attached to one or more printed circuit boards (e.g., a motherboard). In some embodiments, various ones of these components may be fabricated onto a single system-on-a-chip (SoC) die. Additionally, in various embodiments, the quantum computing device **2000** may not include one or more of the components illustrated in FIG. **62**, but the quantum computing device **2000** may include interface circuitry for coupling to the one or more components. For example, the quantum computing device **2000** may not include a display device **2006**, but may include display device interface circuitry (e.g., a connector and driver circuitry) to which a display device **2006** may be coupled. In another set of examples, the quantum computing device **2000** may not include an audio input device **2024** or an audio output device **2008**, but may include audio input or output device interface circuitry (e.g., connectors and supporting circuitry) to which an audio input device **2024** or audio output device **2008** may be coupled.

The quantum computing device **2000** may include a processing device **2002** (e.g., one or more processing devices). As used herein, the term “processing device” or “processor” may refer to any device or portion of a device that processes electronic data from registers and/or memory to transform that electronic data into other electronic data that may be stored in registers and/or memory. The processing device **2002** may include a quantum processing device **2026** (e.g., one or more quantum processing devices), and a non-quantum processing device **2028** (e.g., one or more non-quantum processing devices). The quantum processing device **2026** may include one or more of the quantum dot devices **100** disclosed herein, and may perform data processing by performing operations on the quantum dots that may be generated in the quantum dot devices **100**, and monitoring the result of those operations. For example, as discussed above, different quantum dots may be allowed to interact, the quantum states of different quantum dots may be set or transformed, and the quantum states of quantum dots may be read (e.g., by another quantum dot). The quantum processing device **2026** may be a universal quantum processor, or specialized quantum processor configured to run one or more particular quantum algorithms. In some embodiments, the quantum processing device **2026** may execute algorithms that are particularly suitable for quantum computers, such as cryptographic algorithms that utilize prime factorization, encryption/decryption, algorithms to optimize chemical reactions, algorithms to model protein folding, etc. The quantum processing device **2026** may also include support circuitry to support the processing capability of the quantum processing device **2026**, such as input/output channels, multiplexers, signal mixers, quantum amplifiers, and analog-to-digital converters.

As noted above, the processing device **2002** may include a non-quantum processing device **2028**. In some embodiments, the non-quantum processing device **2028** may provide peripheral logic to support the operation of the quantum processing device **2026**. For example, the non-quantum

processing device **2028** may control the performance of a read operation, control the performance of a write operation, control the clearing of quantum bits, etc. The non-quantum processing device **2028** may also perform conventional computing functions to supplement the computing functions provided by the quantum processing device **2026**. For example, the non-quantum processing device **2028** may interface with one or more of the other components of the quantum computing device **2000** (e.g., the communication chip **2012** discussed below, the display device **2006** discussed below, etc.) in a conventional manner, and may serve as an interface between the quantum processing device **2026** and conventional components. The non-quantum processing device **2028** may include one or more digital signal processors (DSPs), application-specific integrated circuits (ASICs), central processing units (CPUs), graphics processing units (GPUs), cryptoprocessors (specialized processors that execute cryptographic algorithms within hardware), server processors, or any other suitable processing devices.

The quantum computing device **2000** may include a memory **2004**, which may itself include one or more memory devices such as volatile memory (e.g., dynamic random access memory (DRAM)), nonvolatile memory (e.g., read-only memory (ROM)), flash memory, solid state memory, and/or a hard drive. In some embodiments, the states of qubits in the quantum processing device **2026** may be read and stored in the memory **2004**. In some embodiments, the memory **2004** may include memory that shares a die with the non-quantum processing device **2028**. This memory may be used as cache memory and may include embedded dynamic random access memory (eDRAM) or spin transfer torque magnetic random-access memory (STT-MRAM).

The quantum computing device **2000** may include a cooling apparatus **2030**. The cooling apparatus **2030** may maintain the quantum processing device **2026** at a predetermined low temperature during operation to reduce the effects of scattering in the quantum processing device **2026**. This predetermined low temperature may vary depending on the setting; in some embodiments, the temperature may be 5 degrees Kelvin or less. In some embodiments, the non-quantum processing device **2028** (and various other components of the quantum computing device **2000**) may not be cooled by the cooling apparatus **2030**, and may instead operate at room temperature. The cooling apparatus **2030** may be, for example, a dilution refrigerator, a helium-3 refrigerator, or a liquid helium refrigerator.

In some embodiments, the quantum computing device **2000** may include a communication chip **2012** (e.g., one or more communication chips). For example, the communication chip **2012** may be configured for managing wireless communications for the transfer of data to and from the quantum computing device **2000**. The term “wireless” and its derivatives may be used to describe circuits, devices, systems, methods, techniques, communications channels, etc., that may communicate data through the use of modulated electromagnetic radiation through a nonsolid medium. The term does not imply that the associated devices do not contain any wires, although in some embodiments they might not.

The communication chip **2012** may implement any of a number of wireless standards or protocols, including but not limited to Institute for Electrical and Electronic Engineers (IEEE) standards including Wi-Fi (IEEE 1402.11 family), IEEE 1402.16 standards (e.g., IEEE 1402.16-2005 Amendment), Long-Term Evolution (LTE) project along with any amendments, updates, and/or revisions (e.g., advanced LTE



project, ultramobile broadband (UMB) project (also referred to as “3GPP2”), etc.). IEEE 1402.16 compatible Broadband Wireless Access (BWA) networks are generally referred to as WiMAX networks, an acronym that stands for Worldwide Interoperability for Microwave Access, which is a certification mark for products that pass conformity and interoperability tests for the IEEE 1402.16 standards. The communication chip **2012** may operate in accordance with a Global System for Mobile Communication (GSM), General Packet Radio Service (GPRS), Universal Mobile Telecommunications System (UMTS), High Speed Packet Access (HSPA), Evolved HSPA (E-HSPA), or LTE network. The communication chip **2012** may operate in accordance with Enhanced Data for GSM Evolution (EDGE), GSM EDGE Radio Access Network (GERAN), Universal Terrestrial Radio Access Network (UTRAN), or Evolved UTRAN (E-UTRAN). The communication chip **2012** may operate in accordance with Code Division Multiple Access (CDMA), Time Division Multiple Access (TDMA), Digital Enhanced Cordless Telecommunications (DECT), Evolution-Data Optimized (EV-DO), and derivatives thereof, as well as any other wireless protocols that are designated as 3G, 4G, 5G, and beyond. The communication chip **2012** may operate in accordance with other wireless protocols in other embodiments. The quantum computing device **2000** may include an antenna **2022** to facilitate wireless communications and/or to receive other wireless communications (such as AM or FM radio transmissions).

In some embodiments, the communication chip **2012** may manage wired communications, such as electrical, optical, or any other suitable communication protocols (e.g., the Ethernet). As noted above, the communication chip **2012** may include multiple communication chips. For instance, a first communication chip **2012** may be dedicated to shorter-range wireless communications such as Wi-Fi or Bluetooth, and a second communication chip **2012** may be dedicated to longer-range wireless communications such as GPS, EDGE, GPRS, CDMA, WiMAX, LTE, EV-DO, or others. In some embodiments, a first communication chip **2012** may be dedicated to wireless communications, and a second communication chip **2012** may be dedicated to wired communications.

The quantum computing device **2000** may include battery/power circuitry **2014**. The battery/power circuitry **2014** may include one or more energy storage devices (e.g., batteries or capacitors) and/or circuitry for coupling components of the quantum computing device **2000** to an energy source separate from the quantum computing device **2000** (e.g., AC line power).

The quantum computing device **2000** may include a display device **2006** (or corresponding interface circuitry, as discussed above). The display device **2006** may include any visual indicators, such as a heads-up display, a computer monitor, a projector, a touchscreen display, a liquid crystal display (LCD), a light-emitting diode display, or a flat panel display, for example.

The quantum computing device **2000** may include an audio output device **2008** (or corresponding interface circuitry, as discussed above). The audio output device **2008** may include any device that generates an audible indicator, such as speakers, headsets, or earbuds, for example.

The quantum computing device **2000** may include an audio input device **2024** (or corresponding interface circuitry, as discussed above). The audio input device **2024** may include any device that generates a signal representative of a sound, such as microphones, microphone arrays, or

digital instruments (e.g., instruments having a musical instrument digital interface (MIDI) output).

The quantum computing device **2000** may include a global positioning system (GPS) device **2018** (or corresponding interface circuitry, as discussed above). The GPS device **2018** may be in communication with a satellite-based system and may receive a location of the quantum computing device **2000**, as known in the art.

The quantum computing device **2000** may include an other output device **2010** (or corresponding interface circuitry, as discussed above). Examples of the other output device **2010** may include an audio codec, a video codec, a printer, a wired or wireless transmitter for providing information to other devices, or an additional storage device.

The quantum computing device **2000** may include an other input device **2020** (or corresponding interface circuitry, as discussed above). Examples of the other input device **2020** may include an accelerometer, a gyroscope, a compass, an image capture device, a keyboard, a cursor control device such as a mouse, a stylus, a touchpad, a bar code reader, a Quick Response (QR) code reader, any sensor, or a radio frequency identification (RFID) reader.

The quantum computing device **2000**, or a subset of its components, may have any appropriate form factor, such as a hand-held or mobile computing device (e.g., a cell phone, a smart phone, a mobile internet device, a music player, a tablet computer, a laptop computer, a netbook computer, an ultrabook computer, a personal digital assistant (PDA), an ultramobile personal computer, etc.), a desktop computing device, a server or other networked computing component, a printer, a scanner, a monitor, a set-top box, an entertainment control unit, a vehicle control unit, a digital camera, a digital video recorder, or a wearable computing device.

The following paragraphs provide examples of various ones of the embodiments disclosed herein.

Example 1 is a quantum dot device, including: a quantum well stack; a gate interface material; and a high-k gate dielectric; wherein the gate interface material is disposed between the high-k gate dielectric and the quantum well stack.

Example 2 may include the subject matter of Example 1, and may further specify that the gate interface material includes silicon.

Example 3 may include the subject matter of any of Examples 1-2, and may further specify that the quantum well stack includes a barrier layer and a quantum well layer, the barrier layer is disposed between the quantum well layer and the gate interface material, and the gate interface material is disposed on the barrier layer.

Example 4 may include the subject matter of Example 3, and may further specify that the barrier layer is formed of silicon germanium.

Example 5 may include the subject matter of any of Examples 1-4, and may further specify that the quantum well stack includes a quantum well layer formed of silicon.

Example 6 may include the subject matter of any of Examples 1-5, and may further specify that the gate interface material includes silicon oxide.

Example 7 may include the subject matter of any of Examples 1-6, and may further specify that the gate interface material has a thickness between 1 nanometers and 3 nanometers.

Example 8 may include the subject matter of any of Examples 1-7, and may further specify that the gate interface material has a U-shape cross-section.

Example 9 may include the subject matter of any of Examples 1-8, and may further include: a gate metal; and



first and second spacers; wherein the gate metal is disposed between the first and second spacers, and the high-k gate dielectric is disposed between the gate metal and the gate interface material.

Example 10 may include the subject matter of Example 9, and may further specify that the gate interface material extends up sides of the first and second spacers such that the gate interface material is disposed between the gate metal and the first and second spacers.

Example 11 may include the subject matter of any of Examples 1-10, and may further specify that the quantum well stack is included in a fin extending from a base.

Example 12 may include the subject matter of Example 11, and may further specify that the quantum well stack is a first quantum well stack, the fin is a first fin, and the quantum dot device further includes: a second fin, including a quantum well stack, extending from the base; and an insulating material disposed between the first and second fins.

Example 13 is a method of operating a quantum dot device, including: applying one or more voltages to gates on a first quantum well stack region to cause a first quantum dot to form in the first quantum well stack region, wherein at least one gate on the first quantum well stack region includes a gate metal and a gate dielectric, and wherein a gate interface material is disposed between the gate dielectric and the first quantum well stack region; applying one or more voltages to gates on a second quantum well stack region to cause a second quantum dot to form in the second quantum well stack region; and sensing a quantum state of the first quantum dot with the second quantum dot.

Example 14 may include the subject matter of Example 13, and may further specify that applying the one or more voltages to the gates on the first quantum well stack region comprises applying a voltage to a first gate to cause the first quantum dot to form in the first quantum well stack region under the first gate.

Example 15 may include the subject matter of any of Examples 13-14, and may further include: applying the one or more voltages to the gates on the first quantum well stack region to cause a third quantum dot to form in the first quantum well stack region; and prior to sensing the quantum state of the first quantum dot with the second quantum dot, allowing the first and third quantum dots to interact.

Example 16 may include the subject matter of any of Examples 13-15, and may further specify that silicon oxide is disposed between the gate interface material and the gate dielectric.

Example 17 is a method of manufacturing a quantum dot device, including: providing a gate interface material on a quantum well stack; providing a gate dielectric on the gate interface material; and providing a gate metal on the gate dielectric such that the gate dielectric is disposed between the gate interface material and the gate metal.

Example 18 may include the subject matter of Example 17, and may further specify that providing the gate interface material on the quantum well stack includes growing the gate interface material by epitaxy.

Example 19 may include the subject matter of any of Examples 17-18, and may further specify that the gate interface material includes silicon, the quantum well stack includes a silicon germanium barrier layer, the gate interface material is provided on the silicon germanium barrier layer, and the silicon germanium barrier layer is disposed between the gate interface material and a quantum well layer of the quantum well stack.

Example 20 may include the subject matter of Example 19, and may further specify that the gate dielectric includes hafnium oxide.

Example 21 may include the subject matter of any of Examples 17-20, and may further include, prior to providing the gate dielectric, exposing the gate interface material to oxygen to form silicon oxide.

Example 22 may include the subject matter of any of Examples 17-21, and may further include, prior to providing the gate interface material: providing a dummy gate stack on the quantum well stack, patterning the dummy gate stack to form a plurality of dummy gate stacks; wherein providing the gate interface material, providing the gate dielectric, and providing the gate metal include replacing the dummy gate stacks with the gate interface material, the gate dielectric and the gate metal, respectively.

Example 23 is a quantum computing device, including: a quantum processing device, wherein the quantum processing device includes gates on a first quantum well stack region in parallel with gates on a second quantum well stack region, an active quantum well layer in the first quantum well stack region, and a read quantum well layer in the second quantum well stack region, wherein the gates on the first quantum well stack region include a gate dielectric, a gate metal, and a gate interface material disposed between the gate dielectric and the first quantum well stack region; a non-quantum processing device, coupled to the quantum processing device, to control voltages applied to gates on the first and second quantum well stack regions; and a memory device to store data generated by the read quantum well layer during operation of the quantum processing device.

Example 24 may include the subject matter of Example 23, and may further include a cooling apparatus to maintain a temperature of the quantum processing device below 5 degrees Kelvin.

Example 25 may include the subject matter of any of Examples 23-24, and may further specify that silicon oxide is disposed between the gate interface material and the gate dielectric.

The invention claimed is:

1. A quantum dot device, comprising:

a first quantum well stack region, wherein the first quantum well stack region includes an active quantum well layer;

a first set of gates on the first quantum well stack region, wherein an individual gate in the first set of gates includes a gate interface material, a gate electrode, and a high-k gate dielectric, and the gate interface material is between the high-k gate dielectric and the first quantum well stack region;

a second quantum well stack region, wherein the second quantum well stack region includes a read quantum well layer; and

a second set of gates, parallel to the first set of gates, on the second quantum well stack region.

2. The quantum dot device of claim 1, wherein the gate interface material includes silicon.

3. The quantum dot device of claim 1, wherein the first quantum well stack region includes a barrier layer, the barrier layer is between the active quantum well layer and the gate interface material, and the gate interface material is on the barrier layer.

4. The quantum dot device of claim 3, wherein the barrier layer includes silicon germanium.

5. The quantum dot device of claim 1, wherein the active quantum well layer includes silicon.



29

6. The quantum dot device of claim 1, wherein the gate interface material includes silicon oxide.

7. The quantum dot device of claim 1, wherein the gate interface material has a thickness between 1 nanometers and 3 nanometers.

8. The quantum dot device of claim 1, wherein the gate interface material has a U-shaped cross-section.

9. The quantum dot device of claim 1, further comprising: first and second spacers;

wherein the gate electrode of an individual gate in the first set of gates is between the first and second spacers, and the high-k gate dielectric is between the gate electrode and the gate interface material.

10. The quantum dot device of claim 9, wherein the gate interface material extends up sides of the first and second spacers such that the gate interface material is between the gate electrode and the first and second spacers.

11. The quantum dot device of claim 1, wherein the first quantum well stack region is included in a fin extending from a base.

12. The quantum dot device of claim 11, wherein the fin is a first fin, and the quantum dot device further comprises: a second fin, including the second quantum well stack region, extending from the base; and an insulating material between the first and second fins.

13. A quantum computing device, comprising:

a quantum processing device, wherein the quantum processing device includes gates on a first quantum well stack region in parallel with gates on a second quantum well stack region, an active quantum well layer in the first quantum well stack region, and a read quantum well layer in the second quantum well stack region, wherein the gates on the first quantum well stack region include a gate dielectric, a gate metal, and a gate interface material between the gate dielectric and the first quantum well stack region;

30

a non-quantum processing device, coupled to the quantum processing device, to control voltages applied to gates on the first and second quantum well stack regions; and a memory device to store data generated by the read quantum well layer during operation of the quantum processing device.

14. The quantum computing device of claim 13, further comprising:

a cooling apparatus to maintain a temperature of the quantum processing device below 5 degrees Kelvin.

15. The quantum computing device of claim 13, wherein silicon oxide is between the gate interface material and the gate dielectric.

16. The quantum computing device of claim 13, wherein the active quantum well layer includes silicon.

17. The quantum computing device of claim 13, wherein the quantum processing device further includes a barrier layer between the active quantum well layer and the gate interface material, and the barrier layer includes silicon germanium.

18. The quantum computing device of claim 13, wherein the gate interface material has a thickness between 1 nanometers and 3 nanometers.

19. The quantum computing device of claim 13, wherein the gate interface material has a U-shaped cross-section.

20. The quantum computing device of claim 13, wherein the quantum processing device further includes first and second spacers, wherein the gate metal is between the first and second spacers, and the gate dielectric is between the gate metal and the gate interface material.

21. The quantum computing device of claim 20, wherein the gate interface material extends up sides of the first and second spacers such that the gate interface material is between the gate metal and the first and second spacers.

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